

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

NOTES:

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

REGISTER 20-2: PMMODE: PARALLEL PORT MODE REGISTER

| Bit Range | Bit 31/23/15/7 | Bit 30/22/14/6 | Bit 29/21/13/5 | Bit 28/20/12/4 | Bit 27/19/11/3 | Bit 26/18/10/2 | Bit 25/17/9/1 | Bit 24/16/8/0 |
|-----------|---------------------------|----------------|---------------------------|----------------|----------------|---------------------------|---------------|---------------|
| 31:24 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
| | — | — | — | — | — | — | — | — |
| 23:16 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
| | — | — | — | — | — | — | — | — |
| 15:8 | R-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | U-0 | R/W-0 | R/W-0 |
| | BUSY | IRQM<1:0> | | INCM<1:0> | | — | MODE<1:0> | |
| 7:0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
| | WAITB<1:0> ⁽¹⁾ | | WAITM<3:0> ⁽¹⁾ | | | WAITE<1:0> ⁽¹⁾ | | |

Legend:

| | | |
|-------------------|------------------|------------------------------------|
| R = Readable bit | W = Writable bit | U = Unimplemented bit, read as '0' |
| -n = Value at POR | '1' = Bit is set | '0' = Bit is cleared |
| | | x = Bit is unknown |

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **BUSY:** Busy bit (Master mode only)

- 1 = Port is busy
- 0 = Port is not busy

bit 14-13 **IRQM<1:0>:** Interrupt Request Mode bits

- 11 = Reserved, do not use
- 10 = Interrupt generated when Read Buffer 3 is read or Write Buffer 3 is written (Buffered PSP mode) or on a read or write operation when PMA<1:0> = 11 (Addressable Slave mode only)
- 01 = Interrupt generated at the end of the read/write cycle
- 00 = No interrupt generated

bit 12-11 **INCM<1:0>:** Increment Mode bits

- 11 = Slave mode read and write buffers auto-increment (MODE<1:0> = 00 only)
- 10 = Decrement ADDR<10:2> and ADDR<14> by 1 every read/write cycle⁽²⁾
- 01 = Increment ADDR<10:2> and ADDR<14> by 1 every read/write cycle⁽²⁾
- 00 = No increment or decrement of address

bit 10 **Unimplemented:** Read as '0'

bit 9-8 **MODE<1:0>:** Parallel Port Mode Select bits

- 11 = Master mode 1 (PMCS1, PMRD/PMWR, PMENB, PMA<x:0>, and PMD<7:0>)
- 10 = Master mode 2 (PMCS1, PMRD, PMWR, PMA<x:0>, and PMD<7:0>)
- 01 = Enhanced Slave mode, control signals (PMRD, PMWR, PMCS1, PMD<7:0>, and PMA<1:0>)
- 00 = Legacy Parallel Slave Port, control signals (PMRD, PMWR, PMCS1, and PMD<7:0>)

bit 7-6 **WAITB<1:0>:** Data Setup to Read/Write Strobe Wait States bits⁽¹⁾

- 11 = Data wait of 4 TPB; multiplexed address phase of 4 TPB
- 10 = Data wait of 3 TPB; multiplexed address phase of 3 TPB
- 01 = Data wait of 2 TPB; multiplexed address phase of 2 TPB
- 00 = Data wait of 1 TPB; multiplexed address phase of 1 TPB (default)

bit 5-2 **WAITM<3:0>:** Data Read/Write Strobe Wait States bits⁽¹⁾

- 1111 = Wait of 16 TPB
- .
- .
- .
- 0001 = Wait of 2 TPB
- 0000 = Wait of 1 TPB (default)

Note 1: Whenever WAITM<3:0> = 0000, WAITB and WAITE bits are ignored and forced to 1 TPBCLK cycle for a write operation; WAITB = 1 TPBCLK cycle, WAITE = 0 TPBCLK cycles for a read operation.

2: Address bit A14 is not subject to auto-increment/decrement if configured as Chip Select CS1.

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REGISTER 20-2: PPMODE: PARALLEL PORT MODE REGISTER (CONTINUED)

bit 1-0 **WAITE<1:0>**: Data Hold After Read/Write Strobe Wait States bits⁽¹⁾

11 = Wait of 4 TPB

10 = Wait of 3 TPB

01 = Wait of 2 TPB

00 = Wait of 1 TPB (default)

For Read operations:

11 = Wait of 3 TPB

10 = Wait of 2 TPB

01 = Wait of 1 TPB

00 = Wait of 0 TPB (default)

Note 1: Whenever WAITM<3:0> = 0000, WAITB and WAITE bits are ignored and forced to 1 TPBCLK cycle for a write operation; WAITB = 1 TPBCLK cycle, WAITE = 0 TPBCLK cycles for a read operation.

2: Address bit A14 is not subject to auto-increment/decrement if configured as Chip Select CS1.

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REGISTER 20-3: PMADDR: PARALLEL PORT ADDRESS REGISTER

| Bit Range | Bit 31/23/15/7 | Bit 30/22/14/6 | Bit 29/21/13/5 | Bit 28/20/12/4 | Bit 27/19/11/3 | Bit 26/18/10/2 | Bit 25/17/9/1 | Bit 24/16/8/0 |
|-----------|----------------|-----------------------|----------------|----------------|----------------|----------------|---------------|---------------|
| 31:24 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
| | — | — | — | — | — | — | — | — |
| 23:16 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
| | — | — | — | — | — | — | — | — |
| 15:8 | U-0 | R/W-0 | U-0 | U-0 | U-0 | R/W-0 | R/W-0 | R/W-0 |
| | — | CS1 ⁽¹⁾ | — | — | — | ADDR<10:8> | | |
| | | ADDR14 ⁽²⁾ | | | | | | |
| 7:0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
| | ADDR<7:0> | | | | | | | |

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 31-15 **Unimplemented:** Read as '0'

bit 14 **CS1:** Chip Select 1 bit⁽¹⁾

1 = Chip Select 1 is active

0 = Chip Select 1 is inactive

bit 14 **ADDR<14>:** Destination Address bit 14⁽²⁾

bit 13-11 **Unimplemented:** Read as '0'

bit 10-0 **ADDR<10:0>:** Destination Address bits

Note 1: When the CSF<1:0> bits (PMCON<7:6>) = 10.

2: When the CSF<1:0> bits (PMCON<7:6>) = 00 or 01.

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REGISTER 20-4: PMAEN: PARALLEL PORT PIN ENABLE REGISTER

| Bit Range | Bit 31/23/15/7 | Bit 30/22/14/6 | Bit 29/21/13/5 | Bit 28/20/12/4 | Bit 27/19/11/3 | Bit 26/18/10/2 | Bit 25/17/9/1 | Bit 24/16/8/0 |
|-----------|----------------|-----------------|----------------|----------------|----------------|----------------|---------------|---------------|
| 31:24 | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — |
| 23:16 | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — |
| 15:8 | U-0 — | R/W-0 PTEN14 | U-0 — | U-0 — | U-0 — | R/W-0 — | R/W-0 — | R/W-0 — |
| 7:0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
| PTEN<7:0> | | | | | | | | |

Legend:

| | | |
|-------------------|------------------|----------------------------------------------|
| R = Readable bit | W = Writable bit | U = Unimplemented bit, read as '0' |
| -n = Value at POR | '1' = Bit is set | '0' = Bit is cleared x = Bit is unknown |

bit 31-15 **Unimplemented:** Read as '0'

bit 15-14 **PTEN14:** PMCS1 Address Port Enable bits
 1 = PMA14 functions as either PMA14 or PMCS1⁽¹⁾
 0 = PMA14 functions as port I/O

bit 13-11 **Unimplemented:** Read as '0'

bit 10-2 **PTEN<10:2>:** PMP Address Port Enable bits
 1 = PMA<10:2> function as PMP address lines
 0 = PMA<10:2> function as port I/O

bit 1-0 **PTEN<1:0>:** PMALH/PMALL Address Port Enable bits
 1 = PMA1 and PMA0 function as either PMA<1:0> or PMALH and PMALL⁽²⁾
 0 = PMA1 and PMA0 pads functions as port I/O

- Note 1:** The use of this pin as PMA14 or CS1 is selected by the CSF<1:0> bits in the PMCON register.
- 2:** The use of these pins as PMA1/PMA0 or PMALH/PMALL depends on the Address/Data Multiplex mode selected by bits ADRMUX<1:0> in the PMCON register.

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REGISTER 20-5: PMSTAT: PARALLEL PORT STATUS REGISTER (SLAVE MODES ONLY)

| Bit Range | Bit 31/23/15/7 | Bit 30/22/14/6 | Bit 29/21/13/5 | Bit 28/20/12/4 | Bit 27/19/11/3 | Bit 26/18/10/2 | Bit 25/17/9/1 | Bit 24/16/8/0 |
|-----------|----------------|----------------|----------------|----------------|----------------|----------------|---------------|---------------|
| 31:24 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
| | — | — | — | — | — | — | — | — |
| 23:16 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
| | — | — | — | — | — | — | — | — |
| 15:8 | R-0 | R/W-0, HSC | U-0 | U-0 | R-0 | R-0 | R-0 | R-0 |
| | IBF | IBOV | — | — | IB3F | IB2F | IB1F | IB0F |
| 7:0 | R-1 | R/W-0, HSC | U-0 | U-0 | R-1 | R-1 | R-1 | R-1 |
| | OBE | OBUF | — | — | OB3E | OB2E | OB1E | OB0E |

Legend:

R = Readable bit
-n = Value at POR

HSC = Set by Hardware; Cleared by Software

W = Writable bit
'1' = Bit is set

U = Unimplemented bit, read as '0'
'0' = Bit is cleared

x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **IBF:** Input Buffer Full Status bit

- 1 = All writable input buffer registers are full
- 0 = Some or all of the writable input buffer registers are empty

bit 14 **IBOV:** Input Buffer Overflow Status bit

- 1 = A write attempt to a full input byte buffer occurred (must be cleared in software)
- 0 = No overflow occurred

bit 13-12 **Unimplemented:** Read as '0'

bit 11-8 **IBxF:** Input Buffer 'x' Status Full bits

- 1 = Input Buffer contains data that has not been read (reading buffer will clear this bit)
- 0 = Input Buffer does not contain any unread data

bit 7 **OBE:** Output Buffer Empty Status bit

- 1 = All readable output buffer registers are empty
- 0 = Some or all of the readable output buffer registers are full

bit 6 **OBUF:** Output Buffer Underflow Status bit

- 1 = A read occurred from an empty output byte buffer (must be cleared in software)
- 0 = No underflow occurred

bit 5-4 **Unimplemented:** Read as '0'

bit 3-0 **OBxE:** Output Buffer 'x' Status Empty bits

- 1 = Output buffer is empty (writing data to the buffer will clear this bit)
- 0 = Output buffer contains data that has not been transmitted

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NOTES:

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21.0 REAL-TIME CLOCK AND CALENDAR (RTCC)

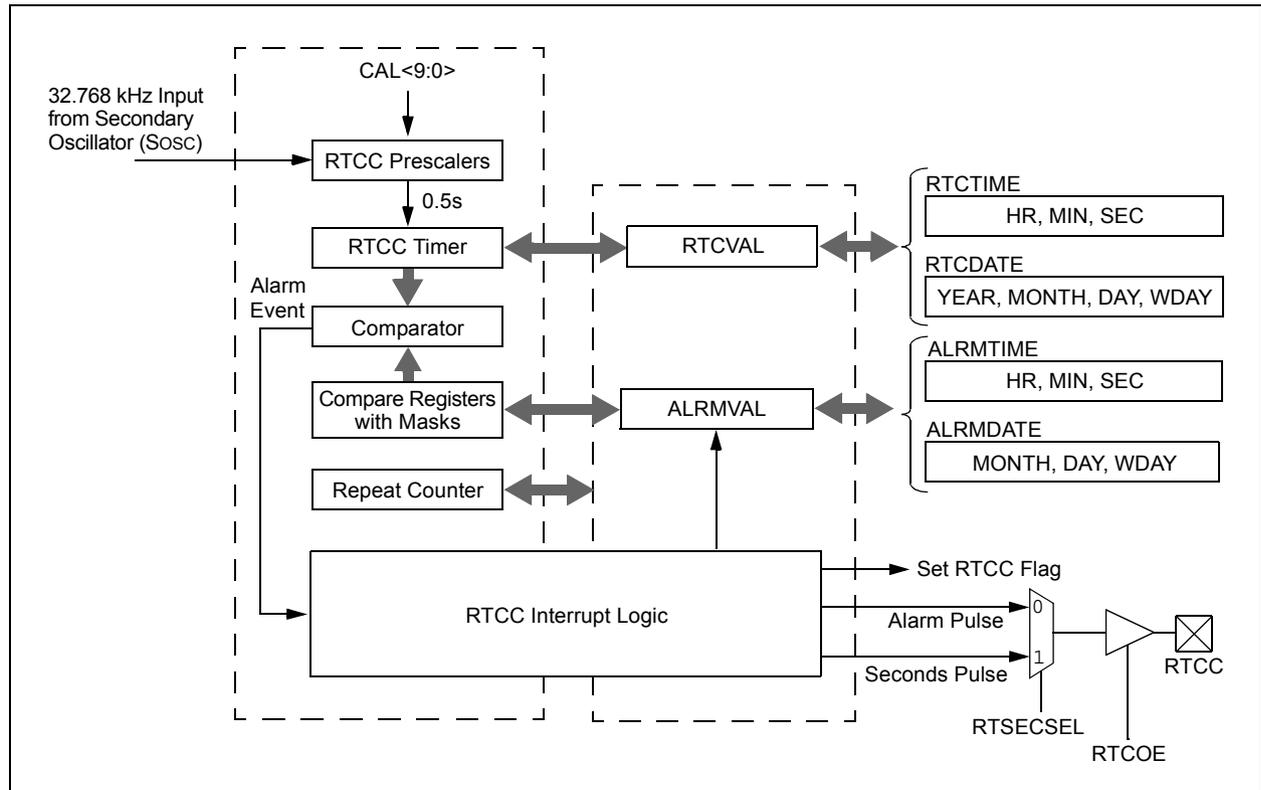
Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 29. “Real-Time Clock and Calendar (RTCC)”** (DS60001125), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The PIC32 RTCC module is intended for applications in which accurate time must be maintained for extended periods of time with minimal or no CPU intervention. Low-power optimization provides extended battery lifetime while keeping track of time.

Following are some of the key features of this module:

- Time: hours, minutes and seconds
- 24-hour format (military time)
- Visibility of one-half second period
- Provides calendar: day, date, month and year
- Alarm intervals are configurable for half of a second, one second, 10 seconds, one minute, 10 minutes, one hour, one day, one week, one month and one year
- Alarm repeat with decrementing counter
- Alarm with indefinite repeat: Chime
- Year range: 2000 to 2099
- Leap year correction
- BCD format for smaller firmware overhead
- Optimized for long-term battery operation
- Fractional second synchronization
- User calibration of the clock crystal frequency with auto-adjust
- Calibration range: ± 0.66 seconds error per month
- Calibrates up to 260 ppm of crystal error
- Requirements: External 32.768 kHz clock crystal
- Alarm pulse or seconds clock output on RTCC pin

FIGURE 21-1: RTCC BLOCK DIAGRAM



21.1 RTCC Control Registers

TABLE 21-1: RTCC REGISTER MAP

| Virtual Address (BF80_#) | Register Name ⁽¹⁾ | Bit Range | Bits | | | | | | | | | | | | | | | All Resets |
|-----------------------------|---------------------------------|-----------|-------------|------------|------------|----------|-------------|-------|----------|-----------|------------|----------|---------|--------------|-------------|---------|---------|------------|
| | | | 31/15 | 30/14 | 29/13 | 28/12 | 27/11 | 26/10 | 25/9 | 24/8 | 23/7 | 22/6 | 21/5 | 20/4 | 19/3 | 18/2 | 17/1 | |
| 0200 | RTCCON | 31:16 | — | — | — | — | — | — | CAL<9:0> | | | | | | | | | 0000 |
| | | 15:0 | ON | — | SIDL | — | — | — | — | — | RTSESEL | RTCCLKON | — | — | RTCWREN | RTCSYNC | HALFSEC | RTCOE |
| 0210 | RTCALRM | 31:16 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | 0000 |
| | | 15:0 | ALRMEN | CHIME | PIV | ALRMSYNC | AMASK<3:0> | | | ARPT<7:0> | | | | | | | 0000 | |
| 0220 | RTCTIME | 31:16 | — | — | HR10<1:0> | | HR01<3:0> | | | — | MIN10<2:0> | | | MIN01<3:0> | | | xxxx | |
| | | 15:0 | — | SEC10<2:0> | | | SEC01<3:0> | | | — | — | — | — | — | — | — | xx00 | |
| 0230 | RTCDATE | 31:16 | YEAR10<3:0> | | | | YEAR01<3:0> | | | — | — | — | MONTH10 | MONTH01<3:0> | | | xxxx | |
| | | 15:0 | — | — | DAY10<1:0> | | DAY01<3:0> | | | — | — | — | — | — | WDAY01<2:0> | | xx00 | |
| 0240 | ALRMTIME | 31:16 | — | — | HR10<1:0> | | HR01<3:0> | | | — | MIN10<2:0> | | | MIN01<3:0> | | | xxxx | |
| | | 15:0 | — | SEC10<2:0> | | | SEC01<3:0> | | | — | — | — | — | — | — | — | xx00 | |
| 0250 | ALRMDATE | 31:16 | — | — | — | — | — | — | — | — | — | — | MONTH10 | MONTH01<3:0> | | | 00xx | |
| | | 15:0 | DAY10<3:0> | | | | DAY01<3:0> | | | — | — | — | — | — | WDAY01<2:0> | | xx0x | |

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See [Section 11.2 “CLR, SET and INV Registers”](#) for more information.

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REGISTER 21-1: RTCCON: RTC CONTROL REGISTER

| Bit Range | Bit 31/23/15/7 | Bit 30/22/14/6 | Bit 29/21/13/5 | Bit 28/20/12/4 | Bit 27/19/11/3 | Bit 26/18/10/2 | Bit 25/17/9/1 | Bit 24/16/8/0 |
|-----------|-------------------------|----------------|----------------|----------------|------------------------|----------------|------------------------|---------------|
| 31:24 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | R/W-0 | R/W-0 |
| | — | — | — | — | — | — | CAL<9:8> | |
| 23:16 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
| | CAL<7:0> | | | | | | | |
| 15:8 | R/W-0 | U-0 | R/W-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
| | ON ^(1,2) | — | SIDL | — | — | — | — | — |
| 7:0 | R/W-0 | R-0 | U-0 | U-0 | R/W-0 | R-0 | R-0 | R/W-0 |
| | RTSECSEL ⁽³⁾ | RTCCLKON | — | — | RTCWREN ⁽⁴⁾ | RTCSYNC | HALFSEC ⁽⁵⁾ | RTCOE |

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
 -n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 31-26 **Unimplemented:** Read as '0'

bit 25-16 **CAL<9:0>:** RTC Drift Calibration bits, which contain a signed 10-bit integer value
 0111111111 = Maximum positive adjustment, adds 511 RTC clock pulses every one minute
 .
 .
 0000000001 = Minimum positive adjustment, adds 1 RTC clock pulse every one minute
 0000000000 = No adjustment
 1111111111 = Minimum negative adjustment, subtracts 1 RTC clock pulse every one minute
 .
 .
 1000000000 = Maximum negative adjustment, subtracts 512 clock pulses every one minute

bit 15 **ON:** RTCC On bit^(1,2)
 1 = RTCC module is enabled
 0 = RTCC module is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Stop in Idle Mode bit
 1 = Disables the PBCLK to the RTCC when the device enters Idle mode
 0 = Continue normal operation when the device enters Idle mode

bit 12-8 **Unimplemented:** Read as '0'

bit 7 **RTSECSEL:** RTCC Seconds Clock Output Select bit⁽³⁾
 1 = RTCC Seconds Clock is selected for the RTCC pin
 0 = RTCC Alarm Pulse is selected for the RTCC pin

bit 6 **RTCCLKON:** RTCC Clock Enable Status bit
 1 = RTCC Clock is actively running
 0 = RTCC Clock is not running

- Note 1:** The ON bit is only writable when RTCWREN = 1.
2: When using the 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSClk cycle immediately following the instruction that clears the module's ON bit.
3: Requires RTCOE = 1 (RTCCON<0>) for the output to be active.
4: The RTCWREN bit can be set only when the write sequence is enabled.
5: This bit is read-only. It is cleared to '0' on a write to the seconds bit fields (RTCTIME<14:8>).

Note: This register is reset only on a Power-on Reset (POR).

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REGISTER 21-1: RTCCON: RTC CONTROL REGISTER (CONTINUED)

- bit 5-4 **Unimplemented:** Read as '0'
- bit 3 **RTCWREN:** RTC Value Registers Write Enable bit⁽⁴⁾
1 = RTC Value registers can be written to by the user
0 = RTC Value registers are locked out from being written to by the user
- bit 2 **RTCSYNC:** RTCC Value Registers Read Synchronization bit
1 = RTC Value registers can change while reading, due to a rollover ripple that results in an invalid data read
If the register is read twice and results in the same data, the data can be assumed to be valid
0 = RTC Value registers can be read without concern about a rollover ripple
- bit 1 **HALFSEC:** Half-Second Status bit⁽⁵⁾
1 = Second half period of a second
0 = First half period of a second
- bit 0 **RTCOE:** RTCC Output Enable bit
1 = RTCC clock output enabled – clock presented onto an I/O
0 = RTCC clock output disabled

- Note 1:** The ON bit is only writable when RTCWREN = 1.
- 2:** When using the 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.
- 3:** Requires RTCOE = 1 (RTCCON<0>) for the output to be active.
- 4:** The RTCWREN bit can be set only when the write sequence is enabled.
- 5:** This bit is read-only. It is cleared to '0' on a write to the seconds bit fields (RTCTIME<14:8>).

Note: This register is reset only on a Power-on Reset (POR).

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

REGISTER 21-2: RTCALRM: RTC ALARM CONTROL REGISTER (CONTINUED)

bit 7-0 **ARPT<7:0>**: Alarm Repeat Counter Value bits⁽²⁾

11111111 = Alarm will trigger 256 times

.

.

00000000 = Alarm will trigger one time

The counter decrements on any alarm event. The counter only rolls over from 0x00 to 0xFF if CHIME = 1.

- Note 1:** Hardware clears the ALRMEN bit anytime the alarm event occurs, when ARPT<7:0> = 00 and CHIME = 0.
- 2:** This field should not be written when the RTCC ON bit = '1' (RTCCON<15>) and ALRMSYNC = 1.
- 3:** This assumes a CPU read will execute in less than 32 PBCLKs.

Note: This register is reset only on a Power-on Reset (POR).

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REGISTER 21-3: RTCTIME: RTC TIME VALUE REGISTER

| Bit Range | Bit 31/23/15/7 | Bit 30/22/14/6 | Bit 29/21/13/5 | Bit 28/20/12/4 | Bit 27/19/11/3 | Bit 26/18/10/2 | Bit 25/17/9/1 | Bit 24/16/8/0 |
|-----------|----------------|----------------|----------------|----------------|----------------|----------------|---------------|---------------|
| 31:24 | U-0 | U-0 | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x |
| | — | — | HR10<1:0> | | HR01<3:0> | | | |
| 23:16 | U-0 | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x |
| | — | MIN10<2:0> | | | MIN01<3:0> | | | |
| 15:8 | U-0 | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x |
| | — | SEC10<2:0> | | | SEC01<3:0> | | | |
| 7:0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
| | — | — | — | — | — | — | — | — |

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 31-30 **Unimplemented:** Read as '0'

bit 29-28 **HR10<1:0>:** Binary-Coded Decimal Value of Hours bits, 10s place digit; contains a value from 0 to 2

bit 27-24 **HR01<3:0>:** Binary-Coded Decimal Value of Hours bits, 1s place digit; contains a value from 0 to 9

bit 23 **Unimplemented:** Read as '0'

bit 22-20 **MIN10<2:0>:** Binary-Coded Decimal Value of Minutes bits, 10s place digit; contains a value from 0 to 5

bit 19-16 **MIN01<3:0>:** Binary-Coded Decimal Value of Minutes bits, 1s place digit; contains a value from 0 to 9

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **SEC10<2:0>:** Binary-Coded Decimal Value of Seconds bits, 10s place digit; contains a value from 0 to 5

bit 11-8 **SEC01<3:0>:** Binary-Coded Decimal Value of Seconds bits, 1s place digit; contains a value from 0 to 9

bit 7-0 **Unimplemented:** Read as '0'

Note: This register is only writable when RTCWREN = 1 (RTCCON<3>).

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REGISTER 21-4: RTCDATE: RTC DATE VALUE REGISTER

| Bit Range | Bit 31/23/15/7 | Bit 30/22/14/6 | Bit 29/21/13/5 | Bit 28/20/12/4 | Bit 27/19/11/3 | Bit 26/18/10/2 | Bit 25/17/9/1 | Bit 24/16/8/0 |
|-----------|----------------|----------------|----------------|----------------|----------------|----------------|---------------|---------------|
| 31:24 | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x |
| | YEAR10<3:0> | | | | YEAR01<3:0> | | | |
| 23:16 | U-0 | U-0 | U-0 | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x |
| | — | — | — | MONTH10 | MONTH01<3:0> | | | |
| 15:8 | U-0 | U-0 | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x |
| | — | — | DAY10<1:0> | | DAY01<3:0> | | | |
| 7:0 | U-0 | U-0 | U-0 | U-0 | U-0 | R/W-x | R/W-x | R/W-x |
| | — | — | — | — | — | WDAY01<2:0> | | |

Legend:

R = Readable bit
-n = Value at POR

W = Writable bit
'1' = Bit is set

U = Unimplemented bit, read as '0'
'0' = Bit is cleared
x = Bit is unknown

- bit 31-28 **YEAR10<3:0>**: Binary-Coded Decimal Value of Years bits, 10s place digit; contains a value from 0 to 9
- bit 27-24 **YEAR01<3:0>**: Binary-Coded Decimal Value of Years bits, 1s place digit; contains a value from 0 to 9
- bit 23-21 **Unimplemented**: Read as '0'
- bit 20 **MONTH10**: Binary-Coded Decimal Value of Months bits, 10s place digit; contains a value of 0 or 1
- bit 19-16 **MONTH01<3:0>**: Binary-Coded Decimal Value of Months bits, 1s place digit; contains a value from 0 to 9
- bit 15-14 **Unimplemented**: Read as '0'
- bit 13-12 **DAY10<1:0>**: Binary-Coded Decimal Value of Days bits, 10s place digit; contains a value of 0 to 3
- bit 11-8 **DAY01<3:0>**: Binary-Coded Decimal Value of Days bits, 1s place digit; contains a value from 0 to 9
- bit 7-3 **Unimplemented**: Read as '0'
- bit 2-0 **WDAY01<2:0>**: Binary-Coded Decimal Value of Weekdays bits; contains a value from 0 to 6

Note: This register is only writable when RTCWREN = 1 (RTCCON<3>).

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REGISTER 21-5: ALRMTIME: ALARM TIME VALUE REGISTER

| Bit Range | Bit 31/23/15/7 | Bit 30/22/14/6 | Bit 29/21/13/5 | Bit 28/20/12/4 | Bit 27/19/11/3 | Bit 26/18/10/2 | Bit 25/17/9/1 | Bit 24/16/8/0 |
|-----------|----------------|----------------|----------------|----------------|----------------|----------------|---------------|---------------|
| 31:24 | U-0 | U-0 | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x |
| | — | — | HR10<1:0> | | HR01<3:0> | | | |
| 23:16 | U-0 | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x |
| | — | MIN10<2:0> | | | MIN01<3:0> | | | |
| 15:8 | U-0 | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x |
| | — | SEC10<2:0> | | | SEC01<3:0> | | | |
| 7:0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
| | — | — | — | — | — | — | — | — |

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 31-30 **Unimplemented:** Read as '0'

bit 29-28 **HR10<1:0>:** Binary Coded Decimal value of hours bits, 10s place digit; contains a value from 0 to 2

bit 27-24 **HR01<3:0>:** Binary Coded Decimal value of hours bits, 1s place digit; contains a value from 0 to 9

bit 23 **Unimplemented:** Read as '0'

bit 22-20 **MIN10<2:0>:** Binary Coded Decimal value of minutes bits, 10s place digit; contains a value from 0 to 5

bit 19-16 **MIN01<3:0>:** Binary Coded Decimal value of minutes bits, 1s place digit; contains a value from 0 to 9

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **SEC10<2:0>:** Binary Coded Decimal value of seconds bits, 10s place digit; contains a value from 0 to 5

bit 11-8 **SEC01<3:0>:** Binary Coded Decimal value of seconds bits, 1s place digit; contains a value from 0 to 9

bit 7-0 **Unimplemented:** Read as '0'

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REGISTER 21-6: ALRMDATE: ALARM DATE VALUE REGISTER

| Bit Range | Bit 31/23/15/7 | Bit 30/22/14/6 | Bit 29/21/13/5 | Bit 28/20/12/4 | Bit 27/19/11/3 | Bit 26/18/10/2 | Bit 25/17/9/1 | Bit 24/16/8/0 |
|-----------|----------------|----------------|----------------|----------------|----------------|----------------|---------------|---------------|
| 31:24 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
| | — | — | — | — | — | — | — | — |
| 23:16 | U-0 | U-0 | U-0 | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x |
| | — | — | — | MONTH10 | MONTH01<3:0> | | | |
| 15:8 | U-0 | U-0 | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x | R/W-x |
| | — | — | DAY10<1:0> | | DAY01<3:0> | | | |
| 7:0 | U-0 | U-0 | U-0 | U-0 | U-0 | R/W-x | R/W-x | R/W-x |
| | — | — | — | — | — | WDAY01<2:0> | | |

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
 -n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

- bit 31-21 **Unimplemented:** Read as '0'
- bit 20 **MONTH10:** Binary Coded Decimal value of months bits, 10s place digit; contains a value of 0 or 1
- bit 19-16 **MONTH01<3:0>:** Binary Coded Decimal value of months bits, 1s place digit; contains a value from 0 to 9
- bit 15-14 **Unimplemented:** Read as '0'
- bit 13-12 **DAY10<1:0>:** Binary Coded Decimal value of days bits, 10s place digit; contains a value from 0 to 3
- bit 11-8 **DAY01<3:0>:** Binary Coded Decimal value of days bits, 1s place digit; contains a value from 0 to 9
- bit 7-3 **Unimplemented:** Read as '0'
- bit 2-0 **WDAY01<2:0>:** Binary Coded Decimal value of weekdays bits; contains a value from 0 to 6

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22.0 10-BIT ANALOG-TO-DIGITAL CONVERTER (ADC)

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 17. “10-bit Analog-to-Digital Converter (ADC)”** (DS60001104), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

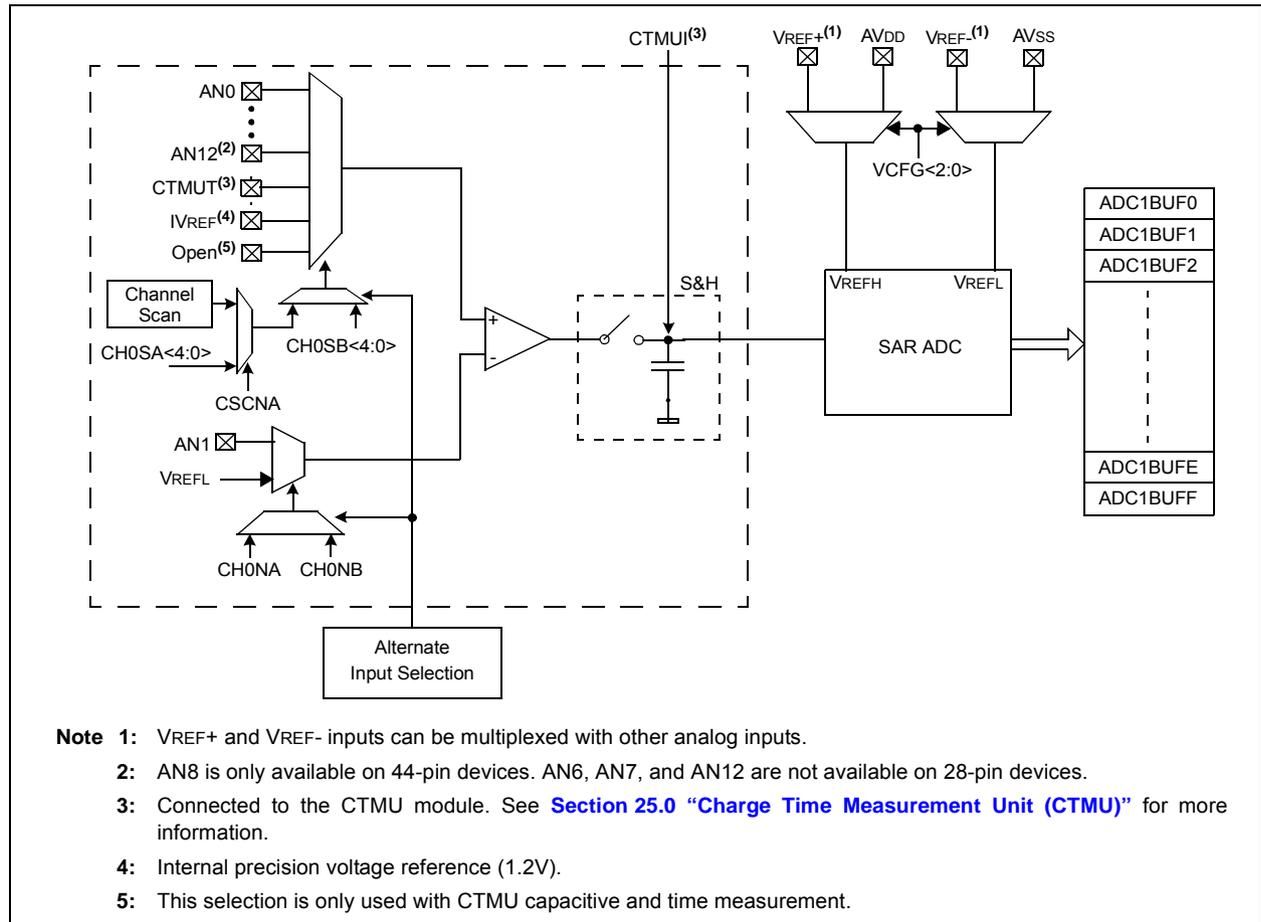
The 10-bit Analog-to-Digital Converter (ADC) includes the following features:

- Successive Approximation Register (SAR) conversion
- Up to 1 Msps conversion speed

- Up to 13 analog input pins
- External voltage reference input pins
- One unipolar, differential Sample and Hold Amplifier (SHA)
- Automatic Channel Scan mode
- Selectable conversion trigger source
- 16-word conversion result buffer
- Selectable buffer fill modes
- Eight conversion result format options
- Operation during Sleep and Idle modes

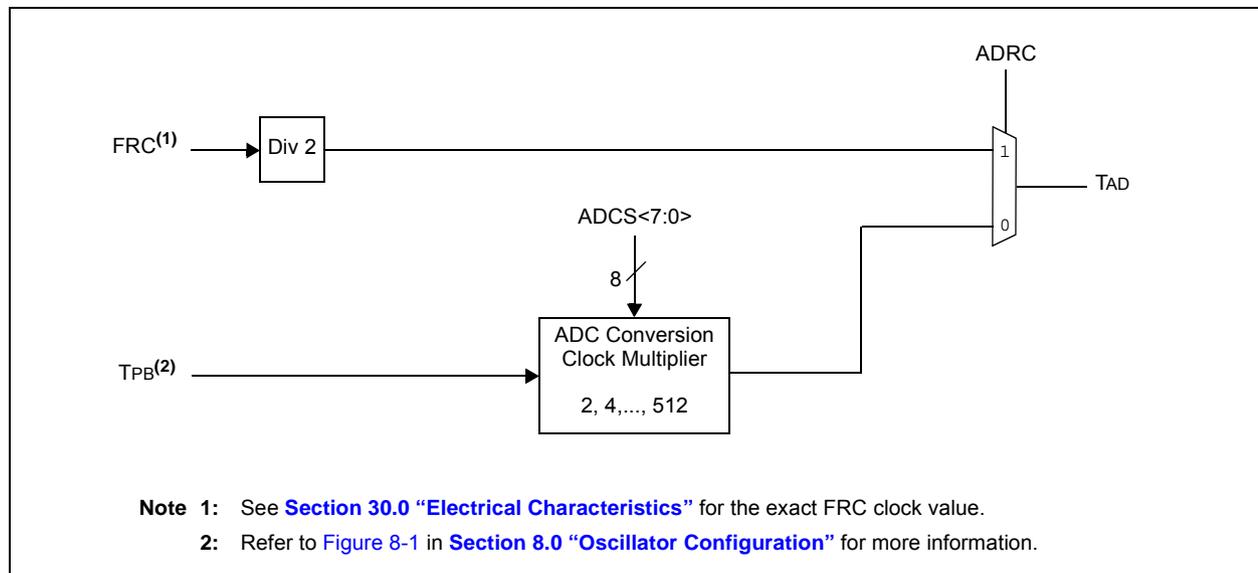
A block diagram of the 10-bit ADC is illustrated in [Figure 22-1](#). [Figure 22-2](#) illustrates a block diagram of the ADC conversion clock period. The 10-bit ADC has up to 13 analog input pins, designated AN0-AN12. In addition, there are two analog input pins for external voltage reference connections. These voltage reference inputs may be shared with other analog input pins and may be common to other analog module references.

FIGURE 22-1: ADC1 MODULE BLOCK DIAGRAM



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FIGURE 22-2: ADC CONVERSION CLOCK PERIOD BLOCK DIAGRAM



22.1 ADC Control Registers

TABLE 22-1: ADC REGISTER MAP

| Virtual Address (BF80_#) | Register Name | Bit Range | Bits | | | | | | | | | | | | | | | All Resets | | |
|-----------------------------|------------------------|-----------|------------------------------------|-----------|--------|--------|--------|------------|-------|-------|-------|-----------|-------|-------|-----------|-------|-------|------------|------------|-----------|
| | | | 31/15 | 30/14 | 29/13 | 28/12 | 27/11 | 26/10 | 25/9 | 24/8 | 23/7 | 22/6 | 21/5 | 20/4 | 19/3 | 18/2 | 17/1 | | 16/0 | |
| 9000 | AD1CON1 ⁽¹⁾ | 31:16 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | 0000 | |
| | | 15:0 | ON | — | SIDL | — | — | FORM<2:0> | — | — | — | SSRC<2:0> | — | — | CLRASAM | — | ASAM | SAMP | DONE | 0000 |
| 9010 | AD1CON2 ⁽¹⁾ | 31:16 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | 0000 | |
| | | 15:0 | — | VCFG<2:0> | — | OFFCAL | — | CSCNA | — | — | BUFS | — | — | — | SMPI<3:0> | — | — | — | BUFM | ALTS |
| 9020 | AD1CON3 ⁽¹⁾ | 31:16 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | 0000 |
| | | 15:0 | ADRC | — | — | — | — | SAMC<4:0> | — | — | — | — | — | — | — | — | — | — | — | ADCS<7:0> |
| 9040 | AD1CHS ⁽¹⁾ | 31:16 | CH0NB | — | — | — | — | CH0SB<3:0> | — | — | CH0NA | — | — | — | — | — | — | — | CH0SA<3:0> | 0000 |
| | | 15:0 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — |
| 9050 | AD1CSSL ⁽¹⁾ | 31:16 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | 0000 |
| | | 15:0 | CSSL15 | CSSL14 | CSSL13 | CSSL12 | CSSL11 | CSSL10 | CSSL9 | CSSL8 | CSSL7 | CSSL6 | CSSL5 | CSSL4 | CSSL3 | CSSL2 | CSSL1 | CSSL0 | — | — |
| 9070 | ADC1BUF0 | 31:16 | ADC Result Word 0 (ADC1BUF0<31:0>) | | | | | | | | | | | | | | | | 0000 | |
| | | 15:0 | | | | | | | | | | | | | | | | | 0000 | |
| 9080 | ADC1BUF1 | 31:16 | ADC Result Word 1 (ADC1BUF1<31:0>) | | | | | | | | | | | | | | | | 0000 | |
| | | 15:0 | | | | | | | | | | | | | | | | | 0000 | |
| 9090 | ADC1BUF2 | 31:16 | ADC Result Word 2 (ADC1BUF2<31:0>) | | | | | | | | | | | | | | | | 0000 | |
| | | 15:0 | | | | | | | | | | | | | | | | | 0000 | |
| 90A0 | ADC1BUF3 | 31:16 | ADC Result Word 3 (ADC1BUF3<31:0>) | | | | | | | | | | | | | | | | 0000 | |
| | | 15:0 | | | | | | | | | | | | | | | | | 0000 | |
| 90B0 | ADC1BUF4 | 31:16 | ADC Result Word 4 (ADC1BUF4<31:0>) | | | | | | | | | | | | | | | | 0000 | |
| | | 15:0 | | | | | | | | | | | | | | | | | 0000 | |
| 90C0 | ADC1BUF5 | 31:16 | ADC Result Word 5 (ADC1BUF5<31:0>) | | | | | | | | | | | | | | | | 0000 | |
| | | 15:0 | | | | | | | | | | | | | | | | | 0000 | |
| 90D0 | ADC1BUF6 | 31:16 | ADC Result Word 6 (ADC1BUF6<31:0>) | | | | | | | | | | | | | | | | 0000 | |
| | | 15:0 | | | | | | | | | | | | | | | | | 0000 | |
| 90E0 | ADC1BUF7 | 31:16 | ADC Result Word 7 (ADC1BUF7<31:0>) | | | | | | | | | | | | | | | | 0000 | |
| | | 15:0 | | | | | | | | | | | | | | | | | 0000 | |
| 90F0 | ADC1BUF8 | 31:16 | ADC Result Word 8 (ADC1BUF8<31:0>) | | | | | | | | | | | | | | | | 0000 | |
| | | 15:0 | | | | | | | | | | | | | | | | | 0000 | |
| 9100 | ADC1BUF9 | 31:16 | ADC Result Word 9 (ADC1BUF9<31:0>) | | | | | | | | | | | | | | | | 0000 | |
| | | 15:0 | | | | | | | | | | | | | | | | | 0000 | |
| 9110 | ADC1BUFA | 31:16 | ADC Result Word A (ADC1BUFA<31:0>) | | | | | | | | | | | | | | | | 0000 | |
| | | 15:0 | | | | | | | | | | | | | | | | | 0000 | |

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus offsets of 0x4, 0x8 and 0xC, respectively. See [Section 11.2 "CLR, SET and INV Registers"](#) for details.

TABLE 22-1: ADC REGISTER MAP (CONTINUED)

| Virtual Address (BF80_#) | Register Name | Bit Range | Bits | | | | | | | | | | | | | | All Resets |
|-----------------------------|------------------|-----------|-------------------------------------|-------|-------|-------|-------|-------|------|------|------|------|------|------|------|------|------------|
| | | | 31/15 | 30/14 | 29/13 | 28/12 | 27/11 | 26/10 | 25/9 | 24/8 | 23/7 | 22/6 | 21/5 | 20/4 | 19/3 | 18/2 | |
| 9120 | ADC1BUF B | 31:16 | ADC Result Word B (ADC1BUF B<31:0>) | | | | | | | | | | | | | | 0000 |
| | | 15:0 | | | | | | | | | | | | | | | 0000 |
| 9130 | ADC1BUF C | 31:16 | ADC Result Word C (ADC1BUF C<31:0>) | | | | | | | | | | | | | | 0000 |
| | | 15:0 | | | | | | | | | | | | | | | 0000 |
| 9140 | ADC1BUF D | 31:16 | ADC Result Word D (ADC1BUF D<31:0>) | | | | | | | | | | | | | | 0000 |
| | | 15:0 | | | | | | | | | | | | | | | 0000 |
| 9150 | ADC1BUF E | 31:16 | ADC Result Word E (ADC1BUF E<31:0>) | | | | | | | | | | | | | | 0000 |
| | | 15:0 | | | | | | | | | | | | | | | 0000 |
| 9160 | ADC1BUF F | 31:16 | ADC Result Word F (ADC1BUF F<31:0>) | | | | | | | | | | | | | | 0000 |
| | | 15:0 | | | | | | | | | | | | | | | 0000 |

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register has corresponding CLR, SET and INV registers at its virtual address, plus offsets of 0x4, 0x8 and 0xC, respectively. See [Section 11.2 "CLR, SET and INV Registers"](#) for details.

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REGISTER 22-1: AD1CON1: ADC CONTROL REGISTER 1

| Bit Range | Bit 31/23/15/7 | Bit 30/22/14/6 | Bit 29/21/13/5 | Bit 28/20/12/4 | Bit 27/19/11/3 | Bit 26/18/10/2 | Bit 25/17/9/1 | Bit 24/16/8/0 |
|-----------|-------------------|----------------|----------------|----------------|----------------|----------------|---------------------|---------------------|
| 31:24 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
| | — | — | — | — | — | — | — | — |
| 23:16 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
| | — | — | — | — | — | — | — | — |
| 15:8 | R/W-0 | U-0 | R/W-0 | U-0 | U-0 | R/W-0 | R/W-0 | R/W-0 |
| | ON ⁽¹⁾ | — | SIDL | — | — | FORM<2:0> | | |
| 7:0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | U-0 | R/W-0 | R/W-0, HSC | R/C-0, HSC |
| | SSRC<2:0> | | | CLRASAM | — | ASAM | SAMP ⁽²⁾ | DONE ⁽³⁾ |

Legend:

| | | |
|-------------------|------------------|------------------------------------|
| R = Readable bit | W = Writable bit | U = Unimplemented bit, read as '0' |
| -n = Value at POR | '1' = Bit is set | '0' = Bit is cleared |
| | | x = Bit is unknown |

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** ADC Operating Mode bit⁽¹⁾

- 1 = ADC module is operating
- 0 = ADC module is not operating

bit 14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Stop in Idle Mode bit

- 1 = Discontinue module operation when device enters Idle mode
- 0 = Continue module operation when the device enters Idle mode

bit 12-11 **Unimplemented:** Read as '0'

bit 10-8 **FORM<2:0>:** Data Output Format bits

- 111 = Signed Fractional 32-bit (DOUT = sddd dddd dd00 0000 0000 0000 0000)
- 110 = Fractional 32-bit (DOUT = dddd dddd dd00 0000 0000 0000 0000 0000)
- 101 = Signed Integer 32-bit (DOUT = ssss ssss ssss ssss ssss sssd dddd dddd)
- 100 = Integer 32-bit (DOUT = 0000 0000 0000 0000 0000 00dd dddd dddd)
- 011 = Signed Fractional 16-bit (DOUT = 0000 0000 0000 0000 sddd dddd dd00 0000)
- 010 = Fractional 16-bit (DOUT = 0000 0000 0000 0000 dddd dddd dd00 0000)
- 001 = Signed Integer 16-bit (DOUT = 0000 0000 0000 0000 ssss sssd dddd dddd)
- 000 = Integer 16-bit (DOUT = 0000 0000 0000 0000 00dd dddd dddd)

bit 7-5 **SSRC<2:0>:** Conversion Trigger Source Select bits

- 111 = Internal counter ends sampling and starts conversion (auto convert)
- 110 = Reserved
- 101 = Reserved
- 100 = Reserved
- 011 = CTMU ends sampling and starts conversion
- 010 = Timer 3 period match ends sampling and starts conversion
- 001 = Active transition on INT0 pin ends sampling and starts conversion
- 000 = Clearing SAMP bit ends sampling and starts conversion

Note 1: When using 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: If ASAM = 0, software can write a '1' to start sampling. This bit is automatically set by hardware if ASAM = 1. If SSRC = 0, software can write a '0' to end sampling and start conversion. If SSRC ≠ '0', this bit is automatically cleared by hardware to end sampling and start conversion.

3: This bit is automatically set by hardware when analog-to-digital conversion is complete. Software can write a '0' to clear this bit (a write of '1' is not allowed). Clearing this bit does not affect any operation already in progress. This bit is automatically cleared by hardware at the start of a new conversion.

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REGISTER 22-1: AD1CON1: ADC CONTROL REGISTER 1 (CONTINUED)

- bit 4 **CLRASAM:** Stop Conversion Sequence bit (when the first ADC interrupt is generated)
1 = Stop conversions when the first ADC interrupt is generated. Hardware clears the ASAM bit when the ADC interrupt is generated.
0 = Normal operation, buffer contents will be overwritten by the next conversion sequence
- bit 3 **Unimplemented:** Read as '0'
- bit 2 **ASAM:** ADC Sample Auto-Start bit
1 = Sampling begins immediately after last conversion completes; SAMP bit is automatically set.
0 = Sampling begins when SAMP bit is set
- bit 1 **SAMP:** ADC Sample Enable bit⁽²⁾
1 = The ADC sample and hold amplifier is sampling
0 = The ADC sample/hold amplifier is holding
When ASAM = 0, writing '1' to this bit starts sampling.
When SSRC = 000, writing '0' to this bit will end sampling and start conversion.
- bit 0 **DONE:** Analog-to-Digital Conversion Status bit⁽³⁾
1 = Analog-to-digital conversion is done
0 = Analog-to-digital conversion is not done or has not started
Clearing this bit will not affect any operation in progress.

- Note 1:** When using 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.
- 2:** If ASAM = 0, software can write a '1' to start sampling. This bit is automatically set by hardware if ASAM = 1. If SSRC = 0, software can write a '0' to end sampling and start conversion. If SSRC ≠ '0', this bit is automatically cleared by hardware to end sampling and start conversion.
- 3:** This bit is automatically set by hardware when analog-to-digital conversion is complete. Software can write a '0' to clear this bit (a write of '1' is not allowed). Clearing this bit does not affect any operation already in progress. This bit is automatically cleared by hardware at the start of a new conversion.

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REGISTER 22-2: AD1CON2: ADC CONTROL REGISTER 2

| Bit Range | Bit 31/23/15/7 | Bit 30/22/14/6 | Bit 29/21/13/5 | Bit 28/20/12/4 | Bit 27/19/11/3 | Bit 26/18/10/2 | Bit 25/17/9/1 | Bit 24/16/8/0 |
|-----------|----------------|----------------|----------------|----------------|----------------|----------------|---------------|---------------|
| 31:24 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
| | — | — | — | — | — | — | — | — |
| 23:16 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
| | — | — | — | — | — | — | — | — |
| 15:8 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | U-0 | R/W-0 | U-0 | U-0 |
| | VCFG<2:0> | | | OFFCAL | — | CSCNA | — | — |
| 7:0 | R-0 | U-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
| | BUFS | — | SMPI<3:0> | | | | BUFM | ALTS |

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
 -n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-13 **VCFG<2:0>**: Voltage Reference Configuration bits

| | VREFH | VREFL |
|-----|--------------------|--------------------|
| 000 | AVDD | AVss |
| 001 | External VREF+ pin | AVss |
| 010 | AVDD | External VREF- pin |
| 011 | External VREF+ pin | External VREF- pin |
| 1xx | AVDD | AVss |

bit 12 **OFFCAL:** Input Offset Calibration Mode Select bit

1 = Enable Offset Calibration mode

Positive and negative inputs of the sample and hold amplifier are connected to VREFL

0 = Disable Offset Calibration mode

The inputs to the sample and hold amplifier are controlled by AD1CHS or AD1CSSL

bit 11 **Unimplemented:** Read as '0'

bit 10 **CSCNA:** Input Scan Select bit

1 = Scan inputs

0 = Do not scan inputs

bit 9-8 **Unimplemented:** Read as '0'

bit 7 **BUFS:** Buffer Fill Status bit

Only valid when BUFM = 1.

1 = ADC is currently filling buffer 0x8-0xF, user should access data in 0x0-0x7

0 = ADC is currently filling buffer 0x0-0x7, user should access data in 0x8-0xF

bit 6 **Unimplemented:** Read as '0'

bit 5-2 **SMPI<3:0>**: Sample/Convert Sequences Per Interrupt Selection bits

1111 = Interrupts at the completion of conversion for each 16th sample/convert sequence

1110 = Interrupts at the completion of conversion for each 15th sample/convert sequence

.

.

.

0001 = Interrupts at the completion of conversion for each 2nd sample/convert sequence

0000 = Interrupts at the completion of conversion for each sample/convert sequence

bit 1 **BUFM:** ADC Result Buffer Mode Select bit

1 = Buffer configured as two 8-word buffers, ADC1BUF7-ADC1BUF0, ADC1BUFF-ADC1BUF8

0 = Buffer configured as one 16-word buffer ADC1BUFF-ADC1BUF0

bit 0 **ALTS:** Alternate Input Sample Mode Select bit

1 = Uses Sample A input multiplexer settings for first sample, then alternates between Sample B and

Sample A input multiplexer settings for all subsequent samples

0 = Always use Sample A input multiplexer settings

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REGISTER 22-3: AD1CON3: ADC CONTROL REGISTER 3

| Bit Range | Bit 31/23/15/7 | Bit 30/22/14/6 | Bit 29/21/13/5 | Bit 28/20/12/4 | Bit 27/19/11/3 | Bit 26/18/10/2 | Bit 25/17/9/1 | Bit 24/16/8/0 |
|-----------|--------------------------|----------------|----------------|--------------------------|----------------|----------------|---------------|---------------|
| 31:24 | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — |
| 23:16 | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — |
| 15:8 | R/W-0 ADRC | U-0 — | U-0 — | SAMC<4:0> ⁽¹⁾ | | | | |
| | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W | R/W-0 |
| 7:0 | ADCS<7:0> ⁽²⁾ | | | | | | | |

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
 -n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ADRC:** ADC Conversion Clock Source bit
 1 = Clock derived from FRC
 0 = Clock derived from Peripheral Bus Clock (PBCLK)

bit 14-13 **Unimplemented:** Read as '0'

bit 12-8 **SAMC<4:0>:** Auto-Sample Time bits⁽¹⁾

11111 = 31 TAD

•
•
•

00001 = 1 TAD

00000 = 0 TAD (Not allowed)

bit 7-0 **ADCS<7:0>:** ADC Conversion Clock Select bits⁽²⁾

11111111 = $TPB \cdot 2 \cdot (ADCS<7:0> + 1) = 512 \cdot TPB = TAD$

•
•
•

00000001 = $TPB \cdot 2 \cdot (ADCS<7:0> + 1) = 4 \cdot TPB = TAD$

00000000 = $TPB \cdot 2 \cdot (ADCS<7:0> + 1) = 2 \cdot TPB = TAD$

Note 1: This bit is only used if the SSRC<2:0> bits (AD1CON1<7:5>) = 111.

2: This bit is not used if the ADRC (AD1CON3<15>) bit = 1.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

REGISTER 22-4: AD1CHS: ADC INPUT SELECT REGISTER

| Bit Range | Bit 31/23/15/7 | Bit 30/22/14/6 | Bit 29/21/13/5 | Bit 28/20/12/4 | Bit 27/19/11/3 | Bit 26/18/10/2 | Bit 25/17/9/1 | Bit 24/16/8/0 |
|-----------|----------------|----------------|----------------|----------------|----------------|----------------|---------------|---------------|
| 31:24 | R/W-0 | U-0 | U-0 | U-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
| | CH0NB | — | — | — | CH0SB<3:0> | | | |
| 23:16 | R/W-0 | U-0 | U-0 | U-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
| | CH0NA | — | — | — | CH0SA<3:0> | | | |
| 15:8 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
| | — | — | — | — | — | — | — | — |
| 7:0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
| | — | — | — | — | — | — | — | — |

Legend:

| | | |
|-------------------|------------------|------------------------------------|
| R = Readable bit | W = Writable bit | U = Unimplemented bit, read as '0' |
| -n = Value at POR | '1' = Bit is set | '0' = Bit is cleared |
| | | x = Bit is unknown |

bit 31 **CH0NB:** Negative Input Select bit for Sample B

- 1 = Channel 0 negative input is AN1
- 0 = Channel 0 negative input is VREFL

bit 30-28 **Unimplemented:** Read as '0'

bit 27-24 **CH0SB<3:0>:** Positive Input Select bits for Sample B

- 1111 = Channel 0 positive input is Open⁽¹⁾
- 1110 = Channel 0 positive input is IVREF⁽²⁾
- 1101 = Channel 0 positive input is CTMU temperature sensor (CTMUT)⁽³⁾
- 1100 = Channel 0 positive input is AN12⁽⁴⁾
-
-
-
- 0001 = Channel 0 positive input is AN1
- 0000 = Channel 0 positive input is AN0

bit 23 **CH0NA:** Negative Input Select bit for Sample A Multiplexer Setting⁽²⁾

- 1 = Channel 0 negative input is AN1
- 0 = Channel 0 negative input is VREFL

bit 22-20 **Unimplemented:** Read as '0'

bit 19-16 **CH0SA<3:0>:** Positive Input Select bits for Sample A Multiplexer Setting

- 1111 = Channel 0 positive input is Open⁽¹⁾
- 1110 = Channel 0 positive input is IVREF⁽²⁾
- 1101 = Channel 0 positive input is CTMU temperature (CTMUT)⁽³⁾
- 1100 = Channel 0 positive input is AN12⁽⁴⁾
-
-
-
- 0001 = Channel 0 positive input is AN1
- 0000 = Channel 0 positive input is AN0

bit 15-0 **Unimplemented:** Read as '0'

Note 1: This selection is only used with CTMU capacitive and time measurement.

2: See [Section 24.0 “Comparator Voltage Reference \(CVREF\)”](#) for more information.

3: See [Section 25.0 “Charge Time Measurement Unit \(CTMU\)”](#) for more information.

4: AN12 is only available on 44-pin devices. AN6-AN8 are not available on 28-pin devices.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

REGISTER 22-5: AD1CSSL: ADC INPUT SCAN SELECT REGISTER

| Bit Range | Bit 31/23/15/7 | Bit 30/22/14/6 | Bit 29/21/13/5 | Bit 28/20/12/4 | Bit 27/19/11/3 | Bit 26/18/10/2 | Bit 25/17/9/1 | Bit 24/16/8/0 |
|-----------|----------------|----------------|----------------|----------------|----------------|----------------|---------------|---------------|
| 31:24 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
| | — | — | — | — | — | — | — | — |
| 23:16 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
| | — | — | — | — | — | — | — | — |
| 15:8 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
| | CSSL15 | CSSL14 | CSSL13 | CSSL12 | CSSL11 | CSSL10 | CSSL9 | CSSL8 |
| 7:0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
| | CSSL7 | CSSL6 | CSSL5 | CSSL4 | CSSL3 | CSSL2 | CSSL1 | CSSL0 |

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-0 **CSSL<15:0>:** ADC Input Pin Scan Selection bits^(1,2)

1 = Select ANx for input scan

0 = Skip ANx for input scan

Note 1: CSSL = ANx, where 'x' = 0-12; CSSL13 selects CTMU input for scan; CSSL14 selects IVREF for scan; CSSL15 selects Vss for scan.

2: On devices with less than 13 analog inputs, all CSSLx bits can be selected; however, inputs selected for scan without a corresponding input on the device will convert to VREFL.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

23.0 COMPARATOR

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 19. “Comparator”** (DS60001110), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

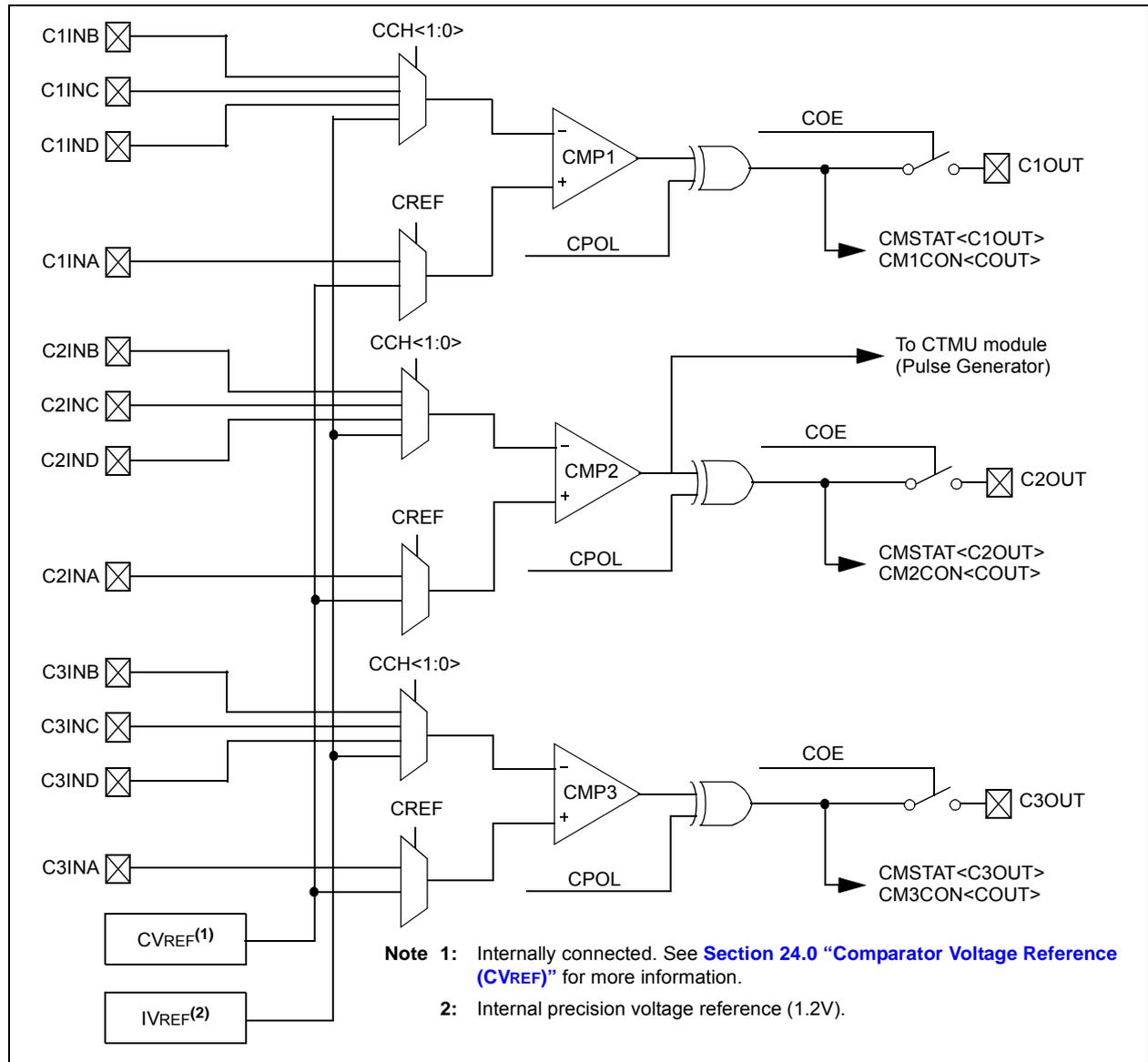
The Analog Comparator module contains three comparators that can be configured in a variety of ways.

Following are some of the key features of this module:

- Selectable inputs available include:
 - Analog inputs multiplexed with I/O pins
 - On-chip internal absolute voltage reference (IVREF)
 - Comparator voltage reference (CVREF)
- Outputs can be Inverted
- Selectable interrupt generation

A block diagram of the comparator module is provided in [Figure 23-1](#).

FIGURE 23-1: COMPARATOR BLOCK DIAGRAM



23.1 Comparator Control Registers

TABLE 23-1: COMPARATOR REGISTER MAP

| Virtual Address (BF80_#) | Register Name ⁽¹⁾ | Bit Range | Bits | | | | | | | | | | | | | | | All Resets |
|-----------------------------|---------------------------------|-----------|-------|-------|-------|-------|-------|-------|------|------|------------|------|------|------|------|-------|----------|------------|
| | | | 31/15 | 30/14 | 29/13 | 28/12 | 27/11 | 26/10 | 25/9 | 24/8 | 23/7 | 22/6 | 21/5 | 20/4 | 19/3 | 18/2 | 17/1 | |
| A000 | CM1CON | 31:16 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | 0000 |
| | | 15:0 | ON | COE | CPOL | — | — | — | — | COUT | EVPOL<1:0> | — | CREF | — | — | — | CCH<1:0> | 00c3 |
| A010 | CM2CON | 31:16 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | 0000 |
| | | 15:0 | ON | COE | CPOL | — | — | — | — | COUT | EVPOL<1:0> | — | CREF | — | — | — | CCH<1:0> | 00c3 |
| A020 | CM3CON | 31:16 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | 0000 |
| | | 15:0 | ON | COE | CPOL | — | — | — | — | COUT | EVPOL<1:0> | — | CREF | — | — | — | CCH<1:0> | 00c3 |
| A060 | CMSTAT | 31:16 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | 0000 |
| | | 15:0 | — | — | SIDL | — | — | — | — | — | — | — | — | — | — | C3OUT | C2OUT | C1OUT |

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See [Section 11.2 “CLR, SET and INV Registers”](#) for more information.

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REGISTER 23-1: CMXCON: COMPARATOR CONTROL REGISTER

| Bit Range | Bit 31/23/15/7 | Bit 30/22/14/6 | Bit 29/21/13/5 | Bit 28/20/12/4 | Bit 27/19/11/3 | Bit 26/18/10/2 | Bit 25/17/9/1 | Bit 24/16/8/0 |
|-----------|-------------------|----------------|---------------------|----------------|----------------|----------------|---------------|------------------|
| 31:24 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
| | — | — | — | — | — | — | — | — |
| 23:16 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
| | — | — | — | — | — | — | — | — |
| 15:8 | R/W-0 | R/W-0 | R/W-0 | U-0 | U-0 | U-0 | U-0 | R-0 |
| | ON ⁽¹⁾ | COE | CPOL ⁽²⁾ | — | — | — | — | COU ^T |
| 7:0 | R/W-1 | R/W-1 | U-0 | R/W-0 | U-0 | U-0 | R/W-1 | R/W-1 |
| | EVPOL<1:0> | | — | CREF | — | — | CCH<1:0> | |

Legend:

| | | |
|-------------------|------------------|----------------------------------------------|
| R = Readable bit | W = Writable bit | U = Unimplemented bit, read as '0' |
| -n = Value at POR | '1' = Bit is set | '0' = Bit is cleared x = Bit is unknown |

- bit 31-16 **Unimplemented:** Read as '0'
- bit 15 **ON:** Comparator ON bit⁽¹⁾
 - 1 = Module is enabled. Setting this bit does not affect the other bits in this register
 - 0 = Module is disabled and does not consume current. Clearing this bit does not affect the other bits in this register
- bit 14 **COE:** Comparator Output Enable bit
 - 1 = Comparator output is driven on the output CxOUT pin
 - 0 = Comparator output is not driven on the output CxOUT pin
- bit 13 **CPOL:** Comparator Output Inversion bit⁽²⁾
 - 1 = Output is inverted
 - 0 = Output is not inverted
- bit 12-9 **Unimplemented:** Read as '0'
- bit 8 **COU^T:** Comparator Output bit
 - 1 = Output of the Comparator is a '1'
 - 0 = Output of the Comparator is a '0'
- bit 7-6 **EVPOL<1:0>:** Interrupt Event Polarity Select bits
 - 11 = Comparator interrupt is generated on a low-to-high or high-to-low transition of the comparator output
 - 10 = Comparator interrupt is generated on a high-to-low transition of the comparator output
 - 01 = Comparator interrupt is generated on a low-to-high transition of the comparator output
 - 00 = Comparator interrupt generation is disabled
- bit 5 **Unimplemented:** Read as '0'
- bit 4 **CREF:** Comparator Positive Input Configure bit
 - 1 = Comparator non-inverting input is connected to the internal CVREF
 - 0 = Comparator non-inverting input is connected to the CxINA pin
- bit 3-2 **Unimplemented:** Read as '0'
- bit 1-0 **CCH<1:0>:** Comparator Negative Input Select bits for Comparator
 - 11 = Comparator inverting input is connected to the IVREF
 - 10 = Comparator inverting input is connected to the CxIND pin
 - 01 = Comparator inverting input is connected to the CxINC pin
 - 00 = Comparator inverting input is connected to the CxINB pin

- Note 1:** When using the 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.
- 2:** Setting this bit will invert the signal to the comparator interrupt generator as well. This will result in an interrupt being generated on the opposite edge from the one selected by EVPOL<1:0>.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

REGISTER 23-2: CMSTAT: COMPARATOR STATUS REGISTER

| Bit Range | Bit 31/23/15/7 | Bit 30/22/14/6 | Bit 29/21/13/5 | Bit 28/20/12/4 | Bit 27/19/11/3 | Bit 26/18/10/2 | Bit 25/17/9/1 | Bit 24/16/8/0 |
|-----------|----------------|----------------|----------------|----------------|----------------|----------------|---------------|---------------|
| 31:24 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
| | — | — | — | — | — | — | — | — |
| 23:16 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
| | — | — | — | — | — | — | — | — |
| 15:8 | U-0 | U-0 | R/W-0 | U-0 | U-0 | U-0 | U-0 | U-0 |
| | — | — | SIDL | — | — | — | — | — |
| 7:0 | U-0 | U-0 | U-0 | U-0 | U-0 | R-0 | R-0 | R-0 |
| | — | — | — | — | — | C3OUT | C2OUT | C1OUT |

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
 -n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 31-14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Stop in Idle Control bit

- 1 = All Comparator modules are disabled when the device enters Idle mode
- 0 = All Comparator modules continue to operate when the device enters Idle mode

bit 12-3 **Unimplemented:** Read as '0'

bit 2 **C3OUT:** Comparator Output bit

- 1 = Output of Comparator 3 is a '1'
- 0 = Output of Comparator 3 is a '0'

bit 1 **C2OUT:** Comparator Output bit

- 1 = Output of Comparator 2 is a '1'
- 0 = Output of Comparator 2 is a '0'

bit 0 **C1OUT:** Comparator Output bit

- 1 = Output of Comparator 1 is a '1'
- 0 = Output of Comparator 1 is a '0'

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

24.0 COMPARATOR VOLTAGE REFERENCE (CVREF)

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 20. “Comparator Voltage Reference (CVREF)”** (DS60001109), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The CVREF module is a 16-tap, resistor ladder network that provides a selectable reference voltage. Although its primary purpose is to provide a reference for the analog comparators, it also may be used independently of them.

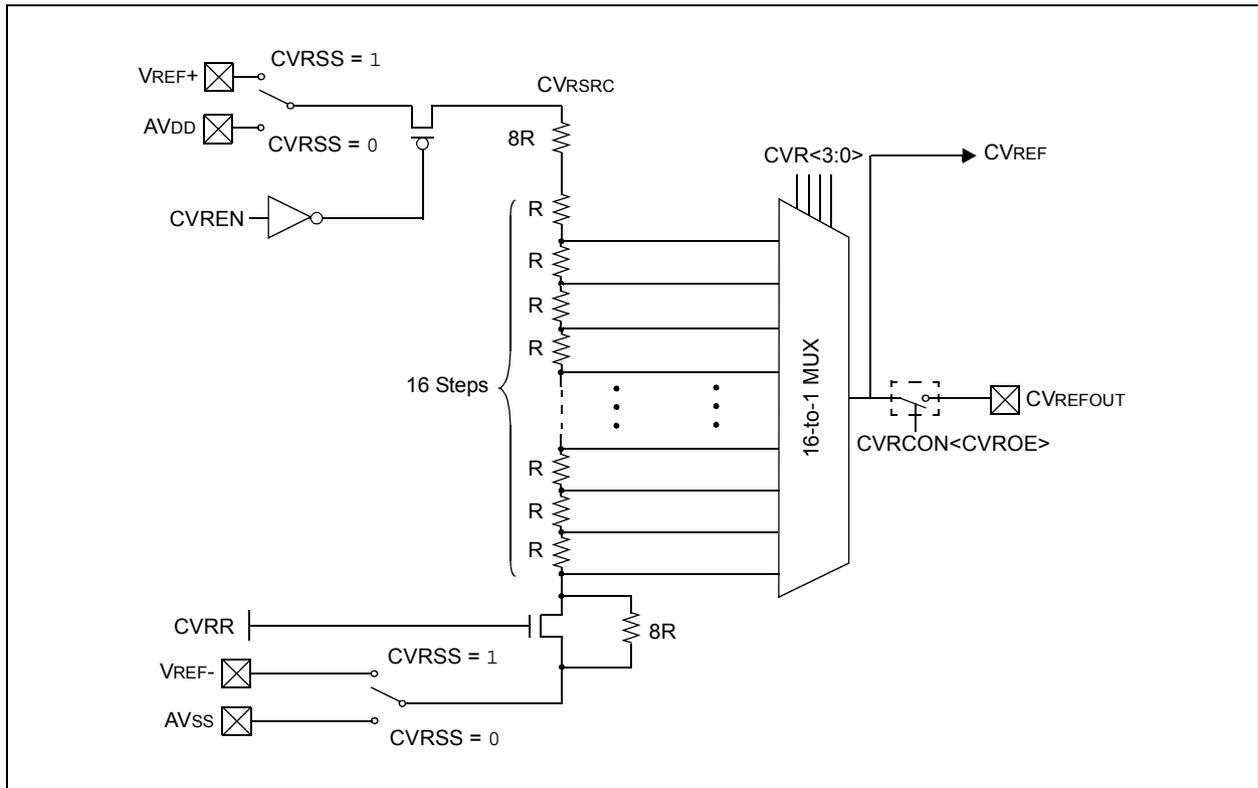
The resistor ladder is segmented to provide two ranges of voltage reference values and has a power-down function to conserve power when the reference is not being used. The module’s supply reference can be provided from either device VDD/VSS or an external voltage reference. The CVREF output is available for the comparators and typically available for pin output.

The comparator voltage reference has the following features:

- High and low range selection
- Sixteen output levels available for each range
- Internally connected to comparators to conserve device pins
- Output can be connected to a pin

A block diagram of the module is shown in [Figure 24-1](#).

FIGURE 24-1: COMPARATOR VOLTAGE REFERENCE BLOCK DIAGRAM



24.1 Comparator Voltage Reference Control Register

TABLE 24-1: COMPARATOR VOLTAGE REFERENCE REGISTER MAP

| Virtual Address (BF80_#) | Register Name | Bit Range | Bits | | | | | | | | | | | | | | | All Resets |
|-----------------------------|------------------|-----------|-------|-------|-------|-------|-------|-------|------|------|------|-------|------|-------|----------|------|------|------------|
| | | | 31/15 | 30/14 | 29/13 | 28/12 | 27/11 | 26/10 | 25/9 | 24/8 | 23/7 | 22/6 | 21/5 | 20/4 | 19/3 | 18/2 | 17/1 | |
| 9800 | CVRCON | 31:16 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | 0000 |
| | | 15:0 | ON | — | — | — | — | — | — | — | — | CVROE | CVRR | CVRSS | CVR<3:0> | | | 0000 |

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See [Section 11.2 "CLR, SET and INV Registers"](#) for more information.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

REGISTER 24-1: CVRCON: COMPARATOR VOLTAGE REFERENCE CONTROL REGISTER

| Bit Range | Bit 31/23/15/7 | Bit 30/22/14/6 | Bit 29/21/13/5 | Bit 28/20/12/4 | Bit 27/19/11/3 | Bit 26/18/10/2 | Bit 25/17/9/1 | Bit 24/16/8/0 |
|-----------|----------------------------|----------------|----------------|----------------|----------------|----------------|---------------|---------------|
| 31:24 | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — |
| 23:16 | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — |
| 15:8 | R/W-0 ON ⁽¹⁾ | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — |
| 7:0 | U-0 — | R/W-0 CVROE | R/W-0 CVRR | R/W-0 CVRSS | CVR<3:0> | | | |

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** Comparator Voltage Reference On bit⁽¹⁾

1 = Module is enabled

Setting this bit does not affect other bits in the register.

0 = Module is disabled and does not consume current.

Clearing this bit does not affect the other bits in the register.

bit 14-7 **Unimplemented:** Read as '0'

bit 6 **CVROE:** CVREFOUT Enable bit

1 = Voltage level is output on CVREFOUT pin

0 = Voltage level is disconnected from CVREFOUT pin

bit 5 **CVRR:** CVREF Range Selection bit

1 = 0 to 0.67 CVRSRC, with CVRSRC/24 step size

0 = 0.25 CVRSRC to 0.75 CVRSRC, with CVRSRC/32 step size

bit 4 **CVRSS:** CVREF Source Selection bit

1 = Comparator voltage reference source, CVRSRC = (VREF+) – (VREF-)

0 = Comparator voltage reference source, CVRSRC = AVDD – AVSS

bit 3-0 **CVR<3:0>:** CVREF Value Selection $0 \leq \text{CVR}<3:0> \leq 15$ bits

When CVRR = 1:

$\text{CVREF} = (\text{CVR}<3:0>/24) \cdot (\text{CVRSRC})$

When CVRR = 0:

$\text{CVREF} = 1/4 \cdot (\text{CVRSRC}) + (\text{CVR}<3:0>/32) \cdot (\text{CVRSRC})$

Note 1: When using 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

NOTES:

25.0 CHARGE TIME MEASUREMENT UNIT (CTMU)

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 37. “Charge Time Measurement Unit (CTMU)”** (DS60001167), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

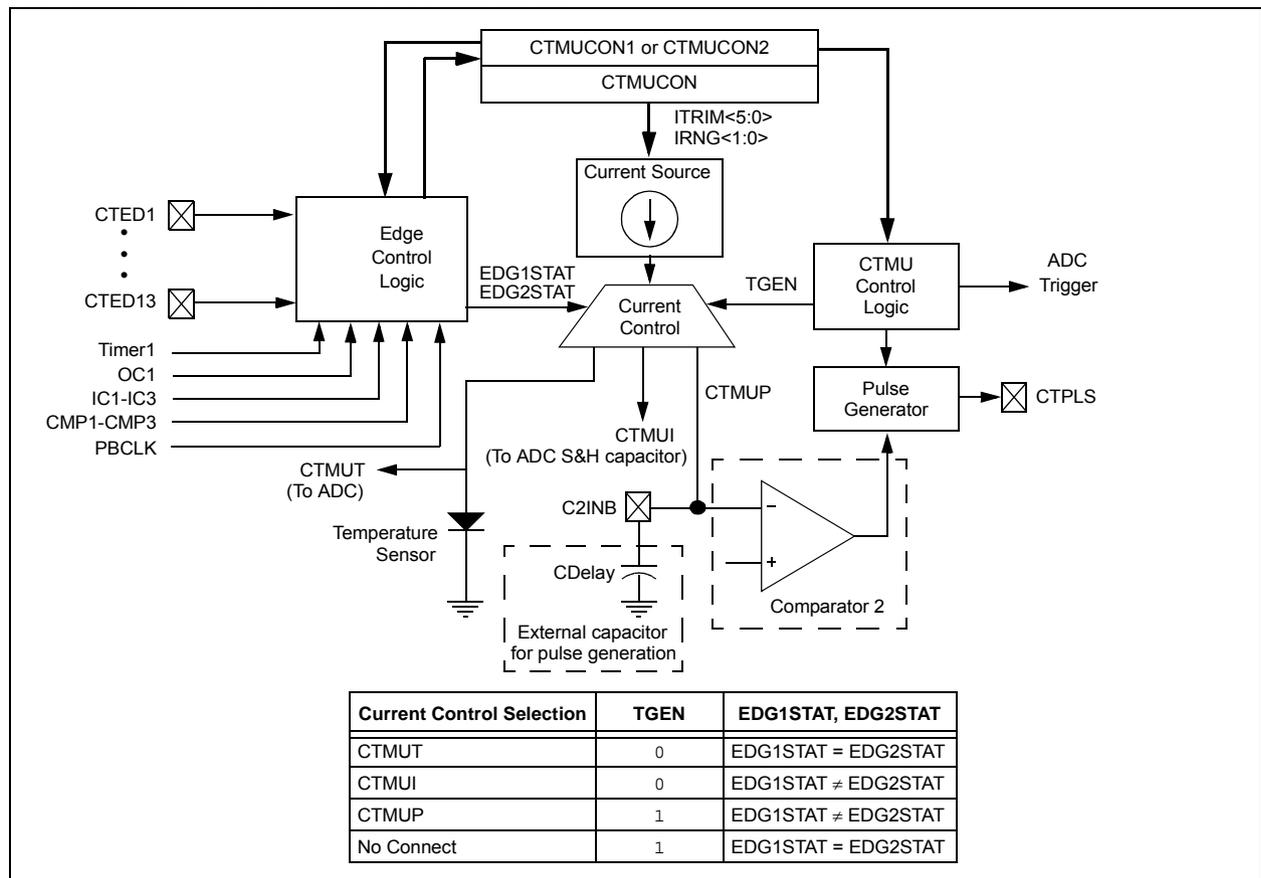
The Charge Time Measurement Unit (CTMU) is a flexible analog module that has a configurable current source with a digital configuration circuit built around it. The CTMU can be used for differential time measurement between pulse sources and can be used for generating an asynchronous pulse. By working with other on-chip analog modules, the CTMU can be used for high resolution time measurement, measure capacitance, measure relative changes in capacitance or generate output pulses with a specific time delay. The CTMU is ideal for interfacing with capacitive-based sensors.

The CTMU module includes the following key features:

- Up to 13 channels available for capacitive or time measurement input
- On-chip precision current source
- 16-edge input trigger sources
- Selection of edge or level-sensitive inputs
- Polarity control for each edge source
- Control of edge sequence
- Control of response to edges
- High precision time measurement
- Time delay of external or internal signal asynchronous to system clock
- Integrated temperature sensing diode
- Control of current source during auto-sampling
- Four current source ranges
- Time measurement resolution of one nanosecond

A block diagram of the CTMU is shown in [Figure 25-1](#).

FIGURE 25-1: CTMU BLOCK DIAGRAM



25.1 CTMU Control Registers

TABLE 25-1: CTMU REGISTER MAP

| Virtual Address (BF80_#) | Register Name ⁽¹⁾ | Bit Range | Bits | | | | | | | | | | | | | | All Resets | |
|-----------------------------|---------------------------------|-----------|---------|---------|--------------|-------|-------|----------|----------|----------|------------|---------|--------------|------|------|-----------|------------|------|
| | | | 31/15 | 30/14 | 29/13 | 28/12 | 27/11 | 26/10 | 25/9 | 24/8 | 23/7 | 22/6 | 21/5 | 20/4 | 19/3 | 18/2 | | 17/1 |
| A200 | CTMUCON | 31:16 | EDG1MOD | EDG1POL | EDG1SEL<3:0> | | | | EDG2STAT | EDG1STAT | EDG2MOD | EDG2POL | EDG2SEL<3:0> | | | — | — | 0000 |
| | | 15:0 | ON | — | CTMUSIDL | TGEN | EDGEN | EDGSEQEN | IDISSEN | CTTRIG | ITRIM<5:0> | | | | | IRNG<1:0> | | 0000 |

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC, respectively. See [Section 11.2 "CLR, SET and INV Registers"](#) for more information.

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REGISTER 25-1: CTMUCON: CTMU CONTROL REGISTER

| Bit Range | Bit 31/23/15/7 | Bit 30/22/14/6 | Bit 29/21/13/5 | Bit 28/20/12/4 | Bit 27/19/11/3 | Bit 26/18/10/2 | Bit 25/17/9/1 | Bit 24/16/8/0 |
|-----------|----------------|----------------|----------------|---------------------|----------------|----------------|------------------------|---------------|
| 31:24 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
| | EDG1MOD | EDG1POL | EDG1SEL<3:0> | | | | EDG2STAT | EDG1STAT |
| 23:16 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | U-0 | U-0 |
| | EDG2MOD | EDG2POL | EDG2SEL<3:0> | | | | — | — |
| 15:8 | R/W-0 | U-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
| | ON | — | CTMUSIDL | TGEN ⁽¹⁾ | EDGEN | EDGSEQEN | IDISSEN ⁽²⁾ | CTTRIG |
| 7:0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 | R/W-0 |
| | ITRIM<5:0> | | | | | | IRNG<1:0> | |

Legend:

R = Readable bit

W = Writable bit

U = Unimplemented bit, read as '0'

-n = Value at POR

'1' = Bit is set

'0' = Bit is cleared

x = Bit is unknown

bit 31 **EDG1MOD:** Edge1 Edge Sampling Select bit

1 = Input is edge-sensitive

0 = Input is level-sensitive

bit 30 **EDG1POL:** Edge 1 Polarity Select bit

1 = Edge1 programmed for a positive edge response

0 = Edge1 programmed for a negative edge response

bit 29-26 **EDG1SEL<3:0>:** Edge 1 Source Select bits

1111 = C3OUT pin is selected

1110 = C2OUT pin is selected

1101 = C1OUT pin is selected

1100 = IC3 Capture Event is selected

1011 = IC2 Capture Event is selected

1010 = IC1 Capture Event is selected

1001 = CTED8 pin is selected

1000 = CTED7 pin is selected

0111 = CTED6 pin is selected

0110 = CTED5 pin is selected

0101 = CTED4 pin is selected

0100 = CTED3 pin is selected

0011 = CTED1 pin is selected

0010 = CTED2 pin is selected

0001 = OC1 Compare Event is selected

0000 = Timer1 Event is selected

bit 25 **EDG2STAT:** Edge2 Status bit

Indicates the status of Edge2 and can be written to control edge source

1 = Edge2 has occurred

0 = Edge2 has not occurred

Note 1: When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to '1110' to select C2OUT.

2: The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to '1', performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.

3: Refer to the CTMU Current Source Specifications (Table 30-41) in [Section 30.0 "Electrical Characteristics"](#) for current values.

4: This bit setting is not available for the CTMU temperature diode.

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REGISTER 25-1: CTMUCON: CTMU CONTROL REGISTER (CONTINUED)

- bit 24 **EDG1STAT:** Edge1 Status bit
Indicates the status of Edge1 and can be written to control edge source
1 = Edge1 has occurred
0 = Edge1 has not occurred
- bit 23 **EDG2MOD:** Edge2 Edge Sampling Select bit
1 = Input is edge-sensitive
0 = Input is level-sensitive
- bit 22 **EDG2POL:** Edge 2 Polarity Select bit
1 = Edge2 programmed for a positive edge response
0 = Edge2 programmed for a negative edge response
- bit 21-18 **EDG2SEL<3:0>:** Edge 2 Source Select bits
1111 = C3OUT pin is selected
1110 = C2OUT pin is selected
1101 = C1OUT pin is selected
1100 = PBCLK clock is selected
1011 = IC3 Capture Event is selected
1010 = IC2 Capture Event is selected
1001 = IC1 Capture Event is selected
1000 = CTED13 pin is selected
0111 = CTED12 pin is selected
0110 = CTED11 pin is selected
0101 = CTED10 pin is selected
0100 = CTED9 pin is selected
0011 = CTED1 pin is selected
0010 = CTED2 pin is selected
0001 = OC1 Compare Event is selected
0000 = Timer1 Event is selected
- bit 17-16 **Unimplemented:** Read as '0'
- bit 15 **ON:** ON Enable bit
1 = Module is enabled
0 = Module is disabled
- bit 14 **Unimplemented:** Read as '0'
- bit 13 **CTMUSIDL:** Stop in Idle Mode bit
1 = Discontinue module operation when the device enters Idle mode
0 = Continue module operation when the device enters Idle mode
- bit 12 **TGEN:** Time Generation Enable bit⁽¹⁾
1 = Enables edge delay generation
0 = Disables edge delay generation
- bit 11 **EDGEN:** Edge Enable bit
1 = Edges are not blocked
0 = Edges are blocked

- Note 1:** When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to '1110' to select C2OUT.
- 2:** The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to '1', performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.
- 3:** Refer to the CTMU Current Source Specifications (Table 30-41) in [Section 30.0 "Electrical Characteristics"](#) for current values.
- 4:** This bit setting is not available for the CTMU temperature diode.

REGISTER 25-1: CTMUCON: CTMU CONTROL REGISTER (CONTINUED)

- bit 10 **EDGSEQEN**: Edge Sequence Enable bit
1 = Edge1 must occur before Edge2 can occur
0 = No edge sequence is needed
- bit 9 **IDISSEN**: Analog Current Source Control bit⁽²⁾
1 = Analog current source output is grounded
0 = Analog current source output is not grounded
- bit 8 **CTTRIG**: Trigger Control bit
1 = Trigger output is enabled
0 = Trigger output is disabled
- bit 7-2 **ITRIM<5:0>**: Current Source Trim bits
011111 = Maximum positive change from nominal current
011110
.
.
.
000001 = Minimum positive change from nominal current
000000 = Nominal current output specified by IRNG<1:0>
111111 = Minimum negative change from nominal current
.
.
.
100010
100001 = Maximum negative change from nominal current
- bit 1-0 **IRNG<1:0>**: Current Range Select bits⁽³⁾
11 = 100 times base current
10 = 10 times base current
01 = Base current level
00 = 1000 times base current⁽⁴⁾

- Note 1:** When this bit is set for Pulse Delay Generation, the EDG2SEL<3:0> bits must be set to '1110' to select C2OUT.
- 2:** The ADC module Sample and Hold capacitor is not automatically discharged between sample/conversion cycles. Software using the ADC as part of a capacitive measurement, must discharge the ADC capacitor before conducting the measurement. The IDISSEN bit, when set to '1', performs this function. The ADC module must be sampling while the IDISSEN bit is active to connect the discharge sink to the capacitor array.
- 3:** Refer to the CTMU Current Source Specifications (Table 30-41) in Section 30.0 "Electrical Characteristics" for current values.
- 4:** This bit setting is not available for the CTMU temperature diode.

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NOTES:

26.0 POWER-SAVING FEATURES

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 10. “Power-Saving Features”** (DS60001130), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

This section describes power-saving features for the PIC32MX1XX/2XX 28/36/44-pin Family. The PIC32 devices offer a total of nine methods and modes, organized into two categories, that allow the user to balance power consumption with device performance. In all of the methods and modes described in this section, power-saving is controlled by software.

26.1 Power Saving with CPU Running

When the CPU is running, power consumption can be controlled by reducing the CPU clock frequency, lowering the PBCLK and by individually disabling modules. These methods are grouped into the following categories:

- FRC Run mode: the CPU is clocked from the FRC clock source with or without postscalers
- LPRC Run mode: the CPU is clocked from the LPRC clock source
- Sosc Run mode: the CPU is clocked from the Sosc clock source

In addition, the Peripheral Bus Scaling mode is available where peripherals are clocked at the programmable fraction of the CPU clock (SYSCLK).

26.2 CPU Halted Methods

The device supports two power-saving modes, Sleep and Idle, both of which Halt the clock to the CPU. These modes operate with all clock sources, as follows:

- Posc Idle mode: the system clock is derived from the Posc. The system clock source continues to operate. Peripherals continue to operate, but can optionally be individually disabled.
- FRC Idle mode: the system clock is derived from the FRC with or without postscalers. Peripherals continue to operate, but can optionally be individually disabled.
- Sosc Idle mode: the system clock is derived from the Sosc. Peripherals continue to operate, but can optionally be individually disabled.

- LPRC Idle mode: the system clock is derived from the LPRC. Peripherals continue to operate, but can optionally be individually disabled. This is the lowest power mode for the device with a clock running.
- Sleep mode: the CPU, the system clock source and any peripherals that operate from the system clock source are Halted. Some peripherals can operate in Sleep using specific clock sources. This is the lowest power mode for the device.

26.3 Power-Saving Operation

Peripherals and the CPU can be Halted or disabled to further reduce power consumption.

26.3.1 SLEEP MODE

Sleep mode has the lowest power consumption of the device power-saving operating modes. The CPU and most peripherals are Halted. Select peripherals can continue to operate in Sleep mode and can be used to wake the device from Sleep. See the individual peripheral module sections for descriptions of behavior in Sleep.

Sleep mode includes the following characteristics:

- The CPU is halted
- The system clock source is typically shutdown. See [Section 26.3.3 “Peripheral Bus Scaling Method”](#) for specific information.
- There can be a wake-up delay based on the oscillator selection
- The Fail-Safe Clock Monitor (FSCM) does not operate during Sleep mode
- The BOR circuit remains operative during Sleep mode
- The WDT, if enabled, is not automatically cleared prior to entering Sleep mode
- Some peripherals can continue to operate at limited functionality in Sleep mode. These peripherals include I/O pins that detect a change in the input signal, WDT, ADC, UART and peripherals that use an external clock input or the internal LPRC oscillator (e.g., RTCC, Timer1 and Input Capture).
- I/O pins continue to sink or source current in the same manner as they do when the device is not in Sleep
- The USB module can override the disabling of the Posc or FRC. Refer to the USB section for specific details.
- Modules can be individually disabled by software prior to entering Sleep in order to further reduce consumption

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The processor will exit, or 'wake-up', from Sleep on one of the following events:

- On any interrupt from an enabled source that is operating in Sleep. The interrupt priority must be greater than the current CPU priority.
- On any form of device Reset
- On a WDT time-out

If the interrupt priority is lower than or equal to the current priority, the CPU will remain Halted, but the PBCLK will start running and the device will enter into Idle mode.

26.3.2 IDLE MODE

In Idle mode, the CPU is Halted but the System Clock (SYSCLK) source is still enabled. This allows peripherals to continue operation when the CPU is Halted. Peripherals can be individually configured to Halt when entering Idle by setting their respective SIDL bit. Latency, when exiting Idle mode, is very low due to the CPU oscillator source remaining active.

Note 1: Changing the PBCLK divider ratio requires recalculation of peripheral timing. For example, assume the UART is configured for 9600 baud with a PB clock ratio of 1:1 and a P_{osc} of 8 MHz. When the PB clock divisor of 1:2 is used, the input frequency to the baud clock is cut in half; therefore, the baud rate is reduced to 1/2 its former value. Due to numeric truncation in calculations (such as the baud rate divisor), the actual baud rate may be a tiny percentage different than expected. For this reason, any timing calculation required for a peripheral should be performed with the new PB clock frequency instead of scaling the previous value based on a change in the PB divisor ratio.

- 2: Oscillator start-up and PLL lock delays are applied when switching to a clock source that was disabled and that uses a crystal and/or the PLL. For example, assume the clock source is switched from P_{osc} to LPRC just prior to entering Sleep in order to save power. No oscillator start-up delay would be applied when exiting Idle. However, when switching back to P_{osc}, the appropriate PLL and/or oscillator start-up/lock delays would be applied.

The device enters Idle mode when the SLPEN (OSCCON<4>) bit is clear and a WAIT instruction is executed.

The processor will wake or exit from Idle mode on the following events:

- On any interrupt event for which the interrupt source is enabled. The priority of the interrupt event must be greater than the current priority of the CPU. If the priority of the interrupt event is lower than or equal to current priority of the CPU, the CPU will remain Halted and the device will remain in Idle mode.
- On any form of device Reset
- On a WDT time-out interrupt

26.3.3 PERIPHERAL BUS SCALING METHOD

Most of the peripherals on the device are clocked using the PBCLK. The Peripheral Bus can be scaled relative to the SYSCLK to minimize the dynamic power consumed by the peripherals. The PBCLK divisor is controlled by PBDIV<1:0> (OSCCON<20:19>), allowing SYSCLK to PBCLK ratios of 1:1, 1:2, 1:4 and 1:8. All peripherals using PBCLK are affected when the divisor is changed. Peripherals such as the USB, Interrupt Controller, DMA, and the bus matrix are clocked directly from SYSCLK. As a result, they are not affected by PBCLK divisor changes.

Changing the PBCLK divisor affects:

- The CPU to peripheral access latency. The CPU has to wait for next PBCLK edge for a read to complete. In 1:8 mode, this results in a latency of one to seven SYSCLKs.
- The power consumption of the peripherals. Power consumption is directly proportional to the frequency at which the peripherals are clocked. The greater the divisor, the lower the power consumed by the peripherals.

To minimize dynamic power, the PB divisor should be chosen to run the peripherals at the lowest frequency that provides acceptable system performance. When selecting a PBCLK divider, peripheral clock requirements, such as baud rate accuracy, should be taken into account. For example, the UART peripheral may not be able to achieve all baud rate values at some PBCLK divider depending on the SYSCLK value.

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26.4 Peripheral Module Disable

The Peripheral Module Disable (PMD) registers provide a method to disable a peripheral module by stopping all clock sources supplied to that module. When a peripheral is disabled using the appropriate PMD control bit, the peripheral is in a minimum power consumption state. The control and status registers associated with the peripheral are also disabled, so writes to those registers do not have effect and read values are invalid.

To disable a peripheral, the associated PMDx bit must be set to '1'. To enable a peripheral, the associated PMDx bit must be cleared (default). See [Table 26-1](#) for more information.

Note: Disabling a peripheral module while it's ON bit is set, may result in undefined behavior. The ON bit for the associated peripheral module must be cleared prior to disable a module via the PMDx bits.

TABLE 26-1: PERIPHERAL MODULE DISABLE BITS AND LOCATIONS

| Peripheral ⁽¹⁾ | PMDx bit Name ⁽¹⁾ | Register Name and Bit Location |
|------------------------------|------------------------------|--------------------------------|
| ADC1 | AD1MD | PMD1<0> |
| CTMU | CTMUMD | PMD1<8> |
| Comparator Voltage Reference | CVRMD | PMD1<12> |
| Comparator 1 | CMP1MD | PMD2<0> |
| Comparator 2 | CMP2MD | PMD2<1> |
| Comparator 3 | CMP3MD | PMD2<2> |
| Input Capture 1 | IC1MD | PMD3<0> |
| Input Capture 2 | IC2MD | PMD3<1> |
| Input Capture 3 | IC3MD | PMD3<2> |
| Input Capture 4 | IC4MD | PMD3<3> |
| Input Capture 5 | IC5MD | PMD3<4> |
| Output Compare 1 | OC1MD | PMD3<16> |
| Output Compare 2 | OC2MD | PMD3<17> |
| Output Compare 3 | OC3MD | PMD3<18> |
| Output Compare 4 | OC4MD | PMD3<19> |
| Output Compare 5 | OC5MD | PMD3<20> |
| Timer1 | T1MD | PMD4<0> |
| Timer2 | T2MD | PMD4<1> |
| Timer3 | T3MD | PMD4<2> |
| Timer4 | T4MD | PMD4<3> |
| Timer5 | T5MD | PMD4<4> |
| UART1 | U1MD | PMD5<0> |
| UART2 | U2MD | PMD5<1> |
| SPI1 | SPI1MD | PMD5<8> |
| SPI2 | SPI2MD | PMD5<9> |
| I2C1 | I2C1MD | PMD5<16> |
| I2C2 | I2C2MD | PMD5<17> |
| USB ⁽²⁾ | USBMD | PMD5<24> |
| RTCC | RTCCMD | PMD6<0> |
| Reference Clock Output | REFOMD | PMD6<1> |
| PMP | PMPMD | PMD6<16> |

Note 1: Not all modules and associated PMDx bits are available on all devices. See [TABLE 1: “PIC32MX1XX 28/36/44-Pin General Purpose Family Features”](#) and [TABLE 2: “PIC32MX2XX 28/36/44-pin USB Family Features”](#) for the lists of available peripherals.

2: The module must not be busy after clearing the associated ON bit and prior to setting the USBMD bit.

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26.4.1 CONTROLLING CONFIGURATION CHANGES

Because peripherals can be disabled during run time, some restrictions on disabling peripherals are needed to prevent accidental configuration changes. PIC32 devices include two features to prevent alterations to enabled or disabled peripherals:

- Control register lock sequence
- Configuration bit select lock

26.4.1.1 Control Register Lock

Under normal operation, writes to the PMDx registers are not allowed. Attempted writes appear to execute normally, but the contents of the registers remain unchanged. To change these registers, they must be unlocked in hardware. The register lock is controlled by the Configuration bit, PMDLOCK (CFGCON<12>). Setting PMDLOCK prevents writes to the control registers; clearing PMDLOCK allows writes.

To set or clear PMDLOCK, an unlock sequence must be executed. Refer to **Section 6. “Oscillator”** (DS60001112) in the *“PIC32 Family Reference Manual”* for details.

26.4.1.2 Configuration Bit Select Lock

As an additional level of safety, the device can be configured to prevent more than one write session to the PMDx registers. The Configuration bit, PMDL1WAY (DEVCFG3<28>), blocks the PMDLOCK bit from being cleared after it has been set once. If PMDLOCK remains set, the register unlock procedure does not execute, and the peripheral pin select control registers cannot be written to. The only way to clear the bit and re-enable PMD functionality is to perform a device Reset.

TABLE 26-2: PERIPHERAL MODULE DISABLE REGISTER MAP

| Virtual Address (BF80_#) | Register Name ⁽¹⁾ | Bit Range | Bits | | | | | | | | | | | | | | | | All Resets | | | | | |
|-----------------------------|---------------------------------|-----------|-------|-------|-------|-------|-------|-------|------|--------|------|------|------|------|------|------|------|------|------------|--------|--------|-------|--------|--------|
| | | | 31/15 | 30/14 | 29/13 | 28/12 | 27/11 | 26/10 | 25/9 | 24/8 | 23/7 | 22/6 | 21/5 | 20/4 | 19/3 | 18/2 | 17/1 | 16/0 | | | | | | |
| F240 | PMD1 | 31:16 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | 0000 | | | | | |
| | | 15:0 | — | — | — | CVRMD | — | — | — | CTMUMD | — | — | — | — | — | — | — | — | AD1MD | 0000 | | | | |
| F250 | PMD2 | 31:16 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | 0000 | | | | | |
| | | 15:0 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | CMP3MD | CMP2MD | CMP1MD | 0000 | | |
| F260 | PMD3 | 31:16 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | 0000 | | | | | |
| | | 15:0 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | OC5MD | OC4MD | OC3MD | OC2MD | OC1MD | 0000 |
| F270 | PMD4 | 31:16 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | 0000 | | | | | |
| | | 15:0 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | T5MD | T4MD | T3MD | T2MD | T1MD | 0000 |
| F280 | PMD5 | 31:16 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | 0000 | | | | | |
| | | 15:0 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | USB1MD | — | — | — | I2C1MD | I2C1MD |
| F290 | PMD6 | 31:16 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | 0000 | | | | | |
| | | 15:0 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | SPI2MD | SPI1MD | — | — | — | U2MD |
| F290 | PMD6 | 31:16 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | 0000 | | | | | |
| | | 15:0 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | PMPMD |
| | | | | | | | | | | | | | | | | | | | REFOMD | RTCCMD | 0000 | | | |

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See [Section 11.2 “CLR, SET and INV Registers”](#) for more information.

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NOTES:

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27.0 SPECIAL FEATURES

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. However, it is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 32. “Configuration”** (DS60001124) and **Section 33. “Programming and Diagnostics”** (DS60001129), which are available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

PIC32MX1XX/2XX 28/36/44-pin Family devices include the following features intended to maximize application flexibility, reliability and minimize cost through elimination of external components.

- Flexible device configuration
- Joint Test Action Group (JTAG) interface
- In-Circuit Serial Programming™ (ICSP™)

27.1 Configuration Bits

The Configuration bits can be programmed using the following registers to select various device configurations.

- [DEVCFG0: Device Configuration Word 0](#)
- [DEVCFG1: Device Configuration Word 1](#)
- [DEVCFG2: Device Configuration Word 2](#)
- [DEVCFG3: Device Configuration Word 3](#)
- [CFGCON: Configuration Control Register](#)

In addition, the DEVID register ([Register 27-6](#)) provides device and revision information.

27.2 Configuration Registers

TABLE 27-1: DEVCFG: DEVICE CONFIGURATION WORD SUMMARY

| Virtual Address (BFC0_#) | Register Name | Bit Range | Bits | | | | | | | | | | | | | | | All Resets | | |
|--------------------------|---------------|-----------|-----------------------|----------|-------------|-----------------------------|-------|-----------|--------------|------|------|--------------|---------|------|------|------------|------|-------------------------|--------|------------|
| | | | 31/15 | 30/14 | 29/13 | 28/12 | 27/11 | 26/10 | 25/9 | 24/8 | 23/7 | 22/6 | 21/5 | 20/4 | 19/3 | 18/2 | 17/1 | | 16/0 | |
| 0BF0 | DEVCFG3 | 31:16 | FVBUSONIO | FUSBIDIO | IOL1WAY | PMDL1WAY | — | — | — | — | — | — | — | — | — | — | — | xxxx | | |
| | | 15:0 | USERID<15:0> | | | | | | | | | | | | | | | xxxx | | |
| 0BF4 | DEVCFG2 | 31:16 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | FPLLODIV<2:0> | xxxx | |
| | | 15:0 | UPLLEN ⁽¹⁾ | | | UPLLDIV<2:0> ⁽¹⁾ | | | | | | FPLLMUL<2:0> | | | | | | FPLLDIV<2:0> | xxxx | |
| 0BF8 | DEVCFG1 | 31:16 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | WDTPS<4:0> | xxxx | |
| | | 15:0 | FCKSM<1:0> | | FPBDIV<1:0> | | — | OSCI OFNC | POSCMOD<1:0> | | IESO | — | FSOSCEN | — | — | FNOSC<2:0> | | | xxxx | |
| 0BFC | DEVCFG0 | 31:16 | — | — | — | CP | — | — | — | BWP | — | — | — | — | — | — | — | PWP<8:6> ⁽²⁾ | | xxxx |
| | | 15:0 | PWP<5:0> | | | | | | — | — | — | — | — | — | — | — | — | ICESEL<1:0> | JTAGEN | DEBUG<1:0> |

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This bit is only available on PIC32MX2XX devices.

Note 2: PWP<8:7> are only available on devices with 256 KB of Flash.

TABLE 27-2: DEVICE ID, REVISION, AND CONFIGURATION SUMMARY

| Virtual Address (BF80_#) | Register Name | Bit Range | Bits | | | | | | | | | | | | | | | All Resets ⁽¹⁾ | |
|--------------------------|-----------------------|-----------|--------------|-------|--------|---------|-------|--------------|------|------|------|------|------|------|------|--------|------|---------------------------|-------|
| | | | 31/15 | 30/14 | 29/13 | 28/12 | 27/11 | 26/10 | 25/9 | 24/8 | 23/7 | 22/6 | 21/5 | 20/4 | 19/3 | 18/2 | 17/1 | | 16/0 |
| F220 | DEVID | 31:16 | VER<3:0> | | | | | DEVID<27:16> | | | | | | | | | | xxxx ⁽¹⁾ | |
| | | 15:0 | DEVID<15:0> | | | | | | | | | | | | | | | xxxx ⁽¹⁾ | |
| F200 | CFGCON | 31:16 | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | — | 0000 |
| | | 15:0 | — | — | IOLOCK | PMDLOCK | — | — | — | — | — | — | — | — | — | JTAGEN | — | — | TDOEN |
| F230 | SYSKEY ⁽³⁾ | 31:16 | SYSKEY<31:0> | | | | | | | | | | | | | | | 0000 | |
| | | 15:0 | | | | | | | | | | | | | | | | 0000 | |

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: Reset values are dependent on the device variant.

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REGISTER 27-1: DEVCFG0: DEVICE CONFIGURATION WORD 0

| Bit Range | Bit 31/23/15/7 | Bit 30/22/14/6 | Bit 29/21/13/5 | Bit 28/20/12/4 | Bit 27/19/11/3 | Bit 26/18/10/2 | Bit 25/17/9/1 | Bit 24/16/8/0 |
|-----------|----------------|----------------|----------------|----------------------------|----------------|-------------------------|---------------|---------------|
| 31:24 | r-0 | r-1 | r-1 | R/P | r-1 | r-1 | r-1 | R/P |
| | — | — | — | CP | — | — | — | BWP |
| 23:16 | r-1 | r-1 | r-1 | r-1 | r-1 | R/P | R/P | R/P |
| | — | — | — | — | — | PWP<8:6> ⁽³⁾ | | |
| 15:8 | R/P | R/P | R/P | R/P | R/P | R/P | r-1 | r-1 |
| | PWP<5:0> | | | | | | — | — |
| 7:0 | r-1 | r-1 | r-1 | R/P | R/P | R/P | R/P | R/P |
| | — | — | — | ICESEL<1:0> ⁽²⁾ | | JTAGEN ⁽¹⁾ | DEBUG<1:0> | |

| | | |
|-------------------|------------------|------------------------------------|
| Legend: | r = Reserved bit | P = Programmable bit |
| R = Readable bit | W = Writable bit | U = Unimplemented bit, read as '0' |
| -n = Value at POR | '1' = Bit is set | '0' = Bit is cleared |
| | | x = Bit is unknown |

bit 31 **Reserved:** Write '0'

bit 30-29 **Reserved:** Write '1'

bit 28 **CP:** Code-Protect bit

Prevents boot and program Flash memory from being read or modified by an external programming device.

1 = Protection is disabled

0 = Protection is enabled

bit 27-25 **Reserved:** Write '1'

bit 24 **BWP:** Boot Flash Write-Protect bit

Prevents boot Flash memory from being modified during code execution.

1 = Boot Flash is writable

0 = Boot Flash is not writable

bit 23-19 **Reserved:** Write '1'

Note 1: This bit sets the value for the JTAGEN bit in the CFGCON register.

2: The PGEC4/PGED4 pin pair is not available on all devices. Refer to the **"Pin Diagrams"** section for availability.

3: The PWP<8:7> bits are only available on devices with 256 KB Flash.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

REGISTER 27-1: DEVCFG0: DEVICE CONFIGURATION WORD 0 (CONTINUED)

bit 18-10 **PWP<8:0>**: Program Flash Write-Protect bits⁽³⁾

Prevents selected program Flash memory pages from being modified during code execution.

11111111 = Disabled

11111110 = Memory below 0x0400 address is write-protected

11111101 = Memory below 0x0800 address is write-protected

11111100 = Memory below 0x0C00 address is write-protected

11111011 = Memory below 0x1000 (4K) address is write-protected

11111010 = Memory below 0x1400 address is write-protected

11111001 = Memory below 0x1800 address is write-protected

11111000 = Memory below 0x1C00 address is write-protected

11110111 = Memory below 0x2000 (8K) address is write-protected

11110110 = Memory below 0x2400 address is write-protected

11110101 = Memory below 0x2800 address is write-protected

11110100 = Memory below 0x2C00 address is write-protected

11110011 = Memory below 0x3000 address is write-protected

11110010 = Memory below 0x3400 address is write-protected

11110001 = Memory below 0x3800 address is write-protected

11110000 = Memory below 0x3C00 address is write-protected

111101111 = Memory below 0x4000 (16K) address is write-protected

.

.

.

110111111 = Memory below 0x10000 (64K) address is write-protected

.

.

.

101111111 = Memory below 0x20000 (128K) address is write-protected

.

.

.

011111111 = Memory below 0x40000 (256K) address is write-protected

.

.

.

000000000 = All possible memory is write-protected

bit 9-5 **Reserved**: Write '1'

bit 4-3 **ICESEL<1:0>**: In-Circuit Emulator/Debugger Communication Channel Select bits⁽²⁾

11 = PGEC1/PGED1 pair is used

10 = PGEC2/PGED2 pair is used

01 = PGEC3/PGED3 pair is used

00 = PGEC4/PGED4 pair is used⁽²⁾

bit 2 **JTAGEN**: JTAG Enable bit⁽¹⁾

1 = JTAG is enabled

0 = JTAG is disabled

bit 1-0 **DEBUG<1:0>**: Background Debugger Enable bits (forced to '11' if code-protect is enabled)

1x = Debugger is disabled

0x = Debugger is enabled

Note 1: This bit sets the value for the JTAGEN bit in the CFGCON register.

2: The PGEC4/PGED4 pin pair is not available on all devices. Refer to the [“Pin Diagrams”](#) section for availability.

3: The PWP<8:7> bits are only available on devices with 256 KB Flash.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

REGISTER 27-2: DEVCFG1: DEVICE CONFIGURATION WORD 1

| Bit Range | Bit 31/23/15/7 | Bit 30/22/14/6 | Bit 29/21/13/5 | Bit 28/20/12/4 | Bit 27/19/11/3 | Bit 26/18/10/2 | Bit 25/17/9/1 | Bit 24/16/8/0 |
|-----------|----------------|----------------|----------------|----------------|----------------|----------------|----------------|---------------|
| 31:24 | r-1 | r-1 | r-1 | r-1 | r-1 | r-1 | R/P | R/P |
| | — | — | — | — | — | — | FWDTWINSZ<1:0> | |
| 23:16 | R/P | R/P | r-1 | R/P | R/P | R/P | R/P | R/P |
| | FWDTEN | WINDIS | — | WDTPS<4:0> | | | | |
| 15:8 | R/P | R/P | R/P | R/P | r-1 | R/P | R/P | R/P |
| | FCKSM<1:0> | | FPBDIV<1:0> | | — | OSCIOFNC | POSCMOD<1:0> | |
| 7:0 | R/P | r-1 | R/P | r-1 | r-1 | R/P | R/P | R/P |
| | IESO | — | FSOSCEN | — | — | FNOSC<2:0> | | |

Legend:

R = Readable bit

-n = Value at POR

r = Reserved bit

W = Writable bit

'1' = Bit is set

P = Programmable bit

U = Unimplemented bit, read as '0'

'0' = Bit is cleared

x = Bit is unknown

bit 31-26 **Reserved:** Write '1'

bit 25-24 **FWDTWINSZ<1:0>**: Watchdog Timer Window Size bits

11 = Window size is 25%

10 = Window size is 37.5%

01 = Window size is 50%

00 = Window size is 75%

bit 23 **FWDTEN:** Watchdog Timer Enable bit

1 = Watchdog Timer is enabled and cannot be disabled by software

0 = Watchdog Timer is not enabled; it can be enabled in software

bit 22 **WINDIS:** Watchdog Timer Window Enable bit

1 = Watchdog Timer is in non-Window mode

0 = Watchdog Timer is in Window mode

bit 21 **Reserved:** Write '1'

bit 20-16 **WDTPS<4:0>**: Watchdog Timer Postscale Select bits

10100 = 1:1048576

10011 = 1:524288

10010 = 1:262144

10001 = 1:131072

10000 = 1:65536

01111 = 1:32768

01110 = 1:16384

01101 = 1:8192

01100 = 1:4096

01011 = 1:2048

01010 = 1:1024

01001 = 1:512

01000 = 1:256

00111 = 1:128

00110 = 1:64

00101 = 1:32

00100 = 1:16

00011 = 1:8

00010 = 1:4

00001 = 1:2

00000 = 1:1

All other combinations not shown result in operation = 10100

Note 1: Do not disable the Posc (POSCMOD = 11) when using this oscillator source.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

REGISTER 27-2: DEVCFG1: DEVICE CONFIGURATION WORD 1 (CONTINUED)

- bit 15-14 **FCKSM<1:0>**: Clock Switching and Monitor Selection Configuration bits
1x = Clock switching is disabled, Fail-Safe Clock Monitor is disabled
01 = Clock switching is enabled, Fail-Safe Clock Monitor is disabled
00 = Clock switching is enabled, Fail-Safe Clock Monitor is enabled
- bit 13-12 **FPBDIV<1:0>**: Peripheral Bus Clock Divisor Default Value bits
11 = PBCLK is SYSCLK divided by 8
10 = PBCLK is SYSCLK divided by 4
01 = PBCLK is SYSCLK divided by 2
00 = PBCLK is SYSCLK divided by 1
- bit 11 **Reserved**: Write '1'
- bit 10 **OSCIOfNC**: CLKO Enable Configuration bit
1 = CLKO output disabled
0 = CLKO output signal active on the OSCO pin; Primary Oscillator must be disabled or configured for the External Clock mode (EC) for the CLKO to be active (POSCMOD<1:0> = 11 or 00)
- bit 9-8 **POSCMOD<1:0>**: Primary Oscillator Configuration bits
11 = Primary Oscillator is disabled
10 = HS Oscillator mode is selected
01 = XT Oscillator mode is selected
00 = External Clock mode is selected
- bit 7 **IESO**: Internal External Switchover bit
1 = Internal External Switchover mode is enabled (Two-Speed Start-up is enabled)
0 = Internal External Switchover mode is disabled (Two-Speed Start-up is disabled)
- bit 6 **Reserved**: Write '1'
- bit 5 **FSOSCEN**: Secondary Oscillator Enable bit
1 = Enable Secondary Oscillator
0 = Disable Secondary Oscillator
- bit 4-3 **Reserved**: Write '1'
- bit 2-0 **FNOSC<2:0>**: Oscillator Selection bits
111 = Fast RC Oscillator with divide-by-N (FRCDIV)
110 = FRCDIV16 Fast RC Oscillator with fixed divide-by-16 postscaler
101 = Low-Power RC Oscillator (LPRC)
100 = Secondary Oscillator (SOSC)
011 = Primary Oscillator (Posc) with PLL module (XT+PLL, HS+PLL, EC+PLL)
010 = Primary Oscillator (XT, HS, EC)⁽¹⁾
001 = Fast RC Oscillator with divide-by-N with PLL module (FRCDIV+PLL)
000 = Fast RC Oscillator (FRC)

Note 1: Do not disable the Posc (POSCMOD = 11) when using this oscillator source.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

REGISTER 27-3: DEVCFG2: DEVICE CONFIGURATION WORD 2

| Bit Range | Bit 31/23/15/7 | Bit 30/22/14/6 | Bit 29/21/13/5 | Bit 28/20/12/4 | Bit 27/19/11/3 | Bit 26/18/10/2 | Bit 25/17/9/1 | Bit 24/16/8/0 |
|-----------|------------------------------|-----------------------|----------------|----------------|----------------|------------------------------------|---------------|---------------|
| 31:24 | r-1 — | r-1 — | r-1 — | r-1 — | r-1 — | r-1 — | r-1 — | r-1 — |
| 23:16 | r-1 — | r-1 — | r-1 — | r-1 — | r-1 — | R/P FPLLODIV<2:0> | R/P | R/P |
| 15:8 | R/P UPLLEN ⁽¹⁾ | r-1 — | r-1 — | r-1 — | r-1 — | R/P UPLLDIV<2:0> ⁽¹⁾ | R/P | R/P |
| 7:0 | r-1 — | R/P-1 FPLLMUL<2:0> | R/P | R/P-1 | r-1 — | R/P FPLLDIV<2:0> | R/P | R/P |

| | | |
|-------------------|------------------|----------------------------------------------|
| Legend: | r = Reserved bit | P = Programmable bit |
| R = Readable bit | W = Writable bit | U = Unimplemented bit, read as '0' |
| -n = Value at POR | '1' = Bit is set | '0' = Bit is cleared x = Bit is unknown |

bit 31-19 **Reserved:** Write '1'

bit 18-16 **FPLLODIV<2:0>:** Default PLL Output Divisor bits

- 111 = PLL output divided by 256
- 110 = PLL output divided by 64
- 101 = PLL output divided by 32
- 100 = PLL output divided by 16
- 011 = PLL output divided by 8
- 010 = PLL output divided by 4
- 001 = PLL output divided by 2
- 000 = PLL output divided by 1

bit 15 **UPLLEN:** USB PLL Enable bit⁽¹⁾

- 1 = Disable and bypass USB PLL
- 0 = Enable USB PLL

bit 14-11 **Reserved:** Write '1'

bit 10-8 **UPLLDIV<2:0>:** USB PLL Input Divider bits⁽¹⁾

- 111 = 12x divider
- 110 = 10x divider
- 101 = 6x divider
- 100 = 5x divider
- 011 = 4x divider
- 010 = 3x divider
- 010 = 3x divider
- 001 = 2x divider
- 000 = 1x divider

bit 7 **Reserved:** Write '1'

bit 6-4 **FPLLMUL<2:0>:** PLL Multiplier bits

- 111 = 24x multiplier
- 110 = 21x multiplier
- 101 = 20x multiplier
- 100 = 19x multiplier
- 011 = 18x multiplier
- 010 = 17x multiplier
- 001 = 16x multiplier
- 000 = 15x multiplier

bit 3 **Reserved:** Write '1'

Note 1: This bit is only available on PIC32MX2XX devices.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

REGISTER 27-3: DEVCFG2: DEVICE CONFIGURATION WORD 2 (CONTINUED)

bit 2-0 **FPLLIDIV<2:0>**: PLL Input Divider bits

111 = 12x divider

110 = 10x divider

101 = 6x divider

100 = 5x divider

011 = 4x divider

010 = 3x divider

001 = 2x divider

000 = 1x divider

Note 1: This bit is only available on PIC32MX2XX devices.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

REGISTER 27-4: DEVCFG3: DEVICE CONFIGURATION WORD 3

| Bit Range | Bit 31/23/15/7 | Bit 30/22/14/6 | Bit 29/21/13/5 | Bit 28/20/12/4 | Bit 27/19/11/3 | Bit 26/18/10/2 | Bit 25/17/9/1 | Bit 24/16/8/0 |
|-----------|----------------|----------------|----------------|----------------|----------------|----------------|---------------|---------------|
| 31:24 | R/P | R/P | R/P | R/P | r-1 | r-1 | r-1 | r-1 |
| | FVBUSONIO | FUSBIDIO | IOL1WAY | PMDL1WAY | — | — | — | — |
| 23:16 | r-1 | r-1 | r-1 | r-1 | r-1 | r-1 | r-1 | r-1 |
| | — | — | — | — | — | — | — | — |
| 15:8 | R/P | R/P | R/P | R/P | R/P | R/P | R/P | R/P |
| | USERID<15:8> | | | | | | | |
| 7:0 | R/P | R/P | R/P | R/P | R/P | R/P | R/P | R/P |
| | USERID<7:0> | | | | | | | |

| | | |
|-------------------|------------------|----------------------------------------------|
| Legend: | r = Reserved bit | P = Programmable bit |
| R = Readable bit | W = Writable bit | U = Unimplemented bit, read as '0' |
| -n = Value at POR | '1' = Bit is set | '0' = Bit is cleared x = Bit is unknown |

- bit 31 **FVBUSONIO:** USB VBUSON Selection bit
 1 = VBUSON pin is controlled by the USB module
 0 = VBUSON pin is controlled by the port function
- bit 30 **FUSBIDIO:** USB USBID Selection bit
 1 = USBID pin is controlled by the USB module
 0 = USBID pin is controlled by the port function
- bit 29 **IOL1WAY:** Peripheral Pin Select Configuration bit
 1 = Allow only one reconfiguration
 0 = Allow multiple reconfigurations
- bit 28 **PMDL1WAY:** Peripheral Module Disable Configuration bit
 1 = Allow only one reconfiguration
 0 = Allow multiple reconfigurations
- bit 27-16 **Reserved:** Write '1'
- bit 15-0 **USERID<15:0>:** User ID bits
 This is a 16-bit value that is user-defined and is readable via ICSP™ and JTAG.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

REGISTER 27-5: CFGCON: CONFIGURATION CONTROL REGISTER

| Bit Range | Bit 31/23/15/7 | Bit 30/22/14/6 | Bit 29/21/13/5 | Bit 28/20/12/4 | Bit 27/19/11/3 | Bit 26/18/10/2 | Bit 25/17/9/1 | Bit 24/16/8/0 |
|-----------|----------------|----------------|--------------------------------|---------------------------------|-----------------|----------------|---------------|----------------|
| 31:24 | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — |
| 23:16 | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — | U-0 — |
| 15:8 | U-0 — | U-0 — | R/W-0 IOLOCK ⁽¹⁾ | R/W-0 PMDLOCK ⁽¹⁾ | U-0 — | U-0 — | U-0 — | U-0 — |
| 7:0 | U-0 — | U-0 — | U-0 — | U-0 — | R/W-1 JTAGEN | U-0 — | U-1 — | R/W-1 TDOEN |

Legend:

R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'
-n = Value at POR '1' = Bit is set '0' = Bit is cleared x = Bit is unknown

bit 31-14 **Unimplemented:** Read as '0'

bit 13 **IOLOCK:** Peripheral Pin Select Lock bit⁽¹⁾
1 = Peripheral Pin Select is locked. Writes to PPS registers is not allowed.
0 = Peripheral Pin Select is not locked. Writes to PPS registers is allowed.

bit 12 **PMDLOCK:** Peripheral Module Disable bit⁽¹⁾
1 = Peripheral module is locked. Writes to PMD registers is not allowed.
0 = Peripheral module is not locked. Writes to PMD registers is allowed.

bit 11-4 **Unimplemented:** Read as '0'

bit 3 **JTAGEN:** JTAG Port Enable bit
1 = Enable the JTAG port
0 = Disable the JTAG port

bit 2-1 **Unimplemented:** Read as '1'

bit 0 **TDOEN:** TDO Enable for 2-Wire JTAG bit
1 = 2-wire JTAG protocol uses TDO
0 = 2-wire JTAG protocol does not use TDO

Note 1: To change this bit, the unlock sequence must be performed. Refer to **Section 6. "Oscillator"** (DS60001112) in the *"PIC32 Family Reference Manual"* for details.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

REGISTER 27-6: DEVID: DEVICE AND REVISION ID REGISTER

| Bit Range | Bit 31/23/15/7 | Bit 30/22/14/6 | Bit 29/21/13/5 | Bit 28/20/12/4 | Bit 27/19/11/3 | Bit 26/18/10/2 | Bit 25/17/9/1 | Bit 24/16/8/0 |
|-----------|-----------------------------|----------------|----------------|----------------|-----------------------------|----------------|---------------|---------------|
| 31:24 | R | R | R | R | R | R | R | R |
| | VER<3:0> ⁽¹⁾ | | | | DEVID<27:24> ⁽¹⁾ | | | |
| 23:16 | R | R | R | R | R | R | R | R |
| | DEVID<23:16> ⁽¹⁾ | | | | | | | |
| 15:8 | R | R | R | R | R | R | R | R |
| | DEVID<15:8> ⁽¹⁾ | | | | | | | |
| 7:0 | R | R | R | R | R | R | R | R |
| | DEVID<7:0> ⁽¹⁾ | | | | | | | |

Legend:

R = Readable bit
-n = Value at POR

W = Writable bit
'1' = Bit is set

U = Unimplemented bit, read as '0'
'0' = Bit is cleared
x = Bit is unknown

bit 31-28 **VER<3:0>**: Revision Identifier bits⁽¹⁾

bit 27-0 **DEVID<27:0>**: Device ID bits⁽¹⁾

Note 1: See the "PIC32 Flash Programming Specification" (DS60001145) for a list of Revision and Device ID values.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

27.3 On-Chip Voltage Regulator

All PIC32MX1XX/2XX 28/36/44-pin Family devices' core and digital logic are designed to operate at a nominal 1.8V. To simplify system designs, most devices in the PIC32MX1XX/2XX 28/36/44-pin Family family incorporate an on-chip regulator providing the required core logic voltage from VDD.

A low-ESR capacitor (such as tantalum) must be connected to the VCAP pin (see Figure 27-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in Section 30.1 "DC Characteristics".

Note: It is important that the low-ESR capacitor is placed as close as possible to the VCAP pin.

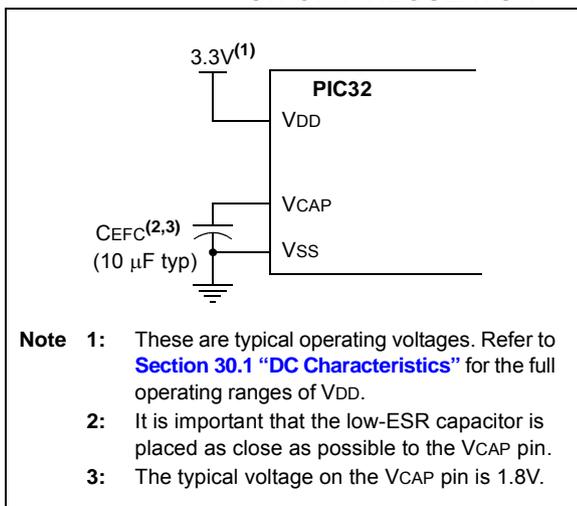
27.3.1 ON-CHIP REGULATOR AND POR

It takes a fixed delay for the on-chip regulator to generate an output. During this time, designated as TPU, code execution is disabled. TPU is applied every time the device resumes operation after any power-down, including Sleep mode.

27.3.2 ON-CHIP REGULATOR AND BOR

PIC32MX1XX/2XX 28/36/44-pin Family devices also have a simple brown-out capability. If the voltage supplied to the regulator is inadequate to maintain a regulated level, the regulator Reset circuitry will generate a Brown-out Reset. This event is captured by the BOR flag bit (RCON<1>). The brown-out voltage levels are specific in Section 30.1 "DC Characteristics".

FIGURE 27-1: CONNECTIONS FOR THE ON-CHIP REGULATOR



27.4 Programming and Diagnostics

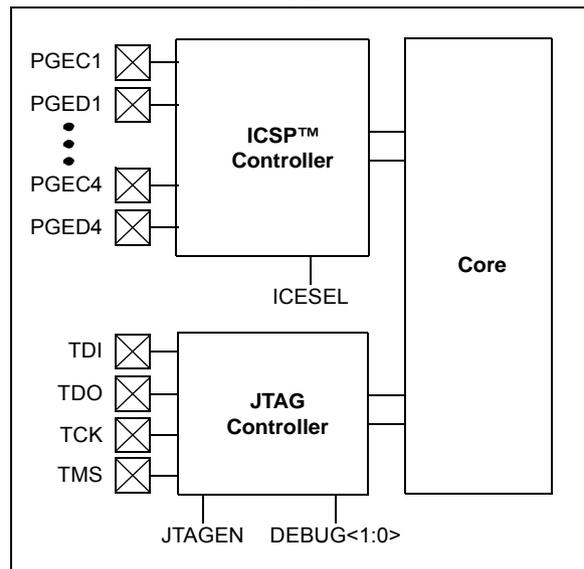
PIC32MX1XX/2XX 28/36/44-pin Family devices provide a complete range of programming and diagnostic features that can increase the flexibility of any application using them. These features allow system designers to include:

- Simplified field programmability using two-wire In-Circuit Serial Programming™ (ICSP™) interfaces
- Debugging using ICSP
- Programming and debugging capabilities using the EJTAG extension of JTAG
- JTAG boundary scan testing for device and board diagnostics

PIC32 devices incorporate two programming and diagnostic modules, and a trace controller, that provide a range of functions to the application developer.

Figure 27-2 illustrates a block diagram of the programming, debugging, and trace ports.

FIGURE 27-2: BLOCK DIAGRAM OF PROGRAMMING, DEBUGGING AND TRACE PORTS



PIC32MX1XX/2XX 28/36/44-PIN FAMILY

28.0 INSTRUCTION SET

The PIC32MX1XX/2XX family instruction set complies with the MIPS32[®] Release 2 instruction set architecture. The PIC32 device family does not support the following features:

- Core extend instructions
- Coprocessor 1 instructions
- Coprocessor 2 instructions

Note: Refer to “MIPS32[®] Architecture for Programmers Volume II: The MIPS32[®] Instruction Set” at www.imgtec.com for more information.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

NOTES:

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

29.0 DEVELOPMENT SUPPORT

The PIC[®] microcontrollers (MCU) and dsPIC[®] digital signal controllers (DSC) are supported with a full range of software and hardware development tools:

- Integrated Development Environment
 - MPLAB[®] X IDE Software
- Compilers/Assemblers/Linkers
 - MPLAB XC Compiler
 - MPASM[™] Assembler
 - MPLINK[™] Object Linker/
MPLIB[™] Object Librarian
 - MPLAB Assembler/Linker/Librarian for
Various Device Families
- Simulators
 - MPLAB X SIM Software Simulator
- Emulators
 - MPLAB REAL ICE[™] In-Circuit Emulator
- In-Circuit Debuggers/Programmers
 - MPLAB ICD 3
 - PICKit[™] 3
- Device Programmers
 - MPLAB PM3 Device Programmer
- Low-Cost Demonstration/Development Boards,
Evaluation Kits and Starter Kits
- Third-party development tools

29.1 MPLAB X Integrated Development Environment Software

The MPLAB X IDE is a single, unified graphical user interface for Microchip and third-party software, and hardware development tool that runs on Windows[®], Linux and Mac OS[®] X. Based on the NetBeans IDE, MPLAB X IDE is an entirely new IDE with a host of free software components and plug-ins for high-performance application development and debugging. Moving between tools and upgrading from software simulators to hardware debugging and programming tools is simple with the seamless user interface.

With complete project management, visual call graphs, a configurable watch window and a feature-rich editor that includes code completion and context menus, MPLAB X IDE is flexible and friendly enough for new users. With the ability to support multiple tools on multiple projects with simultaneous debugging, MPLAB X IDE is also suitable for the needs of experienced users.

Feature-Rich Editor:

- Color syntax highlighting
- Smart code completion makes suggestions and provides hints as you type
- Automatic code formatting based on user-defined rules
- Live parsing

User-Friendly, Customizable Interface:

- Fully customizable interface: toolbars, toolbar buttons, windows, window placement, etc.
- Call graph window

Project-Based Workspaces:

- Multiple projects
- Multiple tools
- Multiple configurations
- Simultaneous debugging sessions

File History and Bug Tracking:

- Local file history feature
- Built-in support for Bugzilla issue tracker

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

29.2 MPLAB XC Compilers

The MPLAB XC Compilers are complete ANSI C compilers for all of Microchip's 8, 16, and 32-bit MCU and DSC devices. These compilers provide powerful integration capabilities, superior code optimization and ease of use. MPLAB XC Compilers run on Windows, Linux or MAC OS X.

For easy source level debugging, the compilers provide debug information that is optimized to the MPLAB X IDE.

The free MPLAB XC Compiler editions support all devices and commands, with no time or memory restrictions, and offer sufficient code optimization for most applications.

MPLAB XC Compilers include an assembler, linker and utilities. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. MPLAB XC Compiler uses the assembler to produce its object file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

29.3 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code, and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB X IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multipurpose source files
- Directives that allow complete control over the assembly process

29.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/librarian features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

29.5 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC DSC devices. MPLAB XC Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

29.6 MPLAB X SIM Software Simulator

The MPLAB X SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB X SIM Software Simulator fully supports symbolic debugging using the MPLAB XC Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

29.7 MPLAB REAL ICE In-Circuit Emulator System

The MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs all 8, 16 and 32-bit MCU, and DSC devices with the easy-to-use, powerful graphical user interface of the MPLAB X IDE.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ-11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB X IDE. MPLAB REAL ICE offers significant advantages over competitive emulators including full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, logic probes, a ruggedized probe interface and long (up to three meters) interconnection cables.

29.8 MPLAB ICD 3 In-Circuit Debugger System

The MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost-effective, high-speed hardware debugger/programmer for Microchip Flash DSC and MCU devices. It debugs and programs PIC Flash microcontrollers and dsPIC DSCs with the powerful, yet easy-to-use graphical user interface of the MPLAB IDE.

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

29.9 PICkit 3 In-Circuit Debugger/Programmer

The MPLAB PICkit 3 allows debugging and programming of PIC and dsPIC Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB IDE. The MPLAB PICkit 3 is connected to the design engineer's PC using a full-speed USB interface and can be connected to the target via a Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the Reset line to implement in-circuit debugging and In-Circuit Serial Programming™ (ICSP™).

29.10 MPLAB PM3 Device Programmer

The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at VDDMIN and VDDMAX for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages, and a modular, detachable socket assembly to support various package types. The ICSP cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PIC devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices, and incorporates an MMC card for file storage and data applications.

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29.11 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

29.12 Third-Party Development Tools

Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent® and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika®

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30.0 ELECTRICAL CHARACTERISTICS

This section provides an overview of the PIC32MX1XX/2XX 28/36/44-pin Family electrical characteristics for devices that operate at 40 MHz. Refer to [Section 31.0 “50 MHz Electrical Characteristics”](#) for additional specifications for operations at higher frequency. Additional information will be provided in future revisions of this document as it becomes available.

Absolute maximum ratings for the PIC32MX1XX/2XX 28/36/44-pin Family devices are listed below. Exposure to these maximum rating conditions for extended periods may affect device reliability. Functional operation of the device at these or any other conditions, above the parameters indicated in the operation listings of this specification, is not implied.

Absolute Maximum Ratings

(See Note 1)

| | |
|-------------------------------------------------------------------------------------------|---------------------------|
| Ambient temperature under bias | -40°C to +105°C |
| Storage temperature | -65°C to +150°C |
| Voltage on VDD with respect to VSS | -0.3V to +4.0V |
| Voltage on any pin that is not 5V tolerant, with respect to VSS (Note 3)..... | -0.3V to (VDD + 0.3V) |
| Voltage on any 5V tolerant pin with respect to VSS when VDD ≥ 2.3V (Note 3)..... | -0.3V to +5.5V |
| Voltage on any 5V tolerant pin with respect to VSS when VDD < 2.3V (Note 3)..... | -0.3V to +3.6V |
| Voltage on D+ or D- pin with respect to VUSB3V3 | -0.3V to (VUSB3V3 + 0.3V) |
| Voltage on VBUS with respect to VSS | -0.3V to +5.5V |
| Maximum current out of VSS pin(s) | 300 mA |
| Maximum current into VDD pin(s) (Note 2)..... | 300 mA |
| Maximum output current sunk by any I/O pin..... | 15 mA |
| Maximum output current sourced by any I/O pin | 15 mA |
| Maximum current sunk by all ports | 200 mA |
| Maximum current sourced by all ports (Note 2)..... | 200 mA |

Note 1: Stresses above those listed under “**Absolute Maximum Ratings**” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions, above those indicated in the operation listings of this specification, is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see [Table 30-2](#)).

3: See the “[Pin Diagrams](#)” section for the 5V tolerant pins.

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30.1 DC Characteristics

TABLE 30-1: OPERATING MIPS VS. VOLTAGE

| Characteristic | VDD Range (in Volts) ⁽¹⁾ | Temp. Range (in °C) | Max. Frequency |
|----------------|----------------------------------------|------------------------|------------------------------------|
| | | | PIC32MX1XX/2XX 28/36/44-pin Family |
| DC5 | 2.3-3.6V | -40°C to +85°C | 40 MHz |
| DC5b | 2.3-3.6V | -40°C to +105°C | 40 MHz |

Note 1: Overall functional device operation at $V_{BORMIN} < V_{DD} < V_{DDMIN}$ is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below V_{DDMIN} . Refer to parameter BO10 in [Table 30-11](#) for BOR values.

TABLE 30-2: THERMAL OPERATING CONDITIONS

| Rating | Symbol | Min. | Typical | Max. | Unit |
|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------|---------------------------|---------|------|------|
| Industrial Temperature Devices | | | | | |
| Operating Junction Temperature Range | TJ | -40 | — | +125 | °C |
| Operating Ambient Temperature Range | TA | -40 | — | +85 | °C |
| V-temp Temperature Devices | | | | | |
| Operating Junction Temperature Range | TJ | -40 | — | +140 | °C |
| Operating Ambient Temperature Range | TA | -40 | — | +105 | °C |
| Power Dissipation: Internal Chip Power Dissipation: $P_{INT} = V_{DD} \times (I_{DD} - S \times I_{OH})$ I/O Pin Power Dissipation: $I/O = S \times ((V_{DD} - V_{OH}) \times I_{OH}) + S \times (V_{OL} \times I_{OL})$ | PD | PINT + PI/O | | | W |
| Maximum Allowed Power Dissipation | PDMAX | $(T_J - T_A)/\theta_{JA}$ | | | W |

TABLE 30-3: THERMAL PACKAGING CHARACTERISTICS

| Characteristics | Symbol | Typical | Max. | Unit | Notes |
|------------------------------------------|---------------|---------|------|------|-------|
| Package Thermal Resistance, 28-pin SSOP | θ_{JA} | 71 | — | °C/W | 1 |
| Package Thermal Resistance, 28-pin SOIC | θ_{JA} | 50 | — | °C/W | 1 |
| Package Thermal Resistance, 28-pin SPDIP | θ_{JA} | 42 | — | °C/W | 1 |
| Package Thermal Resistance, 28-pin QFN | θ_{JA} | 35 | — | °C/W | 1 |
| Package Thermal Resistance, 36-pin VTLA | θ_{JA} | 31 | — | °C/W | 1 |
| Package Thermal Resistance, 44-pin QFN | θ_{JA} | 32 | — | °C/W | 1 |
| Package Thermal Resistance, 44-pin TQFP | θ_{JA} | 45 | — | °C/W | 1 |
| Package Thermal Resistance, 44-pin VTLA | θ_{JA} | 30 | — | °C/W | 1 |

Note 1: Junction to ambient thermal resistance, Theta-JA (θ_{JA}) numbers are achieved by package simulations.

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TABLE 30-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

| DC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp | | | | |
|--------------------------|--------|----------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------|------|-------|-------|------------|
| Param. No. | Symbol | Characteristics | Min. | Typ. | Max. | Units | Conditions |
| Operating Voltage | | | | | | | |
| DC10 | VDD | Supply Voltage (Note 2) | 2.3 | — | 3.6 | V | — |
| DC12 | VDR | RAM Data Retention Voltage (Note 1) | 1.75 | — | — | V | — |
| DC16 | VPOR | VDD Start Voltage to Ensure Internal Power-on Reset Signal | 1.75 | — | 2.1 | V | — |
| DC17 | SVDD | VDD Rise Rate to Ensure Internal Power-on Reset Signal | 0.00005 | — | 0.115 | V/μs | — |

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

- 2:** Overall functional device operation at VBORMIN < VDD < VDDMIN is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below VDDMIN. Refer to parameter BO10 in [Table 30-11](#) for BOR values.

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TABLE 30-5: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

| DC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp | |
|------------------------------------------------|------------------------|------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------------|
| Parameter No. | Typical ⁽³⁾ | Max. | Units | Conditions |
| Operating Current (IDD) (Notes 1, 2, 5) | | | | |
| DC20 | 2 | 3 | mA | 4 MHz (Note 4) |
| DC21 | 7 | 10.5 | mA | 10 MHz |
| DC22 | 10 | 15 | mA | 20 MHz (Note 4) |
| DC23 | 15 | 23 | mA | 30 MHz (Note 4) |
| DC24 | 20 | 30 | mA | 40 MHz |
| DC25 | 100 | 150 | µA | +25°C, 3.3V LPRC (31 kHz) (Note 4) |

- Note 1:** A device's IDD supply current is mainly a function of the operating voltage and frequency. Other factors, such as PBCLK (Peripheral Bus Clock) frequency, number of peripheral modules enabled, internal code execution pattern, execution from Program Flash memory vs. SRAM, I/O pin loading and switching rate, oscillator type, as well as temperature, can have an impact on the current consumption.
- 2:** The test conditions for IDD measurements are as follows:
- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
 - OSC2/CLKO is configured as an I/O input pin
 - USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
 - CPU, Program Flash, and SRAM data memory are operational, SRAM data memory Wait states = 1
 - No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is cleared
 - WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
 - All I/O pins are configured as inputs and pulled to Vss
 - MCLR = VDD
 - CPU executing `while(1)` statement from Flash
 - RTCC and JTAG are disabled
- 3:** Data in "Typical" column is at 3.3V, 25°C at specified operating frequency unless otherwise stated. Parameters are for design guidance only and are not tested.
- 4:** This parameter is characterized, but not tested in manufacturing.
- 5:** IPD electrical characteristics for devices with 256 KB Flash are only provided as Preliminary information.

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TABLE 30-6: DC CHARACTERISTICS: IDLE CURRENT (I_{IDLE})

| DC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ T _A ≤ +85°C for Industrial -40°C ≤ T _A ≤ +105°C for V-temp | | | |
|--------------------------------------------------------------------------------------|------------------------|------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------|------|---------------------------|
| Parameter No. | Typical ⁽²⁾ | Max. | Units | Conditions | | |
| Idle Current (I_{IDLE}): Core Off, Clock on Base Current (Notes 1, 4) | | | | | | |
| DC30a | 1 | 1.5 | mA | 4 MHz (Note 3) | | |
| DC31a | 2 | 3 | mA | 10 MHz | | |
| DC32a | 4 | 6 | mA | 20 MHz (Note 3) | | |
| DC33a | 5.5 | 8 | mA | 30 MHz (Note 3) | | |
| DC34a | 7.5 | 11 | mA | 40 MHz | | |
| DC37a | 100 | — | μA | -40°C | 3.3V | LPRC (31 kHz) (Note 3) |
| DC37b | 250 | — | μA | +25°C | | |
| DC37c | 380 | — | μA | +85°C | | |

Note 1: The test conditions for I_{IDLE} current measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
 - OSC2/CLKO is configured as an I/O input pin
 - USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
 - CPU is in Idle mode (CPU core Halted), and SRAM data memory Wait states = 1
 - No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is cleared
 - WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
 - All I/O pins are configured as inputs and pulled to V_{SS}
 - MCLR = V_{DD}
 - RTCC and JTAG are disabled
- 2:** Data in the “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.
- 3:** This parameter is characterized, but not tested in manufacturing.
- 4:** I_{IDLE} electrical characteristics for devices with 256 KB Flash are only provided as Preliminary information.

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TABLE 30-7: DC CHARACTERISTICS: POWER-DOWN CURRENT (IPD)

| DC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) | | |
|----------------------------------------------|------------------------|------|-------------------------------------------------------------------------------------------|------------|----------------------------------------------------------------------|
| | | | Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp | | |
| Param. No. | Typical ⁽²⁾ | Max. | Units | Conditions | |
| Power-Down Current (IPD) (Notes 1, 5) | | | | | |
| DC40k | 44 | 70 | μA | -40°C | Base Power-Down Current |
| DC40l | 44 | 70 | μA | +25°C | |
| DC40n | 168 | 259 | μA | +85°C | |
| DC40m | 335 | 536 | μA | +105°C | |
| Module Differential Current | | | | | |
| DC41e | 5 | 20 | μA | 3.6V | Watchdog Timer Current: ΔI _{WDT} (Note 3) |
| DC42e | 23 | 50 | μA | 3.6V | RTCC + Timer1 w/32 kHz Crystal: ΔI _{RTCC} (Note 3) |
| DC43d | 1000 | 1100 | μA | 3.6V | ADC: ΔI _{ADC} (Notes 3,4) |

- Note 1:** The test conditions for IPD current measurements are as follows:
- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
 - OSC2/CLKO is configured as an I/O input pin
 - USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
 - CPU is in Sleep mode, and SRAM data memory Wait states = 1
 - No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is set
 - WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
 - All I/O pins are configured as inputs and pulled to V_{SS}
 - $\overline{\text{MCLR}} = \text{V}_{\text{DD}}$
 - RTCC and JTAG are disabled
- 2:** Data in the “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.
- 3:** The Δ current is the additional current consumed when the module is enabled. This current should be added to the base IPD current.
- 4:** Test conditions for ADC module differential current are as follows: Internal ADC RC oscillator enabled.
- 5:** IPD electrical characteristics for devices with 256 KB Flash are only provided as Preliminary information.

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TABLE 30-8: DC CHARACTERISTICS: I/O PIN INPUT SPECIFICATIONS

| DC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp | | | | |
|--------------------|-----------------|------------------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------|----------------------|-------|---------------------------------------------------------------------------------|
| Param. No. | Symbol | Characteristics | Min. | Typical ⁽¹⁾ | Max. | Units | Conditions |
| DI10 | V _{IL} | Input Low Voltage | | | | | |
| | | I/O Pins with PMP | V _{SS} | — | 0.15 V _{DD} | V | |
| | | I/O Pins | V _{SS} | — | 0.2 V _{DD} | V | |
| DI18 | | SDAx, SCLx | V _{SS} | — | 0.3 V _{DD} | V | SMBus disabled (Note 4) |
| DI19 | | SDAx, SCLx | V _{SS} | — | 0.8 | V | SMBus enabled (Note 4) |
| DI20 | V _{IH} | Input High Voltage | | | | | |
| | | I/O Pins not 5V-tolerant ⁽⁵⁾ | 0.65 V _{DD} | — | V _{DD} | V | (Note 4,6) |
| | | I/O Pins 5V-tolerant with PMP ⁽⁵⁾ | 0.25 V _{DD} + 0.8V | — | 5.5 | V | (Note 4,6) |
| DI28 | | I/O Pins 5V-tolerant ⁽⁵⁾ | 0.65 V _{DD} | — | 5.5 | V | |
| | | SDAx, SCLx | 0.65 V _{DD} | — | 5.5 | V | SMBus disabled (Note 4,6) |
| DI29 | | SDAx, SCLx | 2.1 | — | 5.5 | V | SMBus enabled, 2.3V ≤ V _{PIN} ≤ 5.5 (Note 4,6) |
| DI30 | ICNPU | Change Notification Pull-up Current | — | — | -50 | μA | V _{DD} = 3.3V, V _{PIN} = V _{SS} (Note 3,6) |
| DI31 | ICNPD | Change Notification Pull-down Current⁽⁴⁾ | — | — | -50 | μA | V _{DD} = 3.3V, V _{PIN} = V _{DD} |
| DI50 | I _{IL} | Input Leakage Current (Note 3) | | | | | |
| | | I/O Ports | — | — | ±1 | μA | V _{SS} ≤ V _{PIN} ≤ V _{DD} , Pin at high-impedance |
| | | Analog Input Pins | — | — | ±1 | μA | V _{SS} ≤ V _{PIN} ≤ V _{DD} , Pin at high-impedance |
| | | $\overline{\text{MCLR}}^{(2)}$ | — | — | ±1 | μA | V _{SS} ≤ V _{PIN} ≤ V _{DD} |
| | | OSC1 | — | — | ±1 | μA | V _{SS} ≤ V _{PIN} ≤ V _{DD} , XT and HS modes |

Note 1: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

- 2:** The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.
- 3:** Negative current is defined as current sourced by the pin.
- 4:** This parameter is characterized, but not tested in manufacturing.
- 5:** See the “Pin Diagrams” section for the 5V-tolerant pins.
- 6:** The V_{IH} specifications are only in relation to externally applied inputs, and not with respect to the user-selectable internal pull-ups. External open drain input signals utilizing the internal pull-ups of the PIC32 device are guaranteed to be recognized only as a logic “high” internally to the PIC32 device, provided that the external load does not exceed the minimum value of ICNPU. For External “input” logic inputs that require a pull-up source, to guarantee the minimum V_{IH} of those components, it is recommended to use an external pull-up resistor rather than the internal pull-ups of the PIC32 device.

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TABLE 30-9: DC CHARACTERISTICS: I/O PIN INPUT INJECTION CURRENT SPECIFICATIONS

| DC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp | | | | |
|--------------------|---------------------------|------------------------------------------------------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------------------|-----------------------|-------|------------------------------------------------------------------------------------------------------------------------------------|
| Param. No. | Symbol | Characteristics | Min. | Typ. ⁽¹⁾ | Max. | Units | Conditions |
| DI60a | I _{ICL} | Input Low Injection Current | 0 | — | -5 ^(2,5) | mA | This parameter applies to all pins, with the exception of the power pins. |
| DI60b | I _{ICH} | Input High Injection Current | 0 | — | +5 ^(3,4,5) | mA | This parameter applies to all pins, with the exception of all 5V tolerant pins, and the SOSCI, SOSCO, OSC1, D+, and D- pins. |
| DI60c | Σ I _{ICT} | Total Input Injection Current (sum of all I/O and Control pins) | -20 ⁽⁶⁾ | — | +20 ⁽⁶⁾ | mA | Absolute instantaneous sum of all \pm input injection currents from all I/O pins ($ I_{ICL} + I_{ICH} \leq \Sigma I_{ICT}$) |

- Note 1:** Data in “Typical” column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.
- 2:** V_{IL} source < (V_{SS} - 0.3). Characterized but not tested.
- 3:** V_{IH} source > (V_{DD} + 0.3) for non-5V tolerant pins only.
- 4:** Digital 5V tolerant pins do not have an internal high side diode to V_{DD}, and therefore, cannot tolerate any “positive” input injection current.
- 5:** Injection currents > |0| can affect the ADC results by approximately 4 to 6 counts (i.e., V_{IH} Source > (V_{DD} + 0.3) or V_{IL} source < (V_{SS} - 0.3)).
- 6:** Any number and/or combination of I/O pins not excluded under I_{ICL} or I_{ICH} conditions are permitted provided the “absolute instantaneous” sum of the input injection currents from all pins do not exceed the specified limit. If **Note 2**, I_{ICL} = ((V_{SS} - 0.3) - V_{IL} source) / R_S). If **Note 3**, I_{ICH} = ((I_{ICH} source - (V_{DD} + 0.3)) / R_S). R_S = Resistance between input source voltage and device pin. If (V_{SS} - 0.3) ≤ V_{SOURCE} ≤ (V_{DD} + 0.3), injection current = 0.

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TABLE 30-10: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

| DC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp | | | | |
|--------------------|-----------------|----------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------|------|-------|--------------------------------------------------|
| Param. | Symbol | Characteristic | Min. | Typ. | Max. | Units | Conditions |
| DO10 | V _{OL} | Output Low Voltage I/O Pins | — | — | 0.4 | V | I _{OL} ≤ 10 mA, V _{DD} = 3.3V |
| DO20 | V _{OH} | Output High Voltage I/O Pins | 1.5 ⁽¹⁾ | — | — | V | I _{OH} ≥ -14 mA, V _{DD} = 3.3V |
| | | | 2.0 ⁽¹⁾ | — | — | | I _{OH} ≥ -12 mA, V _{DD} = 3.3V |
| | | | 2.4 | — | — | | I _{OH} ≥ -10 mA, V _{DD} = 3.3V |
| | | | 3.0 ⁽¹⁾ | — | — | | I _{OH} ≥ -7 mA, V _{DD} = 3.3V |

Note 1: Parameters are characterized, but not tested.

TABLE 30-11: ELECTRICAL CHARACTERISTICS: BOR

| DC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp | | | | |
|--------------------|------------------|--------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------|------|-------|------------|
| Param. No. | Symbol | Characteristics | Min. ⁽¹⁾ | Typical | Max. | Units | Conditions |
| BO10 | V _{BOR} | BOR Event on V _{DD} transition high-to-low ⁽²⁾ | 2.0 | — | 2.3 | V | — |

Note 1: Parameters are for design guidance only and are not tested in manufacturing.

2: Overall functional device operation at V_{BORMIN} < V_{DD} < V_{DDMIN} is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below V_{DDMIN}.

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TABLE 30-12: DC CHARACTERISTICS: PROGRAM MEMORY

| DC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp | | | | |
|-------------------------------------------|--------|-----------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------|------|------------|-----------------------------------------------|
| Param. No. | Symbol | Characteristics | Min. | Typical ⁽¹⁾ | Max. | Units | Conditions |
| Program Flash Memory⁽³⁾ | | | | | | | |
| D130 | EP | Cell Endurance | 20,000 | — | — | E/W | — |
| D131 | VPR | VDD for Read | 2.3 | — | 3.6 | V | — |
| D132 | VPEW | VDD for Erase or Write | 2.3 | — | 3.6 | V | — |
| D134 | TRETD | Characteristic Retention | 20 | — | — | Year | Provided no other specifications are violated |
| D135 | IDDP | Supply Current during Programming | — | 10 | — | mA | — |
| D136 | TWW | Word Write Cycle Time | — | 411 | — | FRC Cycles | See Note 4 |
| | TRW | Row Write Cycle Time | — | 6675 | — | | See Note 2,4 |
| | TPE | Page Erase Cycle Time | — | 20011 | — | | See Note 4 |
| | TCE | Chip Erase Cycle Time | — | 80180 | — | | See Note 4 |

- Note 1:** Data in “Typical” column is at 3.3V, 25°C unless otherwise stated.
- 2:** The minimum SYSCLK for row programming is 4 MHz. Care should be taken to minimize bus activities during row programming, such as suspending any memory-to-memory DMA operations. If heavy bus loads are expected, selecting Bus Matrix Arbitration mode 2 (rotating priority) may be necessary. The default Arbitration mode is mode 1 (CPU has lowest priority).
- 3:** Refer to the “PIC32 Flash Programming Specification” (DS60001145) for operating conditions during programming and erase cycles.
- 4:** This parameter depends on FRC accuracy (See [Table 30-19](#)) and FRC tuning values (See [Register 8-2](#)).

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TABLE 30-13: COMPARATOR SPECIFICATIONS

| DC CHARACTERISTICS | | | Standard Operating Conditions (see Note 4): 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp | | | | |
|--------------------|--------------------|--------------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------|-----------------|-------|-----------------------------------------------------------------------------------------------|
| Param. No. | Symbol | Characteristics | Min. | Typical | Max. | Units | Comments |
| D300 | VI _{OFF} | Input Offset Voltage | — | ±7.5 | ±25 | mV | AV _{DD} = V _{DD} , AV _{SS} = V _{SS} |
| D301 | VI _{CM} | Input Common Mode Voltage | 0 | — | V _{DD} | V | AV _{DD} = V _{DD} , AV _{SS} = V _{SS} (Note 2) |
| D302 | CMRR | Common Mode Rejection Ratio | 55 | — | — | dB | Max VI _{CM} = (V _{DD} - 1)V (Note 2) |
| D303A | T _{RESP} | Large Signal Response Time | — | 150 | 400 | ns | AV _{DD} = V _{DD} , AV _{SS} = V _{SS} (Note 1,2) |
| D303B | T _{SRESP} | Small Signal Response Time | — | 1 | — | μs | This is defined as an input step of 50 mV with 15 mV of overdrive (Note 2) |
| D304 | ON2OV | Comparator Enabled to Output Valid | — | — | 10 | μs | Comparator module is configured before setting the comparator ON bit (Note 2) |
| D305 | IV _{REF} | Internal Voltage Reference | 1.14 | 1.2 | 1.26 | V | — |
| D312 | T _{SET} | Internal Comparator Voltage DRC Reference Setting time | — | — | 10 | μs | (Note 3) |

- Note 1:** Response time measured with one comparator input at $(V_{DD} - 1.5)/2$, while the other input transitions from V_{SS} to V_{DD}.
- 2:** These parameters are characterized but not tested.
- 3:** Settling time measured while CVRR = 1 and CVR<3:0> transitions from '0000' to '1111'. This parameter is characterized, but not tested in manufacturing.
- 4:** The Comparator module is functional at $V_{BORMIN} < V_{DD} < V_{DDMIN}$, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

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TABLE 30-14: COMPARATOR VOLTAGE REFERENCE SPECIFICATIONS

| DC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp | | | | |
|--------------------|---------|-------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------|------|-----------------|-------|-----------------------------------------------------------|
| Param. No. | Symbol | Characteristics | Min. | Typ. | Max. | Units | Comments |
| D312 | TSET | Internal 4-bit DAC Comparator Reference Settling time | — | — | 10 | μs | See Note 1 |
| D313 | DACREFH | CVREF Input Voltage Reference Range | AVSS | — | AVDD | V | CVRSRC with CVRSS = 0 |
| | | | VREF- | — | VREF+ | V | CVRSRC with CVRSS = 1 |
| D314 | DVREF | CVREF Programmable Output Range | 0 | — | 0.625 x DACREFH | V | 0 to 0.625 DACREFH with DACREFH/24 step size |
| | | | 0.25 x DACREFH | — | 0.719 x DACREFH | V | 0.25 x DACREFH to 0.719 DACREFH with DACREFH/32 step size |
| D315 | DACRES | Resolution | — | — | DACREFH/24 | — | CVRCON<CVRR> = 1 |
| | | | — | — | DACREFH/32 | — | CVRCON<CVRR> = 0 |
| D316 | DACACC | Absolute Accuracy ⁽²⁾ | — | — | 1/4 | LSB | DACREFH/24, CVRCON<CVRR> = 1 |
| | | | — | — | 1/2 | LSB | DACREFH/32, CVRCON<CVRR> = 0 |

Note 1: Settling time was measured while CVRR = 1 and CVR<3:0> transitions from '0000' to '1111'. This parameter is characterized, but is not tested in manufacturing.

2: These parameters are characterized but not tested.

TABLE 30-15: INTERNAL VOLTAGE REGULATOR SPECIFICATIONS

| DC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp | | | | |
|--------------------|--------|---------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------|------|-------|-------------------------------------------------------------------------------------------|
| Param. No. | Symbol | Characteristics | Min. | Typical | Max. | Units | Comments |
| D321 | CEFC | External Filter Capacitor Value | 8 | 10 | — | μF | Capacitor must be low series resistance (1 ohm). Typical voltage on the VCAP pin is 1.8V. |

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30.2 AC Characteristics and Timing Parameters

The information contained in this section defines PIC32MX1XX/2XX 28/36/44-pin Family AC characteristics and timing parameters.

FIGURE 30-1: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS

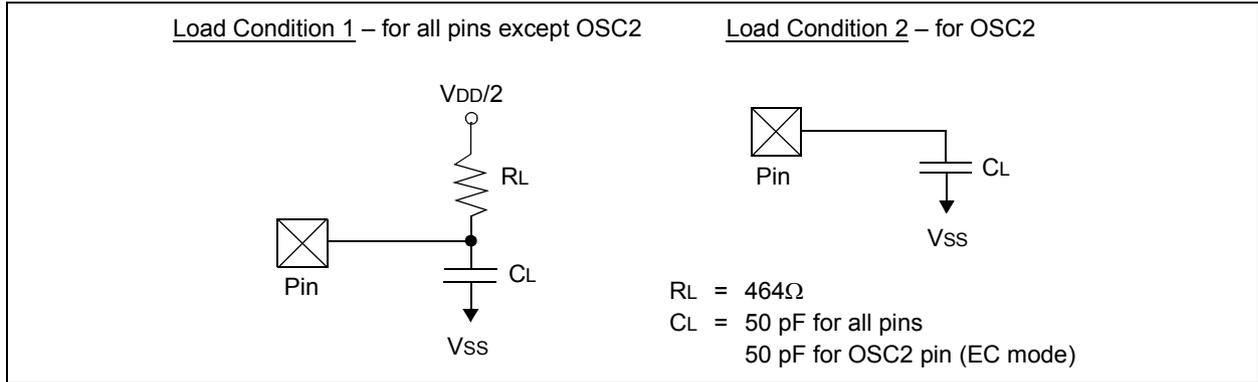
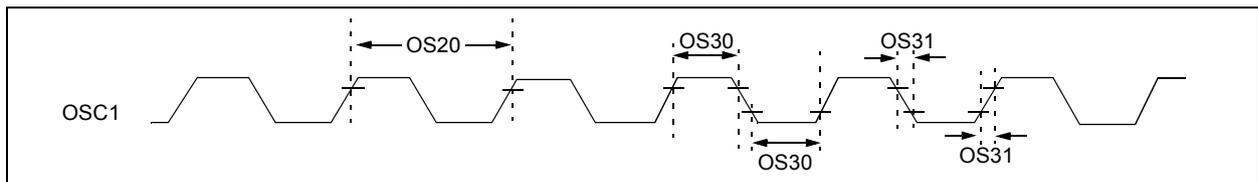


TABLE 30-16: CAPACITIVE LOADING REQUIREMENTS ON OUTPUT PINS

| AC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$ for Industrial $-40^\circ\text{C} \leq T_A \leq +105^\circ\text{C}$ for V-temp | | | | |
|--------------------|-----------------|-----------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------|------|-------|--------------------------|
| Param. No. | Symbol | Characteristics | Min. | Typical ⁽¹⁾ | Max. | Units | Conditions |
| DO56 | C _{IO} | All I/O pins and OSC2 | — | — | 50 | pF | EC mode |
| DO58 | C _B | SCLx, SDAx | — | — | 400 | pF | In I ² C mode |

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

FIGURE 30-2: EXTERNAL CLOCK TIMING



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TABLE 30-17: EXTERNAL CLOCK TIMING REQUIREMENTS

| AC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp | | | | |
|--------------------|---------------|------------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------|-----------------------|------------|-----------------------------------------------------------------------|
| Param. No. | Symbol | Characteristics | Min. | Typical ⁽¹⁾ | Max. | Units | Conditions |
| OS10 | Fosc | External CLKI Frequency (External clocks allowed only in EC and ECPLL modes) | DC 4 | — — | 40 40 | MHz MHz | EC (Note 4) ECPLL (Note 3) |
| OS11 | | Oscillator Crystal Frequency | 3 | — | 10 | MHz | XT (Note 4) |
| OS12 | | | 4 | — | 10 | MHz | XTPLL (Notes 3,4) |
| OS13 | | | 10 | — | 25 | MHz | HS (Note 5) |
| OS14 | | | 10 | — | 25 | MHz | HSPLL (Notes 3,4) |
| OS15 | | | 32 | 32.768 | 100 | kHz | Sosc (Note 4) |
| OS20 | Tosc | $T_{osc} = 1/F_{osc} = T_{cy}$ (Note 2) | — | — | — | — | See parameter OS10 for Fosc value |
| OS30 | TosL, TosH | External Clock In (OSC1) High or Low Time | $0.45 \times T_{osc}$ | — | — | ns | EC (Note 4) |
| OS31 | TosR, TosF | External Clock In (OSC1) Rise or Fall Time | — | — | $0.05 \times T_{osc}$ | ns | EC (Note 4) |
| OS40 | TOST | Oscillator Start-up Timer Period (Only applies to HS, HSPLL, XT, XTPLL and Sosc Clock Oscillator modes) | — | 1024 | — | Tosc | (Note 4) |
| OS41 | TFSCM | Primary Clock Fail Safe Time-out Period | — | 2 | — | ms | (Note 4) |
| OS42 | GM | External Oscillator Transconductance (Primary Oscillator only) | — | 12 | — | mA/V | $V_{DD} = 3.3V$, $T_A = +25^{\circ}\text{C}$ (Note 4) |

Note 1: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are characterized but are not tested.

2: Instruction cycle period (Tcy) equals the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at “min.” values with an external clock applied to the OSC1/CLKI pin.

3: PLL input requirements: $4 \text{ MHz} \leq F_{PLLIN} \leq 5 \text{ MHz}$ (use PLL prescaler to reduce Fosc). This parameter is characterized, but tested at 10 MHz only at manufacturing.

4: This parameter is characterized, but not tested in manufacturing.

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TABLE 30-18: PLL CLOCK TIMING SPECIFICATIONS

| AC CHARACTERISTICS | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp | | | | | |
|--------------------|--------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------|---------|-------|-------|-----------------------------------|
| Param. No. | Symbol | Characteristics ⁽¹⁾ | Min. | Typical | Max. | Units | Conditions |
| OS50 | FPLLI | PLL Voltage Controlled Oscillator (VCO) Input Frequency Range | 3.92 | — | 5 | MHz | ECPLL, HSPLL, XTPLL, FRCPLL modes |
| OS51 | FSYS | On-Chip VCO System Frequency | 60 | — | 120 | MHz | — |
| OS52 | TLOCK | PLL Start-up Time (Lock Time) | — | — | 2 | ms | — |
| OS53 | DCLK | CLKO Stability ⁽²⁾ (Period Jitter or Cumulative) | -0.25 | — | +0.25 | % | Measured over 100 ms period |

Note 1: These parameters are characterized, but not tested in manufacturing.

Note 2: This jitter specification is based on clock-cycle by clock-cycle measurements. To get the effective jitter for individual time-bases on communication clocks, use the following formula:

$$EffectiveJitter = \frac{D_{CLK}}{\sqrt{\frac{SYSCLK}{CommunicationClock}}}$$

For example, if SYSCLK = 40 MHz and SPI bit rate = 20 MHz, the effective jitter is as follows:

$$EffectiveJitter = \frac{D_{CLK}}{\sqrt{\frac{40}{20}}} = \frac{D_{CLK}}{1.41}$$

TABLE 30-19: INTERNAL FRC ACCURACY

| AC CHARACTERISTICS | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp | | | | |
|-------------------------------------------------------|-----------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------|------|-------|------------|
| Param. No. | Characteristics | Min. | Typical | Max. | Units | Conditions |
| Internal FRC Accuracy @ 8.00 MHz⁽¹⁾ | | | | | | |
| F20b | FRC | -0.9 | — | +0.9 | % | — |

Note 1: Frequency calibrated at 25°C and 3.3V. The TUN bits can be used to compensate for temperature drift.

TABLE 30-20: INTERNAL LPRC ACCURACY

| AC CHARACTERISTICS | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp | | | | |
|---------------------------------------|-----------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------|------|-------|------------|
| Param. No. | Characteristics | Min. | Typical | Max. | Units | Conditions |
| LPRC @ 31.25 kHz⁽¹⁾ | | | | | | |
| F21 | LPRC | -15 | — | +15 | % | — |

Note 1: Change of LPRC frequency as VDD changes.

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FIGURE 30-3: I/O TIMING CHARACTERISTICS

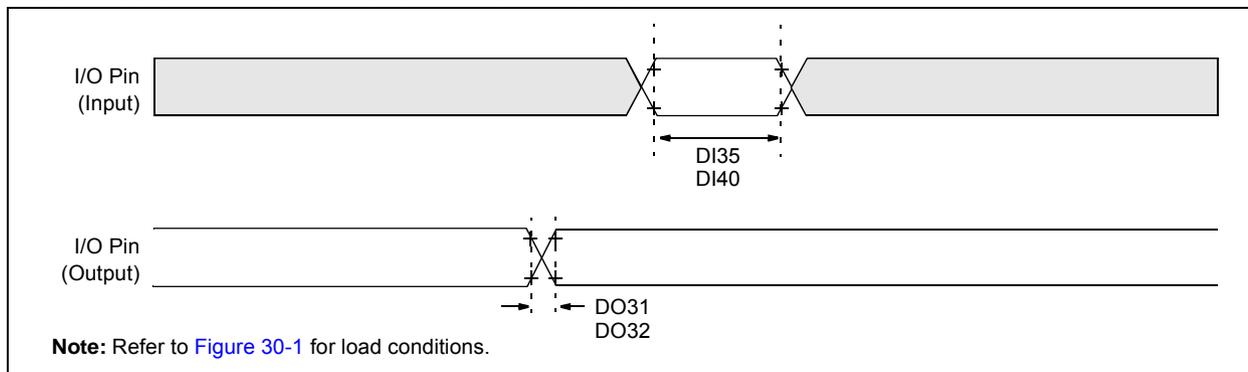


TABLE 30-21: I/O TIMING REQUIREMENTS

| AC CHARACTERISTICS | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp | | | | | |
|--------------------|--------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------|------------------------|------|---------|------------------------|
| Param. No. | Symbol | Characteristics ⁽²⁾ | Min. | Typical ⁽¹⁾ | Max. | Units | Conditions |
| DO31 | TioR | Port Output Rise Time | — | 5 | 15 | ns | $V_{DD} < 2.5\text{V}$ |
| | | | — | 5 | 10 | ns | $V_{DD} > 2.5\text{V}$ |
| DO32 | TioF | Port Output Fall Time | — | 5 | 15 | ns | $V_{DD} < 2.5\text{V}$ |
| | | | — | 5 | 10 | ns | $V_{DD} > 2.5\text{V}$ |
| DI35 | TINP | INTx Pin High or Low Time | 10 | — | — | ns | — |
| DI40 | TRBP | CNx High or Low Time (input) | 2 | — | — | TSYSCLK | — |

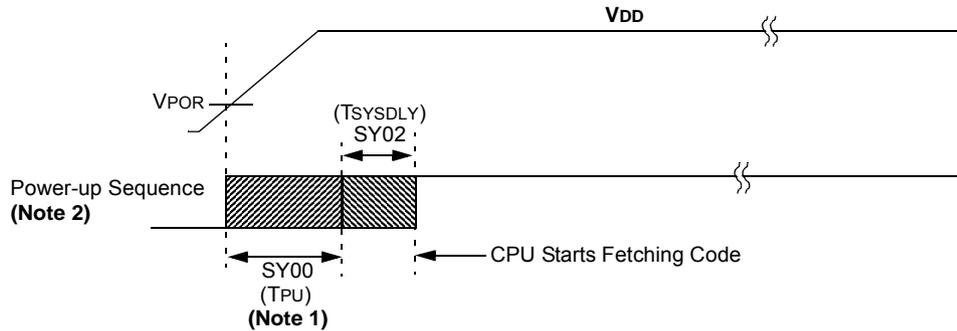
Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated.

Note 2: This parameter is characterized, but not tested in manufacturing.

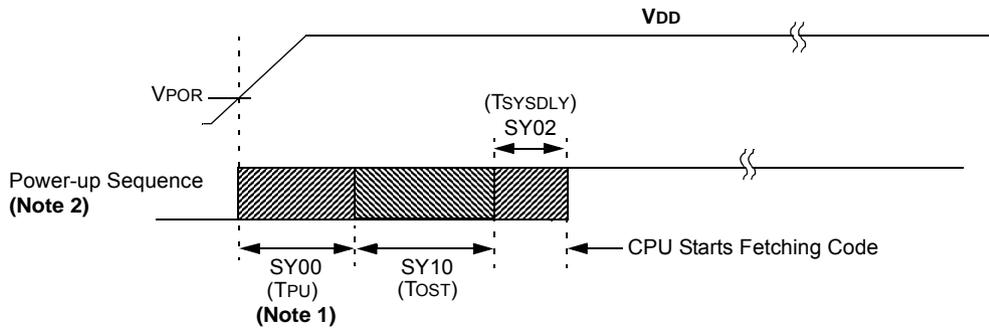
PIC32MX1XX/2XX 28/36/44-PIN FAMILY

FIGURE 30-4: POWER-ON RESET TIMING CHARACTERISTICS

Internal Voltage Regulator Enabled
Clock Sources = (FRC, FRCDIV, FRCDIV16, FRCPLL, EC, ECPLL and LPRC)



Internal Voltage Regulator Enabled
Clock Sources = (HS, HSPLL, XT, XTPLL and Sosc)



Note 1: The power-up period will be extended if the power-up sequence completes before the device exits from BOR ($V_{DD} < V_{DDMIN}$).

2: Includes interval voltage regulator stabilization delay.

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FIGURE 30-5: EXTERNAL RESET TIMING CHARACTERISTICS

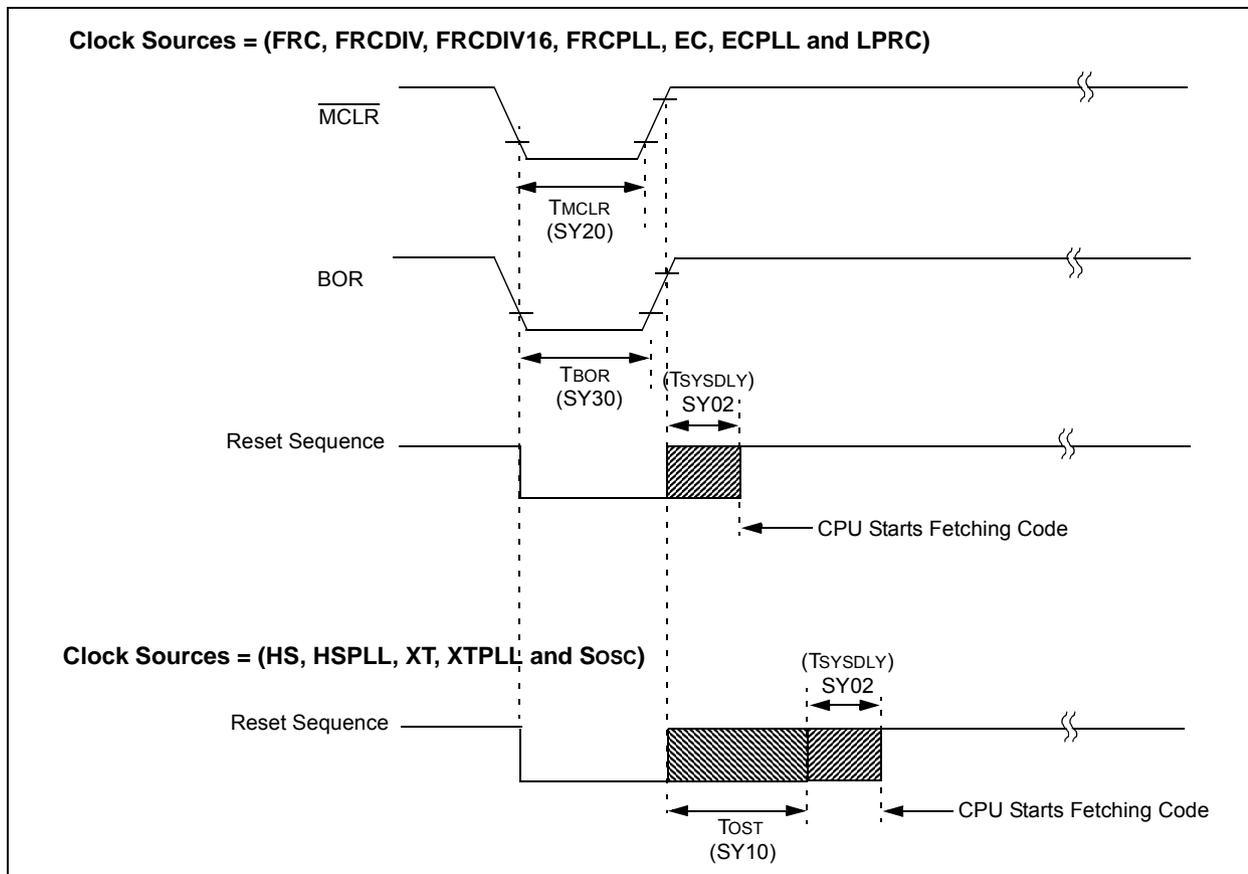


TABLE 30-22: RESETS TIMING

| AC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp | | | | |
|--------------------|---------|--------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------|------|-------|------------|
| Param. No. | Symbol | Characteristics ⁽¹⁾ | Min. | Typical ⁽²⁾ | Max. | Units | Conditions |
| SY00 | TPU | Power-up Period Internal Voltage Regulator Enabled | — | 400 | 600 | μs | — |
| SY02 | TSYSDLY | System Delay Period: Time Required to Reload Device Configuration Fuses plus SYSCLK Delay before First instruction is Fetched. | — | 1 μs + 8 SYSCLK cycles | — | — | — |
| SY20 | TMCLR | MCLR Pulse Width (low) | 2 | — | — | μs | — |
| SY30 | TBOR | BOR Pulse Width (low) | — | 1 | — | μs | — |

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated. Characterized by design but not tested.

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FIGURE 30-6: TIMER1, 2, 3, 4, 5 EXTERNAL CLOCK TIMING CHARACTERISTICS

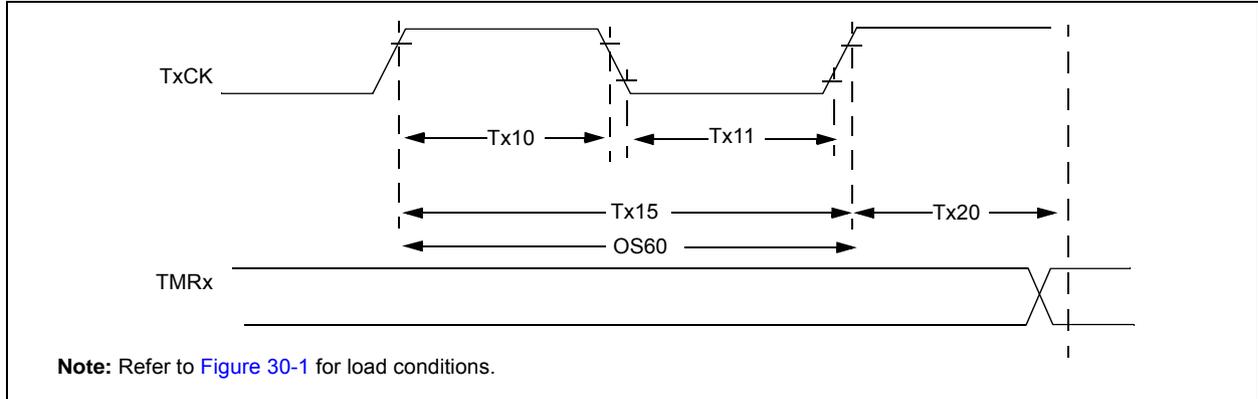


TABLE 30-23: TIMER1 EXTERNAL CLOCK TIMING REQUIREMENTS

| AC CHARACTERISTICS ⁽¹⁾ | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp | | | | | | |
|-----------------------------------|-----------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------------|----------------------------------------------------------------------------|---------|------|-------------------------------------------|-------------------------------------------|
| Param. No. | Symbol | Characteristics ⁽²⁾ | | Min. | Typical | Max. | Units | Conditions |
| TA10 | T _{TXH} | TxCK High Time | Synchronous, with prescaler | $[(12.5 \text{ ns or } 1 \text{ TPB})/N] + 25 \text{ ns}$ | — | — | ns | Must also meet parameter TA15 |
| | | | Asynchronous, with prescaler | 10 | — | — | ns | — |
| TA11 | T _{TXL} | TxCK Low Time | Synchronous, with prescaler | $[(12.5 \text{ ns or } 1 \text{ TPB})/N] + 25 \text{ ns}$ | — | — | ns | Must also meet parameter TA15 |
| | | | Asynchronous, with prescaler | 10 | — | — | ns | — |
| TA15 | T _{TXP} | TxCK Input Period | Synchronous, with prescaler | $[(\text{Greater of } 25 \text{ ns or } 2 \text{ TPB})/N] + 30 \text{ ns}$ | — | — | ns | V _{DD} > 2.7V |
| | | | | $[(\text{Greater of } 25 \text{ ns or } 2 \text{ TPB})/N] + 50 \text{ ns}$ | — | — | ns | V _{DD} < 2.7V |
| | | | Asynchronous, with prescaler | 20 | — | — | ns | V _{DD} > 2.7V (Note 3) |
| | | 50 | | — | — | ns | V _{DD} < 2.7V (Note 3) | |
| OS60 | F _{T1} | SOSC1/T1CK Oscillator Input Frequency Range (oscillator enabled by setting the TCS (T1CON<1>) bit) | | 32 | — | 100 | kHz | — |
| TA20 | T _{CKEXTMRL} | Delay from External TxCK Clock Edge to Timer Increment | | — | — | 1 | TPB | — |

Note 1: Timer1 is a Type A timer.

2: This parameter is characterized, but not tested in manufacturing.

3: N = Prescale Value (1, 8, 64, 256).

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TABLE 30-24: TIMER2, 3, 4, 5 EXTERNAL CLOCK TIMING REQUIREMENTS

| AC CHARACTERISTICS | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp | | | | | |
|--------------------|-----------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-----------------------------|--------------------------------------------------------------------------------|------|-------|-----------------------------------------------------------------------------------|
| Param. No. | Symbol | Characteristics ⁽¹⁾ | | Min. | Max. | Units | Conditions |
| TB10 | TtXH | TxCK High Time | Synchronous, with prescaler | $[(12.5 \text{ ns or } 1 \text{ TPB})/N] + 25 \text{ ns}$ | — | ns | Must also meet parameter TB15 N = prescale value (1, 2, 4, 8, 16, 32, 64, 256) |
| TB11 | TtXL | TxCK Low Time | Synchronous, with prescaler | $[(12.5 \text{ ns or } 1 \text{ TPB})/N] + 25 \text{ ns}$ | — | ns | |
| TB15 | TtXP | TxCK Input Period | Synchronous, with prescaler | $[(\text{Greater of } [(25 \text{ ns or } 2 \text{ TPB})/N] + 30 \text{ ns})]$ | — | ns | |
| | | | | $[(\text{Greater of } [(25 \text{ ns or } 2 \text{ TPB})/N] + 50 \text{ ns})]$ | — | ns | VDD < 2.7V |
| TB20 | TCKEXTMRL | Delay from External TxCK Clock Edge to Timer Increment | | — | 1 | TPB | — |

Note 1: These parameters are characterized, but not tested in manufacturing.

FIGURE 30-7: INPUT CAPTURE (CAPx) TIMING CHARACTERISTICS

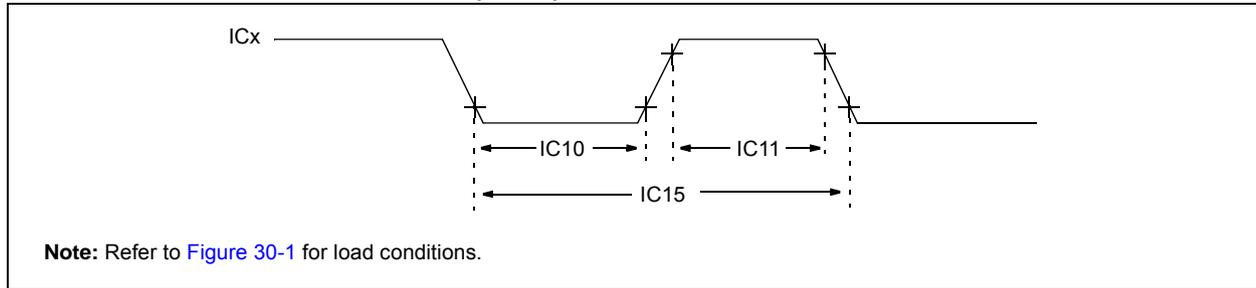


TABLE 30-25: INPUT CAPTURE MODULE TIMING REQUIREMENTS

| AC CHARACTERISTICS | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp | | | | | |
|--------------------|--------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--|-----------------------------------------------------------|------|-------|-----------------------------------------------------------------|
| Param. No. | Symbol | Characteristics ⁽¹⁾ | | Min. | Max. | Units | Conditions |
| IC10 | TccL | ICx Input Low Time | | $[(12.5 \text{ ns or } 1 \text{ TPB})/N] + 25 \text{ ns}$ | — | ns | Must also meet parameter IC15. N = prescale value (1, 4, 16) |
| IC11 | TccH | ICx Input High Time | | $[(12.5 \text{ ns or } 1 \text{ TPB})/N] + 25 \text{ ns}$ | — | ns | |
| IC15 | TccP | ICx Input Period | | $[(25 \text{ ns or } 2 \text{ TPB})/N] + 50 \text{ ns}$ | — | ns | — |

Note 1: These parameters are characterized, but not tested in manufacturing.

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FIGURE 30-8: OUTPUT COMPARE MODULE (OCx) TIMING CHARACTERISTICS

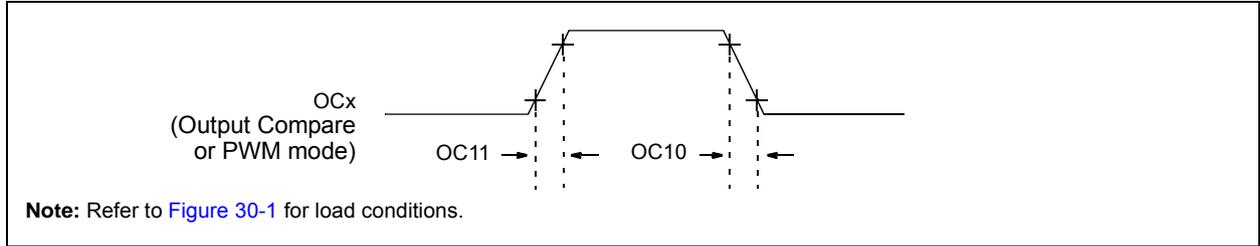


TABLE 30-26: OUTPUT COMPARE MODULE TIMING REQUIREMENTS

| AC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp | | | | |
|--------------------|--------|--------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------|------|-------|--------------------|
| Param. No. | Symbol | Characteristics ⁽¹⁾ | Min. | Typical ⁽²⁾ | Max. | Units | Conditions |
| OC10 | TccF | OCx Output Fall Time | — | — | — | ns | See parameter DO32 |
| OC11 | TccR | OCx Output Rise Time | — | — | — | ns | See parameter DO31 |

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

FIGURE 30-9: OCx/PWM MODULE TIMING CHARACTERISTICS

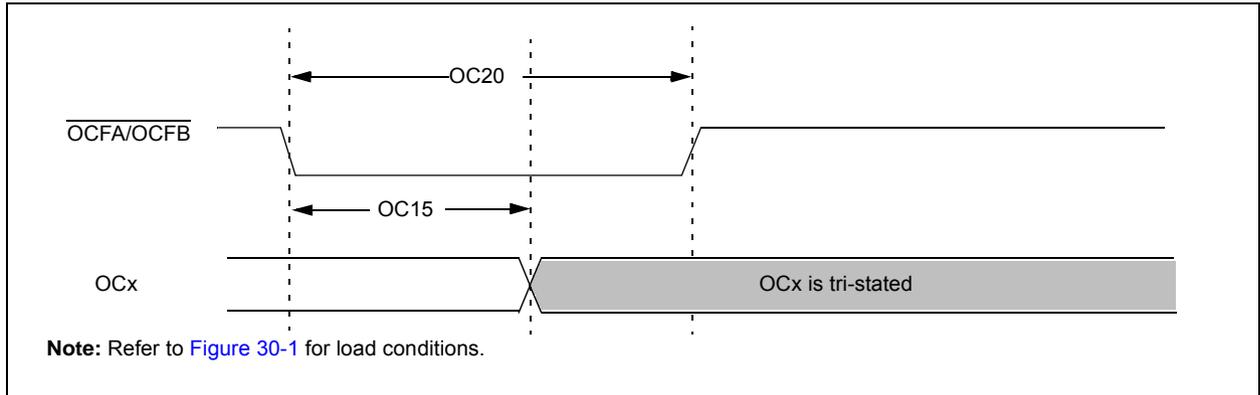


TABLE 30-27: SIMPLE OCx/PWM MODE TIMING REQUIREMENTS

| AC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp | | | | |
|--------------------|--------|--------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------|-----|-------|------------|
| Param No. | Symbol | Characteristics ⁽¹⁾ | Min | Typical ⁽²⁾ | Max | Units | Conditions |
| OC15 | TFD | Fault Input to PWM I/O Change | — | — | 50 | ns | — |
| OC20 | TFLT | Fault Input Pulse Width | 50 | — | — | ns | — |

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

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FIGURE 30-10: SPIx MODULE MASTER MODE (CKE = 0) TIMING CHARACTERISTICS

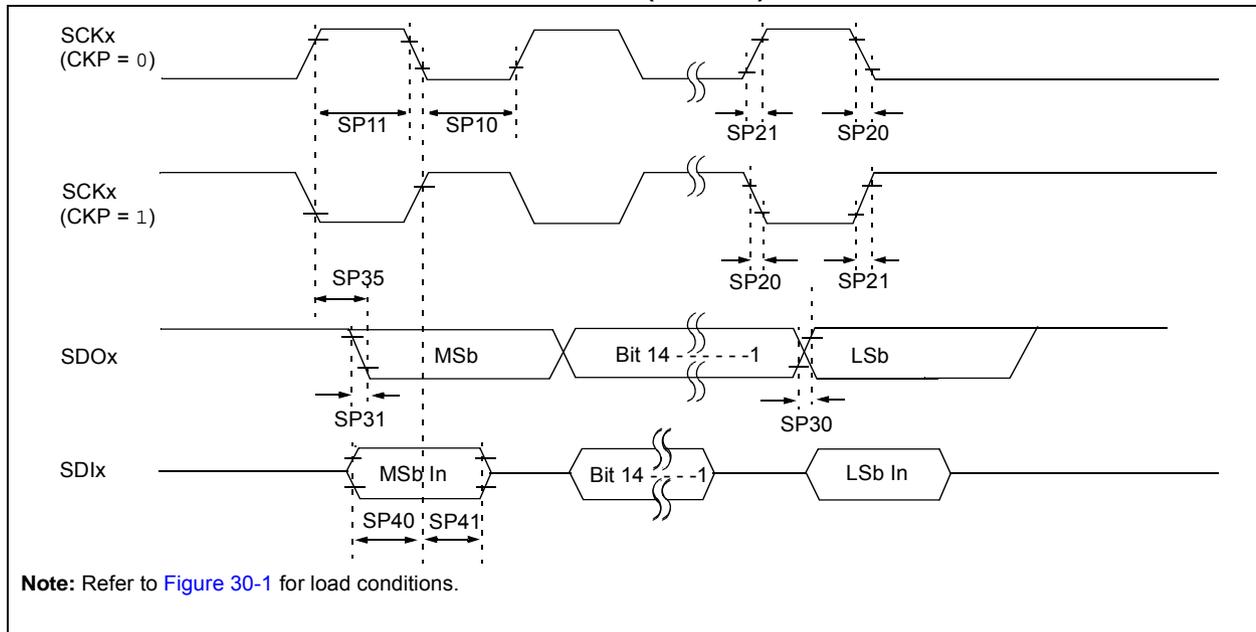


TABLE 30-28: SPIx MASTER MODE (CKE = 0) TIMING REQUIREMENTS

| AC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ Ta ≤ +85°C for Industrial -40°C ≤ Ta ≤ +105°C for V-temp | | | | |
|--------------------|-----------------------|-----------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------|------|-------|--------------------|
| Param. No. | Symbol | Characteristics ⁽¹⁾ | Min. | Typical ⁽²⁾ | Max. | Units | Conditions |
| SP10 | TsCL | SCKx Output Low Time (Note 3) | TsCK/2 | — | — | ns | — |
| SP11 | TsCH | SCKx Output High Time (Note 3) | TsCK/2 | — | — | ns | — |
| SP20 | TsCF | SCKx Output Fall Time (Note 4) | — | — | — | ns | See parameter DO32 |
| SP21 | TsCR | SCKx Output Rise Time (Note 4) | — | — | — | ns | See parameter DO31 |
| SP30 | TdOF | SDOx Data Output Fall Time (Note 4) | — | — | — | ns | See parameter DO32 |
| SP31 | TdOR | SDOx Data Output Rise Time (Note 4) | — | — | — | ns | See parameter DO31 |
| SP35 | TsCH2DoV, TsCL2DoV | SDOx Data Output Valid after SCKx Edge | — | — | 15 | ns | VDD > 2.7V |
| | | | — | — | 20 | ns | VDD < 2.7V |
| SP40 | TdIV2sCH, TdIV2sCL | Setup Time of SDIx Data Input to SCKx Edge | 10 | — | — | ns | — |
| SP41 | TsCH2dIL, TsCL2dIL | Hold Time of SDIx Data Input to SCKx Edge | 10 | — | — | ns | — |

- Note 1:** These parameters are characterized, but not tested in manufacturing.
- Note 2:** Data in “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.
- Note 3:** The minimum clock period for SCKx is 50 ns. Therefore, the clock generated in Master mode must not violate this specification.
- Note 4:** Assumes 50 pF load on all SPIx pins.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

FIGURE 30-11: SPIx MODULE MASTER MODE (CKE = 1) TIMING CHARACTERISTICS

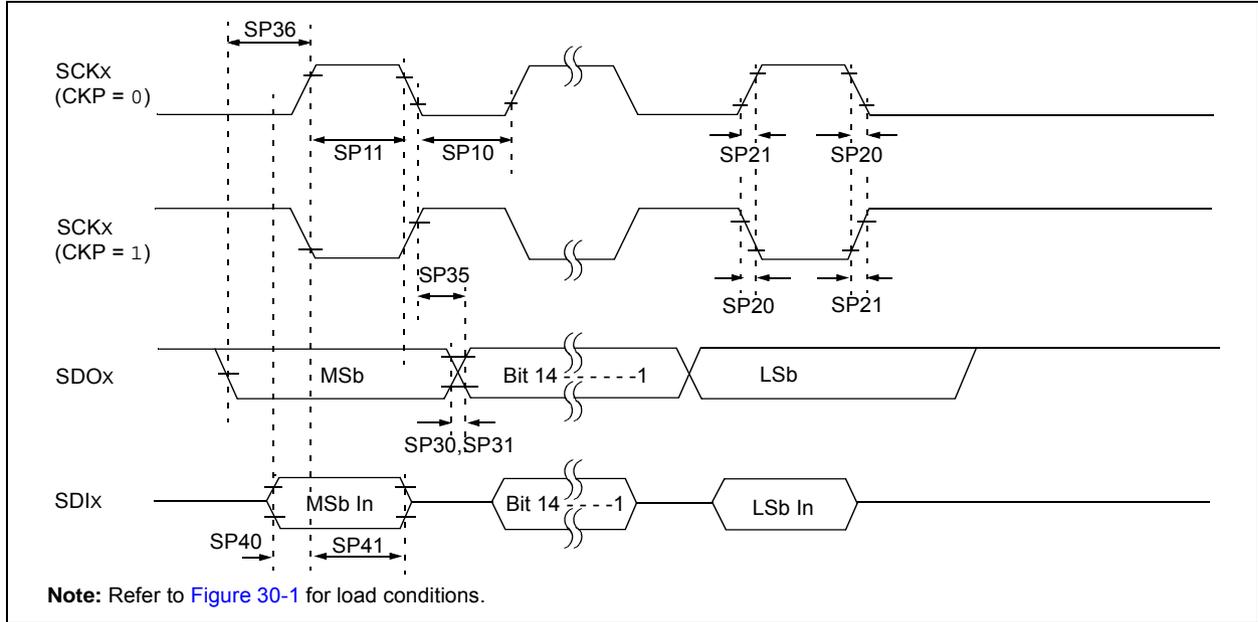


TABLE 30-29: SPIx MODULE MASTER MODE (CKE = 1) TIMING REQUIREMENTS

| AC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp | | | | |
|--------------------|-----------------------|--------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------------------|------|-------|------------------------|
| Param. No. | Symbol | Characteristics ⁽¹⁾ | Min. | Typ. ⁽²⁾ | Max. | Units | Conditions |
| SP10 | TscL | SCKx Output Low Time (Note 3) | T _{SCK} /2 | — | — | ns | — |
| SP11 | Tsch | SCKx Output High Time (Note 3) | T _{SCK} /2 | — | — | ns | — |
| SP20 | TscF | SCKx Output Fall Time (Note 4) | — | — | — | ns | See parameter DO32 |
| SP21 | TscR | SCKx Output Rise Time (Note 4) | — | — | — | ns | See parameter DO31 |
| SP30 | TdoF | SDOx Data Output Fall Time (Note 4) | — | — | — | ns | See parameter DO32 |
| SP31 | TdoR | SDOx Data Output Rise Time (Note 4) | — | — | — | ns | See parameter DO31 |
| SP35 | Tsch2doV, TscL2doV | SDOx Data Output Valid after SCKx Edge | — | — | 15 | ns | V _{DD} > 2.7V |
| | | | — | — | 20 | ns | V _{DD} < 2.7V |
| SP36 | TdoV2sc, TdoV2scL | SDOx Data Output Setup to First SCKx Edge | 15 | — | — | ns | — |
| SP40 | TdiV2sch, TdiV2scL | Setup Time of SDIx Data Input to SCKx Edge | 15 | — | — | ns | V _{DD} > 2.7V |
| | | | 20 | — | — | ns | V _{DD} < 2.7V |
| SP41 | Tsch2diL, TscL2diL | Hold Time of SDIx Data Input to SCKx Edge | 15 | — | — | ns | V _{DD} > 2.7V |
| | | | 20 | — | — | ns | V _{DD} < 2.7V |

Note 1: These parameters are characterized, but not tested in manufacturing.

Note 2: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

Note 3: The minimum clock period for SCKx is 50 ns. Therefore, the clock generated in Master mode must not violate this specification.

Note 4: Assumes 50 pF load on all SPIx pins.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

FIGURE 30-12: SPIx MODULE SLAVE MODE (CKE = 0) TIMING CHARACTERISTICS

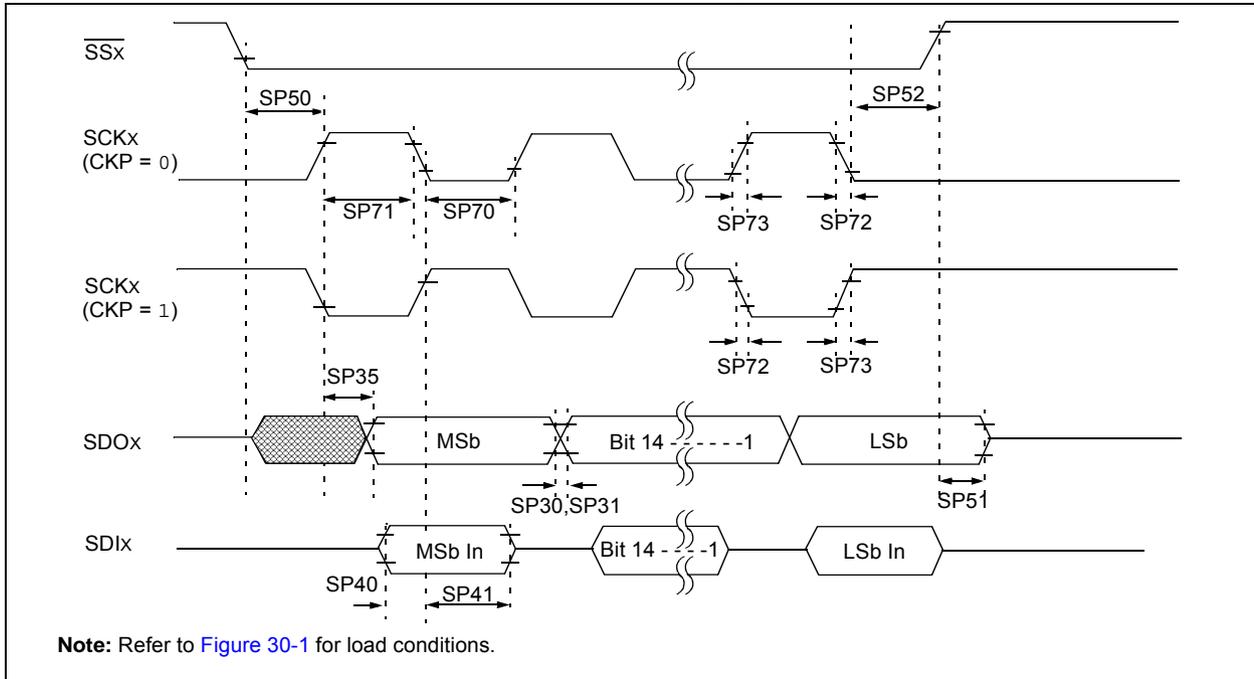


TABLE 30-30: SPIx MODULE SLAVE MODE (CKE = 0) TIMING REQUIREMENTS

| AC CHARACTERISTICS | | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp | | | |
|--------------------|-----------------------|-------------------------------------------------------------------------------------|-----------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------|-------|-------------------------------|
| Param. No. | Symbol | Characteristics ⁽¹⁾ | Min. | Typ. ⁽²⁾ | Max. | Units | Conditions |
| SP70 | TscL | SCKx Input Low Time (Note 3) | $T_{\text{SCK}}/2$ | — | — | ns | — |
| SP71 | Tsch | SCKx Input High Time (Note 3) | $T_{\text{SCK}}/2$ | — | — | ns | — |
| SP72 | TscF | SCKx Input Fall Time | — | — | — | ns | See parameter DO32 |
| SP73 | TscR | SCKx Input Rise Time | — | — | — | ns | See parameter DO31 |
| SP30 | TdoF | SDOx Data Output Fall Time (Note 4) | — | — | — | ns | See parameter DO32 |
| SP31 | TdoR | SDOx Data Output Rise Time (Note 4) | — | — | — | ns | See parameter DO31 |
| SP35 | Tsch2boV, TscL2doV | SDOx Data Output Valid after SCKx Edge | — | — | 15 | ns | $V_{\text{DD}} > 2.7\text{V}$ |
| | | | — | — | 20 | ns | $V_{\text{DD}} < 2.7\text{V}$ |
| SP40 | TdIV2sch, TdIV2scL | Setup Time of SDIx Data Input to SCKx Edge | 10 | — | — | ns | — |
| SP41 | Tsch2diL, TscL2diL | Hold Time of SDIx Data Input to SCKx Edge | 10 | — | — | ns | — |
| SP50 | Tssl2sch, Tssl2scL | $\overline{\text{SSx}} \downarrow$ to SCKx \uparrow or SCKx Input | 175 | — | — | ns | — |
| SP51 | Tssh2doZ | $\overline{\text{SSx}} \uparrow$ to SDOx Output High-Impedance (Note 3) | 5 | — | 25 | ns | — |
| SP52 | Tsch2ssh, TscL2ssh | $\overline{\text{SSx}}$ after SCKx Edge | $T_{\text{SCK}} + 20$ | — | — | ns | — |

Note 1: These parameters are characterized, but not tested in manufacturing.

Note 2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

Note 3: The minimum clock period for SCKx is 50 ns.

Note 4: Assumes 50 pF load on all SPIx pins.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

FIGURE 30-13: SPIx MODULE SLAVE MODE (CKE = 1) TIMING CHARACTERISTICS

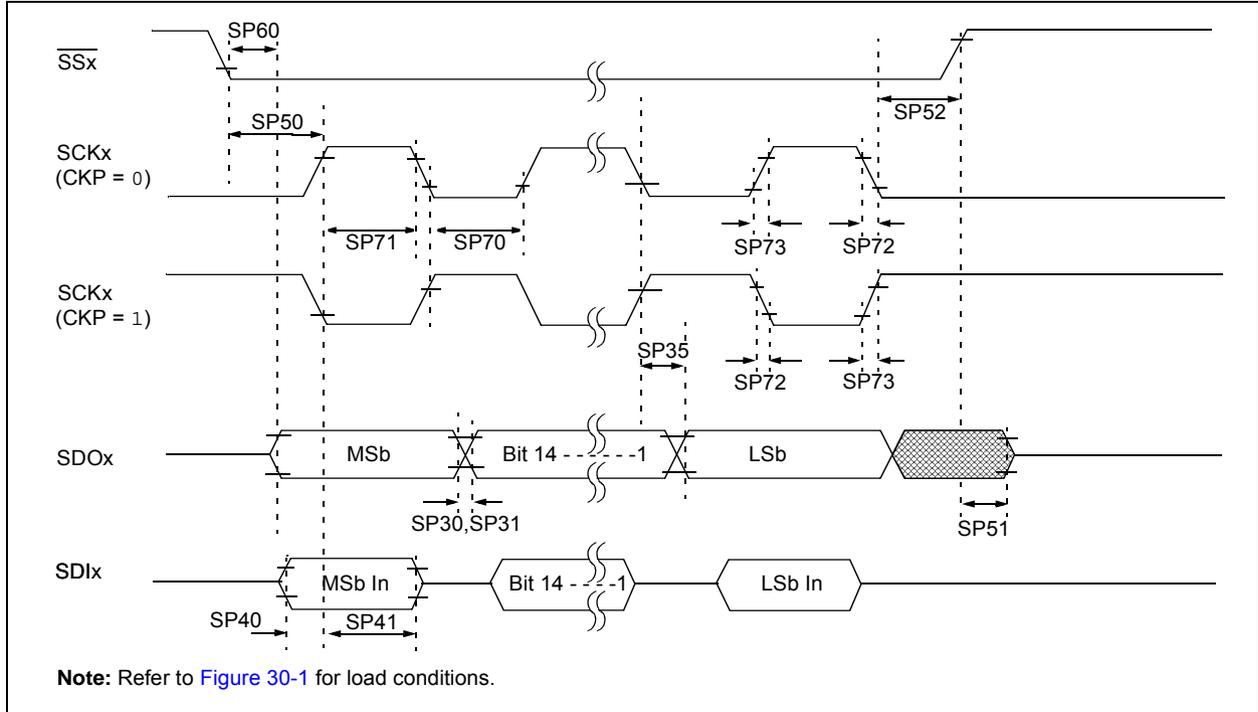


TABLE 30-31: SPIx MODULE SLAVE MODE (CKE = 1) TIMING REQUIREMENTS

| AC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp | | | | |
|--------------------|-----------------------|----------------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------|------|-------|-------------------------------|
| Param. No. | Symbol | Characteristics ⁽¹⁾ | Min. | Typical ⁽²⁾ | Max. | Units | Conditions |
| SP70 | TsCL | SCKx Input Low Time (Note 3) | $T_{\text{SCK}}/2$ | — | — | ns | — |
| SP71 | TsCH | SCKx Input High Time (Note 3) | $T_{\text{SCK}}/2$ | — | — | ns | — |
| SP72 | TsCF | SCKx Input Fall Time | — | 5 | 10 | ns | — |
| SP73 | TsCR | SCKx Input Rise Time | — | 5 | 10 | ns | — |
| SP30 | TdOF | SDOx Data Output Fall Time (Note 4) | — | — | — | ns | See parameter DO32 |
| SP31 | TdOR | SDOx Data Output Rise Time (Note 4) | — | — | — | ns | See parameter DO31 |
| SP35 | TsCH2doV, TsCL2doV | SDOx Data Output Valid after SCKx Edge | — | — | 20 | ns | $V_{\text{DD}} > 2.7\text{V}$ |
| | | | — | — | 30 | ns | $V_{\text{DD}} < 2.7\text{V}$ |
| SP40 | TdIV2sCH, TdIV2sCL | Setup Time of SDIx Data Input to SCKx Edge | 10 | — | — | ns | — |
| SP41 | TsCH2dIL, TsCL2dIL | Hold Time of SDIx Data Input to SCKx Edge | 10 | — | — | ns | — |
| SP50 | TssL2sCH, TssL2sCL | $\overline{\text{SSx}} \downarrow$ to SCKx \downarrow or SCKx \uparrow Input | 175 | — | — | ns | — |

Note 1: These parameters are characterized, but not tested in manufacturing.

Note 2: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

Note 3: The minimum clock period for SCKx is 50 ns.

Note 4: Assumes 50 pF load on all SPIx pins.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 30-31: SPIx MODULE SLAVE MODE (CKE = 1) TIMING REQUIREMENTS (CONTINUED)

| AC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp | | | | |
|--------------------|----------------------|------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------|------|-------|------------|
| Param. No. | Symbol | Characteristics ⁽¹⁾ | Min. | Typical ⁽²⁾ | Max. | Units | Conditions |
| SP51 | TssH2boZ | $\overline{\text{SS}}_x \uparrow$ to SDOx Output High-Impedance (Note 4) | 5 | — | 25 | ns | — |
| SP52 | Tsch2ssH TscL2ssH | $\overline{\text{SS}}_x \uparrow$ after SCKx Edge | Tsck + 20 | — | — | ns | — |
| SP60 | Tssl2boV | SDOx Data Output Valid after $\overline{\text{SS}}_x$ Edge | — | — | 25 | ns | — |

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 50 ns.

4: Assumes 50 pF load on all SPIx pins.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

FIGURE 30-14: I2Cx BUS START/STOP BITS TIMING CHARACTERISTICS (MASTER MODE)

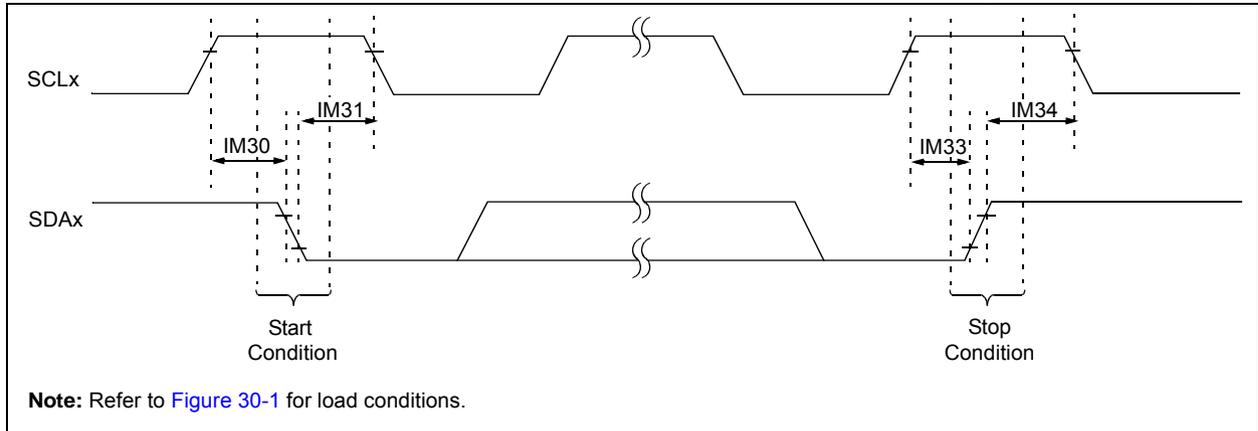
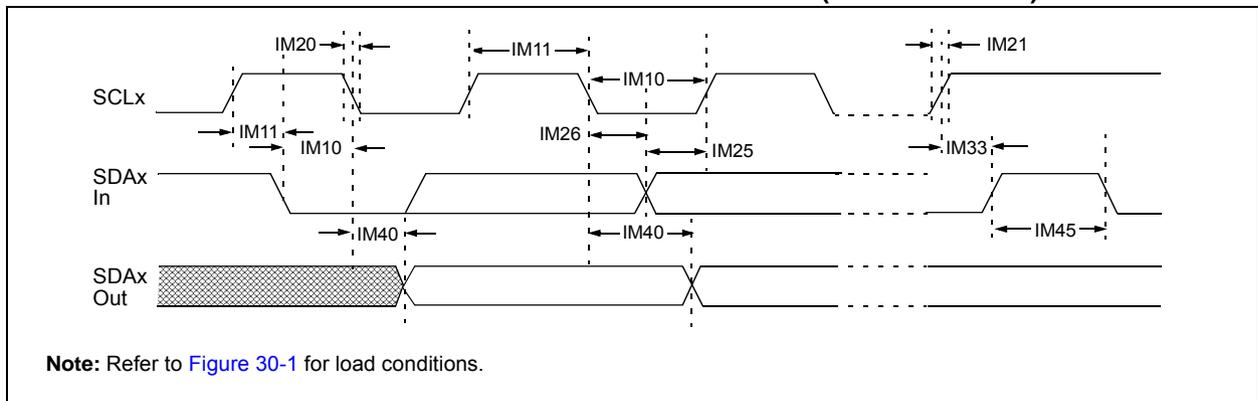


FIGURE 30-15: I2Cx BUS DATA TIMING CHARACTERISTICS (MASTER MODE)



PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 30-32: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE)

| AC CHARACTERISTICS | | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp | | | |
|--------------------|---------|-------------------------------|-------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------|-------|-------------------------------------------------------------|
| Param. No. | Symbol | Characteristics | | Min. ⁽¹⁾ | Max. | Units | Conditions |
| IM10 | TLO:SCL | Clock Low Time | 100 kHz mode | TPB * (BRG + 2) | — | μs | — |
| | | | 400 kHz mode | TPB * (BRG + 2) | — | μs | — |
| | | | 1 MHz mode (Note 2) | TPB * (BRG + 2) | — | μs | — |
| IM11 | THI:SCL | Clock High Time | 100 kHz mode | TPB * (BRG + 2) | — | μs | — |
| | | | 400 kHz mode | TPB * (BRG + 2) | — | μs | — |
| | | | 1 MHz mode (Note 2) | TPB * (BRG + 2) | — | μs | — |
| IM20 | TF:SCL | SDAx and SCLx Fall Time | 100 kHz mode | — | 300 | ns | Cb is specified to be from 10 to 400 pF |
| | | | 400 kHz mode | 20 + 0.1 Cb | 300 | ns | |
| | | | 1 MHz mode (Note 2) | — | 100 | ns | |
| IM21 | TR:SCL | SDAx and SCLx Rise Time | 100 kHz mode | — | 1000 | ns | Cb is specified to be from 10 to 400 pF |
| | | | 400 kHz mode | 20 + 0.1 Cb | 300 | ns | |
| | | | 1 MHz mode (Note 2) | — | 300 | ns | |
| IM25 | TSU:DAT | Data Input Setup Time | 100 kHz mode | 250 | — | ns | — |
| | | | 400 kHz mode | 100 | — | ns | |
| | | | 1 MHz mode (Note 2) | 100 | — | ns | |
| IM26 | THD:DAT | Data Input Hold Time | 100 kHz mode | 0 | — | μs | — |
| | | | 400 kHz mode | 0 | 0.9 | μs | |
| | | | 1 MHz mode (Note 2) | 0 | 0.3 | μs | |
| IM30 | TSU:STA | Start Condition Setup Time | 100 kHz mode | TPB * (BRG + 2) | — | μs | Only relevant for Repeated Start condition |
| | | | 400 kHz mode | TPB * (BRG + 2) | — | μs | |
| | | | 1 MHz mode (Note 2) | TPB * (BRG + 2) | — | μs | |
| IM31 | THD:STA | Start Condition Hold Time | 100 kHz mode | TPB * (BRG + 2) | — | μs | After this period, the first clock pulse is generated |
| | | | 400 kHz mode | TPB * (BRG + 2) | — | μs | |
| | | | 1 MHz mode (Note 2) | TPB * (BRG + 2) | — | μs | |
| IM33 | TSU:STO | Stop Condition Setup Time | 100 kHz mode | TPB * (BRG + 2) | — | μs | — |
| | | | 400 kHz mode | TPB * (BRG + 2) | — | μs | |
| | | | 1 MHz mode (Note 2) | TPB * (BRG + 2) | — | μs | |
| IM34 | THD:STO | Stop Condition Hold Time | 100 kHz mode | TPB * (BRG + 2) | — | ns | — |
| | | | 400 kHz mode | TPB * (BRG + 2) | — | ns | |
| | | | 1 MHz mode (Note 2) | TPB * (BRG + 2) | — | ns | |

Note 1: BRG is the value of the I²C Baud Rate Generator.

2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

3: The typical value for this parameter is 104 ns.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 30-32: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE) (CONTINUED)

| AC CHARACTERISTICS | | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp | | | |
|--------------------|---------|-------------------------|-------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------|------|-------|-----------------------------------------------------------------------------|
| Param. No. | Symbol | Characteristics | | Min. ⁽¹⁾ | Max. | Units | Conditions |
| IM40 | TAA:SCL | Output Valid from Clock | 100 kHz mode | — | 3500 | ns | — |
| | | | 400 kHz mode | — | 1000 | ns | — |
| | | | 1 MHz mode (Note 2) | — | 350 | ns | — |
| IM45 | TBF:SDA | Bus Free Time | 100 kHz mode | 4.7 | — | μs | The amount of time the bus must be free before a new transmission can start |
| | | | 400 kHz mode | 1.3 | — | μs | |
| | | | 1 MHz mode (Note 2) | 0.5 | — | μs | |
| IM50 | CB | Bus Capacitive Loading | | — | 400 | pF | — |
| IM51 | TPGD | Pulse Gobbler Delay | | 52 | 312 | ns | See Note 3 |

Note 1: BRG is the value of the I²C Baud Rate Generator.

2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

3: The typical value for this parameter is 104 ns.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

FIGURE 30-16: I2Cx BUS START/STOP BITS TIMING CHARACTERISTICS (SLAVE MODE)

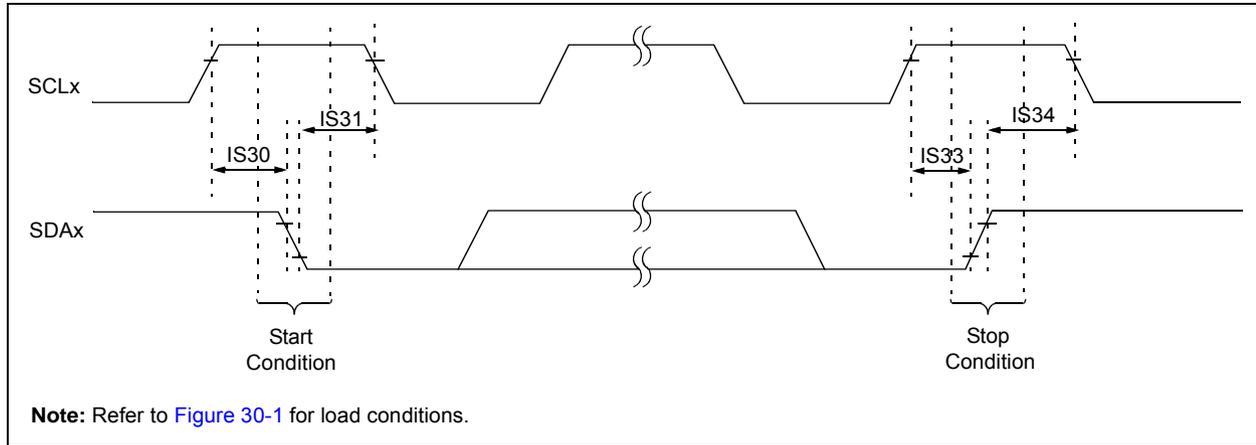
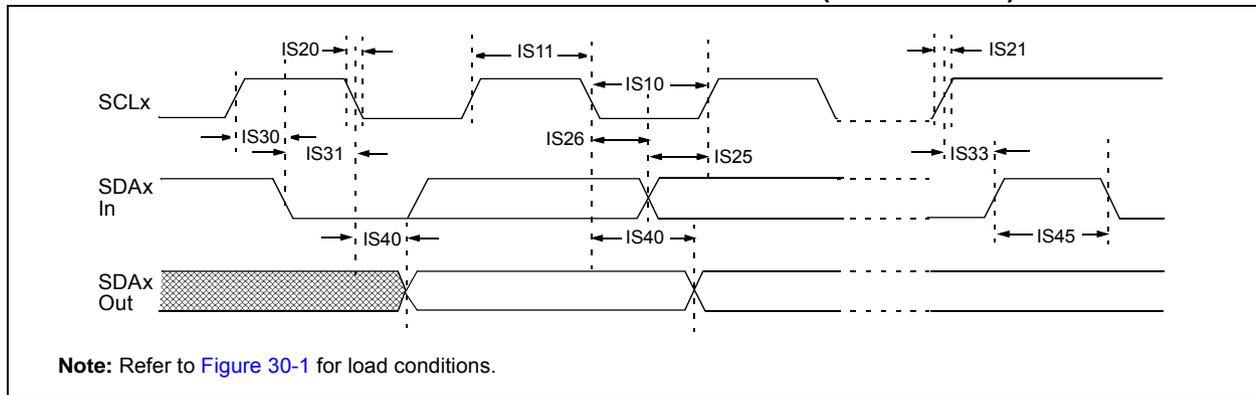


FIGURE 30-17: I2Cx BUS DATA TIMING CHARACTERISTICS (SLAVE MODE)



PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 30-33: I2Cx BUS DATA TIMING REQUIREMENTS (SLAVE MODE)

| AC CHARACTERISTICS | | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp | | | |
|--------------------|---------|----------------------------|------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------|---------------|-------------------------------------------------------|
| Param. No. | Symbol | Characteristics | | Min. | Max. | Units | Conditions |
| IS10 | TLO:SCL | Clock Low Time | 100 kHz mode | 4.7 | — | μs | PBCLK must operate at a minimum of 800 kHz |
| | | | 400 kHz mode | 1.3 | — | μs | PBCLK must operate at a minimum of 3.2 MHz |
| | | | 1 MHz mode (Note 1) | 0.5 | — | μs | — |
| IS11 | THI:SCL | Clock High Time | 100 kHz mode | 4.0 | — | μs | PBCLK must operate at a minimum of 800 kHz |
| | | | 400 kHz mode | 0.6 | — | μs | PBCLK must operate at a minimum of 3.2 MHz |
| | | | 1 MHz mode (Note 1) | 0.5 | — | μs | — |
| IS20 | TF:SCL | SDAx and SCLx Fall Time | 100 kHz mode | — | 300 | ns | Cb is specified to be from 10 to 400 pF |
| | | | 400 kHz mode | $20 + 0.1 C_B$ | 300 | ns | |
| | | | 1 MHz mode (Note 1) | — | 100 | ns | |
| IS21 | TR:SCL | SDAx and SCLx Rise Time | 100 kHz mode | — | 1000 | ns | Cb is specified to be from 10 to 400 pF |
| | | | 400 kHz mode | $20 + 0.1 C_B$ | 300 | ns | |
| | | | 1 MHz mode (Note 1) | — | 300 | ns | |
| IS25 | TSU:DAT | Data Input Setup Time | 100 kHz mode | 250 | — | ns | — |
| | | | 400 kHz mode | 100 | — | ns | |
| | | | 1 MHz mode (Note 1) | 100 | — | ns | |
| IS26 | THD:DAT | Data Input Hold Time | 100 kHz mode | 0 | — | ns | — |
| | | | 400 kHz mode | 0 | 0.9 | μs | |
| | | | 1 MHz mode (Note 1) | 0 | 0.3 | μs | |
| IS30 | TSU:STA | Start Condition Setup Time | 100 kHz mode | 4700 | — | ns | Only relevant for Repeated Start condition |
| | | | 400 kHz mode | 600 | — | ns | |
| | | | 1 MHz mode (Note 1) | 250 | — | ns | |
| IS31 | THD:STA | Start Condition Hold Time | 100 kHz mode | 4000 | — | ns | After this period, the first clock pulse is generated |
| | | | 400 kHz mode | 600 | — | ns | |
| | | | 1 MHz mode (Note 1) | 250 | — | ns | |
| IS33 | TSU:STO | Stop Condition Setup Time | 100 kHz mode | 4000 | — | ns | — |
| | | | 400 kHz mode | 600 | — | ns | |
| | | | 1 MHz mode (Note 1) | 600 | — | ns | |

Note 1: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 30-33: I2Cx BUS DATA TIMING REQUIREMENTS (SLAVE MODE) (CONTINUED)

| AC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp | | | | |
|--------------------|---------|--------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------|------|-------|------------|-----------------------------------------------------------------------------|
| Param. No. | Symbol | Characteristics | Min. | Max. | Units | Conditions | |
| IS34 | THD:STO | Stop Condition Hold Time | 100 kHz mode | 4000 | — | ns | — |
| | | | 400 kHz mode | 600 | — | ns | |
| | | | 1 MHz mode (Note 1) | 250 | — | ns | |
| IS40 | TAA:SCL | Output Valid from Clock | 100 kHz mode | 0 | 3500 | ns | — |
| | | | 400 kHz mode | 0 | 1000 | ns | |
| | | | 1 MHz mode (Note 1) | 0 | 350 | ns | |
| IS45 | TBF:SDA | Bus Free Time | 100 kHz mode | 4.7 | — | μs | The amount of time the bus must be free before a new transmission can start |
| | | | 400 kHz mode | 1.3 | — | μs | |
| | | | 1 MHz mode (Note 1) | 0.5 | — | μs | |
| IS50 | CB | Bus Capacitive Loading | — | 400 | pF | — | |

Note 1: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 30-34: ADC MODULE SPECIFICATIONS

| AC CHARACTERISTICS | | | Standard Operating Conditions (see Note 5): 2.5V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp | | | | |
|--------------------------------------------------------------|-----------|------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------------|----------------------------|--------------------------------|--------------------------------------------------------------------------------------|
| Param. No. | Symbol | Characteristics | Min. | Typical | Max. | Units | Conditions |
| Device Supply | | | | | | | |
| AD01 | AVDD | Module VDD Supply | Greater of VDD – 0.3 or 2.5 | — | Lesser of VDD + 0.3 or 3.6 | V | — |
| AD02 | AVSS | Module Vss Supply | Vss | — | AVDD | V | (Note 1) |
| Reference Inputs | | | | | | | |
| AD05 AD05a | VREFH | Reference Voltage High | AVSS + 2.0 2.5 | — — | AVDD 3.6 | V V | (Note 1) VREFH = AVDD (Note 3) |
| AD06 | VREFL | Reference Voltage Low | AVSS | — | VREFH – 2.0 | V | (Note 1) |
| AD07 | VREF | Absolute Reference Voltage (VREFH – VREFL) | 2.0 | — | AVDD | V | (Note 3) |
| AD08 AD08a | IREF | Current Drain | — — | 250 — | 400 3 | μA μA | ADC operating ADC off |
| Analog Input | | | | | | | |
| AD12 | VINH-VINL | Full-Scale Input Span | VREFL | — | VREFH | V | — |
| AD13 | VINL | Absolute VINL Input Voltage | AVSS – 0.3 | — | AVDD/2 | V | — |
| AD14 | VIN | Absolute Input Voltage | AVSS – 0.3 | — | AVDD + 0.3 | V | — |
| AD15 | — | Leakage Current | — | ± 0.001 | ± 0.610 | μA | VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.3V Source Impedance = 10 k Ω |
| AD17 | RIN | Recommended Impedance of Analog Voltage Source | — | — | 5k | Ω | (Note 1) |
| ADC Accuracy – Measurements with External VREF+/VREF- | | | | | | | |
| AD20c | Nr | Resolution | 10 data bits | | | bits | — |
| AD21c | INL | Integral Non-linearity | > -1 | — | < 1 | LSb | VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.3V |
| AD22c | DNL | Differential Non-linearity | > -1 | — | < 1 | LSb | VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.3V (Note 2) |
| AD23c | GERR | Gain Error | > -1 | — | < 1 | LSb | VINL = AVSS = VREFL = 0V, AVDD = VREFH = 3.3V |
| AD24c | E0FF | Offset Error | > -1 | — | < 1 | Lsb | VINL = AVSS = 0V, AVDD = 3.3V |
| AD25c | — | Monotonicity | — | — | — | — | Guaranteed |

Note 1: These parameters are not characterized or tested in manufacturing.

2: With no missing codes.

3: These parameters are characterized, but not tested in manufacturing.

4: Characterized with a 1 kHz sine wave.

5: The ADC module is functional at $V_{BORMIN} < V_{DD} < 2.5\text{V}$, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 30-34: ADC MODULE SPECIFICATIONS

| AC CHARACTERISTICS | | | Standard Operating Conditions (see Note 5): 2.5V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp | | | | |
|--------------------------------------------------------------|------------------|--------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------|------|-------|----------------------------------------------------------------------------------------------------|
| Param. No. | Symbol | Characteristics | Min. | Typical | Max. | Units | Conditions |
| ADC Accuracy – Measurements with Internal VREF+/VREF- | | | | | | | |
| AD20d | Nr | Resolution | 10 data bits | | | bits | (Note 3) |
| AD21d | INL | Integral Non-linearity | > -1 | — | < 1 | LSb | V _{INL} = AV _{SS} = 0V, AV _{DD} = 2.5V to 3.6V (Note 3) |
| AD22d | DNL | Differential Non-linearity | > -1 | — | < 1 | LSb | V _{INL} = AV _{SS} = 0V, AV _{DD} = 2.5V to 3.6V (Notes 2,3) |
| AD23d | GERR | Gain Error | > -4 | — | < 4 | LSb | V _{INL} = AV _{SS} = 0V, AV _{DD} = 2.5V to 3.6V (Note 3) |
| AD24d | E _{OFF} | Offset Error | > -2 | — | < 2 | Lsb | V _{INL} = AV _{SS} = 0V, AV _{DD} = 2.5V to 3.6V (Note 3) |
| AD25d | — | Monotonicity | — | — | — | — | Guaranteed |
| Dynamic Performance | | | | | | | |
| AD32b | SINAD | Signal to Noise and Distortion | 55 | 58.5 | — | dB | (Notes 3,4) |
| AD34b | ENOB | Effective Number of bits | 9.0 | 9.5 | — | bits | (Notes 3,4) |

- Note 1:** These parameters are not characterized or tested in manufacturing.
2: With no missing codes.
3: These parameters are characterized, but not tested in manufacturing.
4: Characterized with a 1 kHz sine wave.
5: The ADC module is functional at $V_{BORMIN} < V_{DD} < 2.5\text{V}$, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 30-35: 10-BIT CONVERSION RATE PARAMETERS

| AC CHARACTERISTICS ⁽²⁾ | | | Standard Operating Conditions (see Note 3): 2.5V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp | | |
|-----------------------------------|----------|--------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------|----------------------------|
| ADC Speed | TAD Min. | Sampling Time Min. | Rs Max. | VDD | ADC Channels Configuration |
| 1 Msps to 400 ksps ⁽¹⁾ | 65 ns | 132 ns | 500Ω | 3.0V to 3.6V | |
| Up to 400 ksps | 200 ns | 200 ns | 5.0 kΩ | 2.5V to 3.6V | |

- Note 1:** External VREF- and VREF+ pins must be used for correct operation.
- 2:** These parameters are characterized, but not tested in manufacturing.
- 3:** The ADC module is functional at VBORMIN < VDD < 2.5V, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

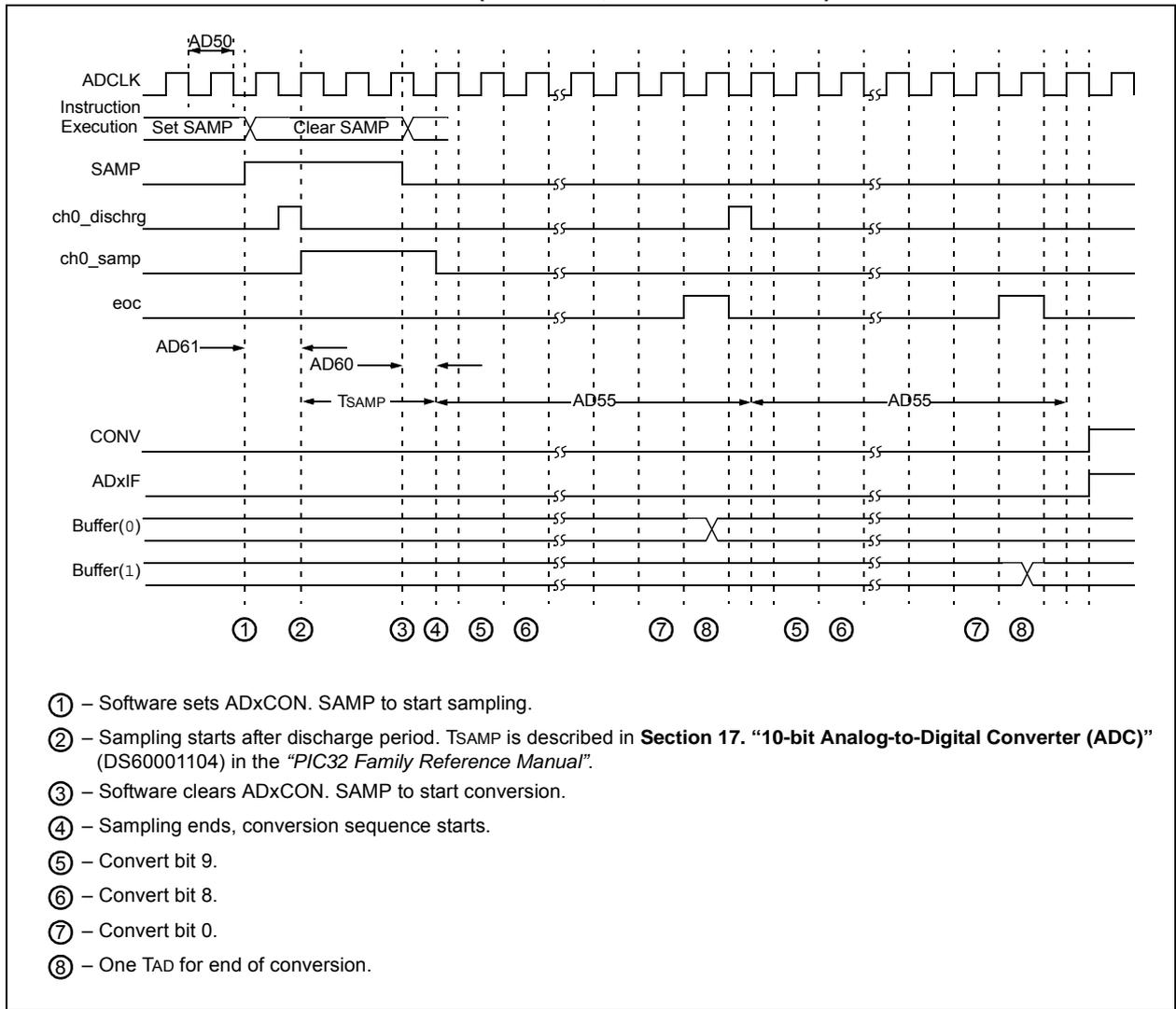
TABLE 30-36: ANALOG-TO-DIGITAL CONVERSION TIMING REQUIREMENTS

| AC CHARACTERISTICS | | | Standard Operating Conditions (see Note 4): 2.5V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp | | | | |
|--------------------------|--------|----------------------------------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------------------|---------|-------|-----------------------------------------------------|
| Param. No. | Symbol | Characteristics | Min. | Typical ⁽¹⁾ | Max. | Units | Conditions |
| Clock Parameters | | | | | | | |
| AD50 | TAD | ADC Clock Period ⁽²⁾ | 65 | — | — | ns | See Table 30-35 |
| Conversion Rate | | | | | | | |
| AD55 | TCONV | Conversion Time | — | 12 TAD | — | — | — |
| AD56 | FCNV | Throughput Rate (Sampling Speed) | — | — | 1000 | ksps | AVDD = 3.0V to 3.6V |
| | | | — | — | 400 | ksps | AVDD = 2.5V to 3.6V |
| AD57 | TSAMP | Sample Time | 1 TAD | — | — | — | TSAMP must be ≥ 132 ns |
| Timing Parameters | | | | | | | |
| AD60 | TPCS | Conversion Start from Sample Trigger ⁽³⁾ | — | 1.0 TAD | — | — | Auto-Convert Trigger (SSRC<2:0> = 111) not selected |
| AD61 | TPSS | Sample Start from Setting Sample (SAMP) bit | 0.5 TAD | — | 1.5 TAD | — | — |
| AD62 | TCSS | Conversion Completion to Sample Start (ASAM = 1) ⁽³⁾ | — | 0.5 TAD | — | — | — |
| AD63 | TDPU | Time to Stabilize Analog Stage from ADC Off to ADC On ⁽³⁾ | — | — | 2 | μs | — |

- Note 1:** These parameters are characterized, but not tested in manufacturing.
- 2:** Because the sample caps will eventually lose charge, clock rates below 10 kHz can affect linearity performance, especially at elevated temperatures.
- 3:** Characterized by design but not tested.
- 4:** The ADC module is functional at VBORMIN < VDD < 2.5V, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

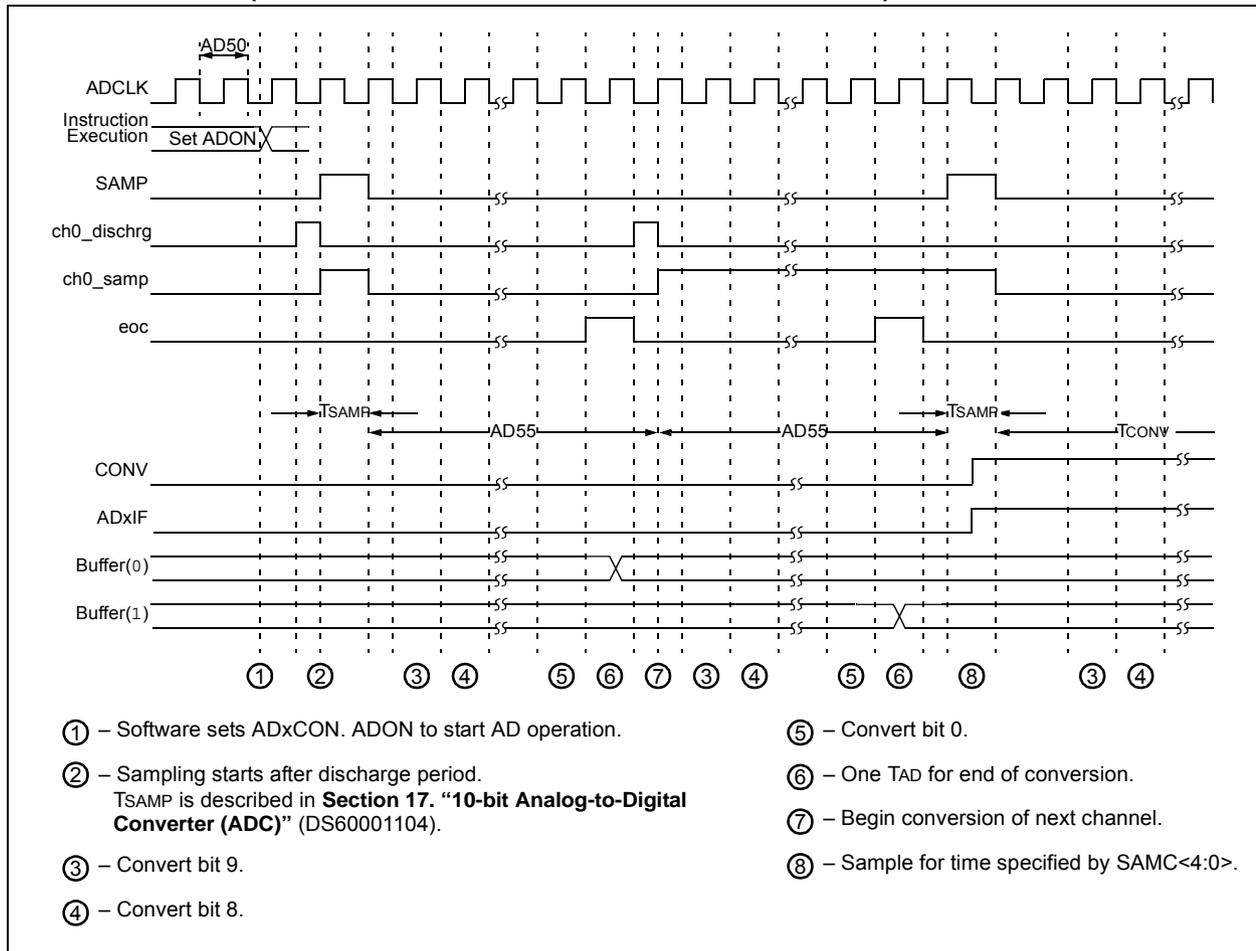
PIC32MX1XX/2XX 28/36/44-PIN FAMILY

FIGURE 30-18: ANALOG-TO-DIGITAL CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (ASAM = 0, SSRC<2:0> = 000)



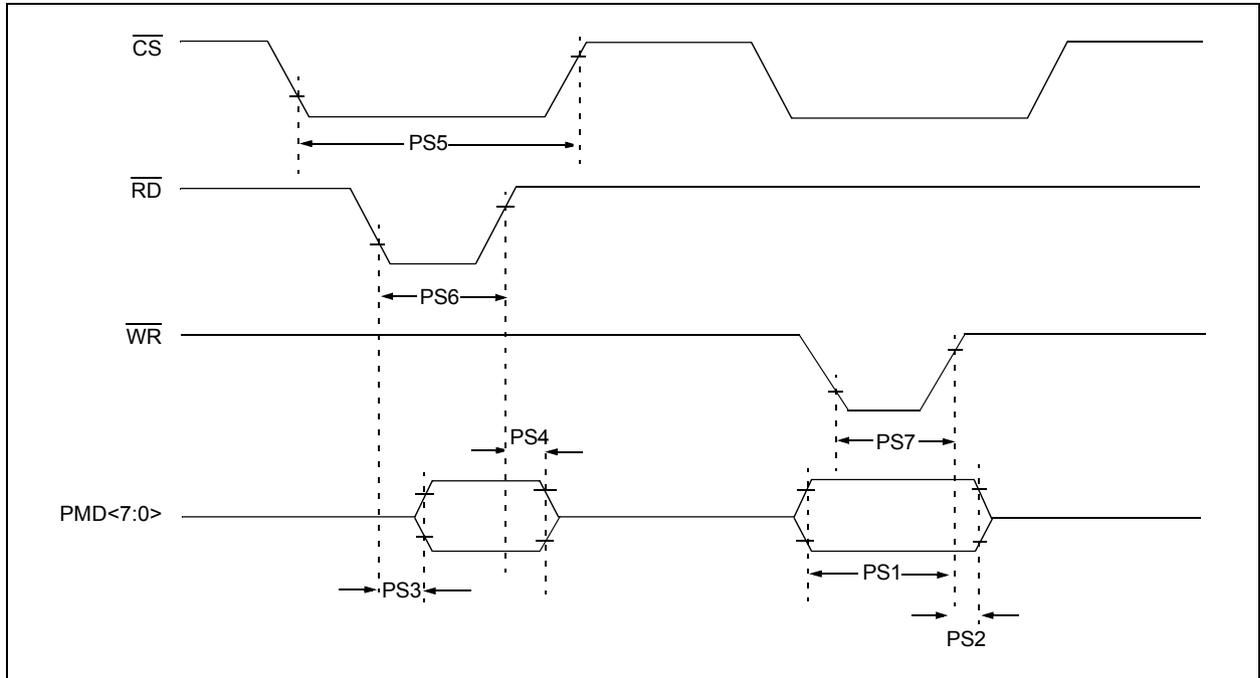
PIC32MX1XX/2XX 28/36/44-PIN FAMILY

FIGURE 30-19: ANALOG-TO-DIGITAL CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (ASAM = 1, SSRC<2:0> = 111, SAMC<4:0> = 00001)



PIC32MX1XX/2XX 28/36/44-PIN FAMILY

FIGURE 30-20: PARALLEL SLAVE PORT TIMING



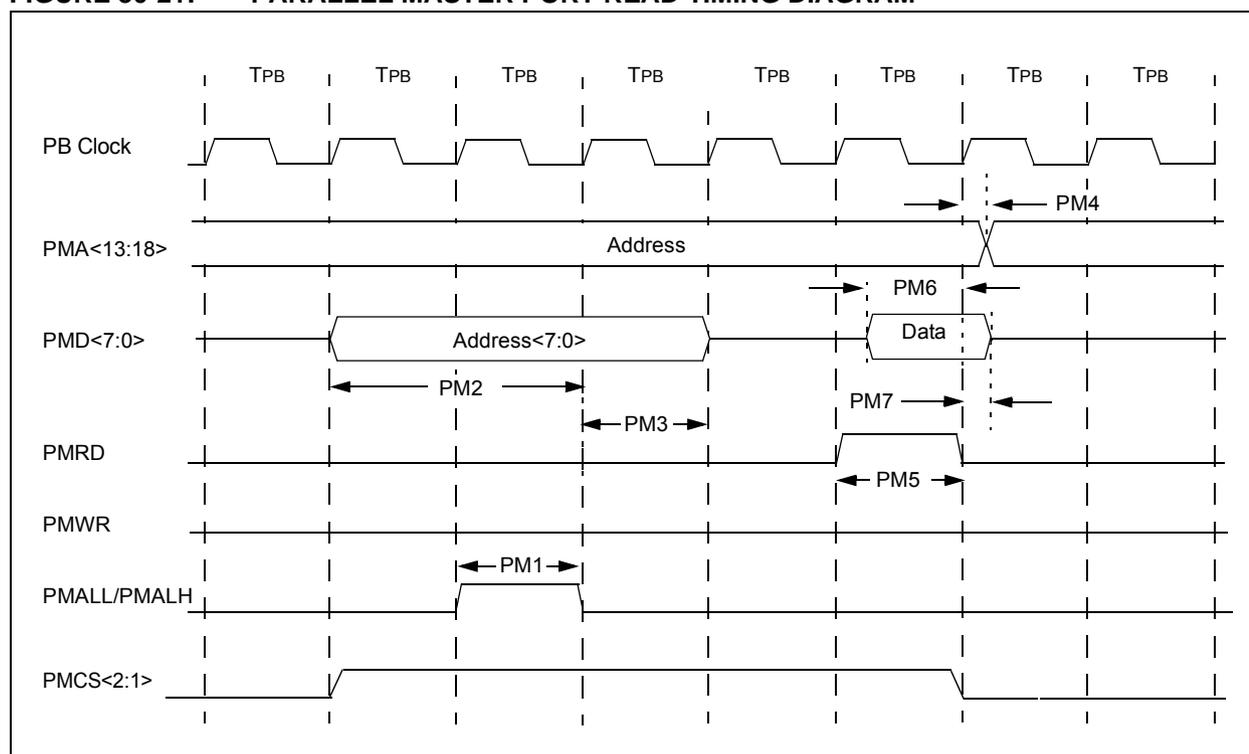
PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 30-37: PARALLEL SLAVE PORT REQUIREMENTS

| AC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp | | | | |
|--------------------|--------------|---------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------|------|-------|------------|
| Para m.No. | Symbol | Characteristics ⁽¹⁾ | Min. | Typ. | Max. | Units | Conditions |
| PS1 | TdtV2wr H | Data In Valid before $\overline{\text{WR}}$ or $\overline{\text{CS}}$ Inactive (setup time) | 20 | — | — | ns | — |
| PS2 | TwrH2dt I | $\overline{\text{WR}}$ or $\overline{\text{CS}}$ Inactive to Data-In Invalid (hold time) | 40 | — | — | ns | — |
| PS3 | TrdL2dt V | $\overline{\text{RD}}$ and $\overline{\text{CS}}$ Active to Data-Out Valid | — | — | 60 | ns | — |
| PS4 | TrdH2dtI | $\overline{\text{RD}}$ Active or $\overline{\text{CS}}$ Inactive to Data-Out Invalid | 0 | — | 10 | ns | — |
| PS5 | Tcs | $\overline{\text{CS}}$ Active Time | TPB + 40 | — | — | ns | — |
| PS6 | TWR | $\overline{\text{WR}}$ Active Time | TPB + 25 | — | — | ns | — |
| PS7 | TRD | $\overline{\text{RD}}$ Active Time | TPB + 25 | — | — | ns | — |

Note 1: These parameters are characterized, but not tested in manufacturing.

FIGURE 30-21: PARALLEL MASTER PORT READ TIMING DIAGRAM



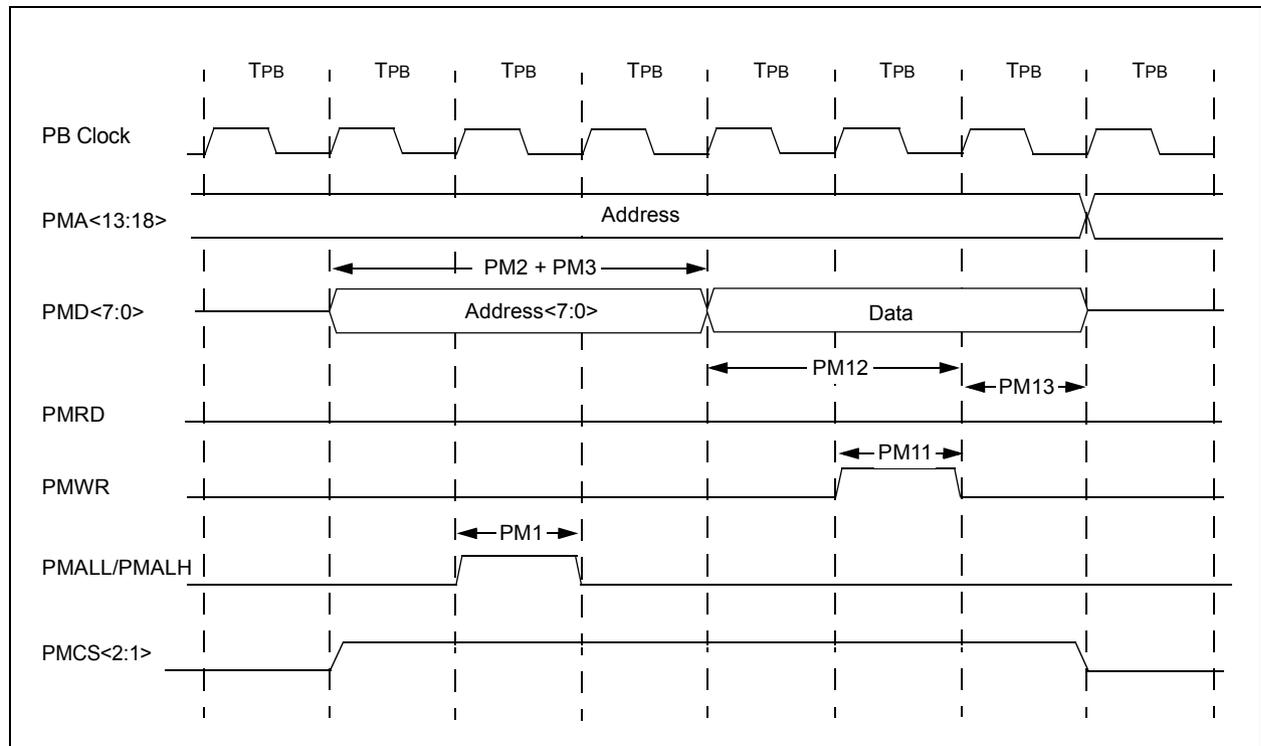
PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 30-38: PARALLEL MASTER PORT READ TIMING REQUIREMENTS

| AC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp | | | | |
|--------------------|---------------------|----------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------|------|-------|------------|
| Param. No. | Symbol | Characteristics ⁽¹⁾ | Min. | Typ. | Max. | Units | Conditions |
| PM1 | T _{LAT} | PMALL/PMALH Pulse Width | — | 1 TPB | — | — | — |
| PM2 | T _{ADSU} | Address Out Valid to PMALL/PMALH Invalid (address setup time) | — | 2 TPB | — | — | — |
| PM3 | T _{ADHOLD} | PMALL/PMALH Invalid to Address Out Invalid (address hold time) | — | 1 TPB | — | — | — |
| PM4 | T _{AHOLD} | PMRD Inactive to Address Out Invalid (address hold time) | 5 | — | — | ns | — |
| PM5 | T _{RD} | PMRD Pulse Width | — | 1 TPB | — | — | — |
| PM6 | T _{DSU} | PMRD or PMENB Active to Data In Valid (data setup time) | 15 | — | — | ns | — |
| PM7 | T _{DHOLD} | PMRD or PMENB Inactive to Data In Invalid (data hold time) | — | 80 | — | ns | — |

Note 1: These parameters are characterized, but not tested in manufacturing.

FIGURE 30-22: PARALLEL MASTER PORT WRITE TIMING DIAGRAM



PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 30-39: PARALLEL MASTER PORT WRITE TIMING REQUIREMENTS

| AC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp | | | | |
|--------------------|---------|---------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------|------|-------|------------|
| Param. No. | Symbol | Characteristics ⁽¹⁾ | Min. | Typ. | Max. | Units | Conditions |
| PM11 | TWR | PMWR Pulse Width | — | 1 TPB | — | — | — |
| PM12 | TDVSU | Data Out Valid before PMWR or PMENB goes Inactive (data setup time) | — | 2 TPB | — | — | — |
| PM13 | TDVHOLD | PMWR or PMEMB Invalid to Data Out Invalid (data hold time) | — | 1 TPB | — | — | — |

Note 1: These parameters are characterized, but not tested in manufacturing.

TABLE 30-40: OTG ELECTRICAL SPECIFICATIONS

| AC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp | | | | |
|--------------------|---------|-----------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------|------|----------|--------------------------------------------------------------------------|
| Param. No. | Symbol | Characteristics ⁽¹⁾ | Min. | Typ. | Max. | Units | Conditions |
| USB313 | VUSB3V3 | USB Voltage | 3.0 | — | 3.6 | V | Voltage on VUSB3V3 must be in this range for proper USB operation |
| USB315 | VILUSB | Input Low Voltage for USB Buffer | — | — | 0.8 | V | — |
| USB316 | VIHUSB | Input High Voltage for USB Buffer | 2.0 | — | — | V | — |
| USB318 | VDIFS | Differential Input Sensitivity | — | — | 0.2 | V | The difference between D+ and D- must exceed this value while VCM is met |
| USB319 | VCM | Differential Common Mode Range | 0.8 | — | 2.5 | V | — |
| USB320 | ZOUT | Driver Output Impedance | 28.0 | — | 44.0 | Ω | — |
| USB321 | VoL | Voltage Output Low | 0.0 | — | 0.3 | V | 1.425 k Ω load connected to VUSB3V3 |
| USB322 | VoH | Voltage Output High | 2.8 | — | 3.6 | V | 1.425 k Ω load connected to ground |

Note 1: These parameters are characterized, but not tested in manufacturing.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 30-41: CTMU CURRENT SOURCE SPECIFICATIONS

| DC CHARACTERISTICS | | | Standard Operating Conditions (see Note 3): 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp | | | | |
|----------------------------|--------|----------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|-------|------|-------|----------------------------------------------|
| Param No. | Symbol | Characteristic | Min. | Typ. | Max. | Units | Conditions |
| CTMU CURRENT SOURCE | | | | | | | |
| CTMUI1 | IOUT1 | Base Range ⁽¹⁾ | — | 0.55 | — | μA | CTMUCON<9:8> = 01 |
| CTMUI2 | IOUT2 | 10x Range ⁽¹⁾ | — | 5.5 | — | μA | CTMUCON<9:8> = 10 |
| CTMUI3 | IOUT3 | 100x Range ⁽¹⁾ | — | 55 | — | μA | CTMUCON<9:8> = 11 |
| CTMUI4 | IOUT4 | 1000x Range ⁽¹⁾ | — | 550 | — | μA | CTMUCON<9:8> = 00 |
| CTMUFV1 | VF | Temperature Diode Forward Voltage ^(1,2) | — | 0.598 | — | V | T _A = +25°C, CTMUCON<9:8> = 01 |
| | | | — | 0.658 | — | V | T _A = +25°C, CTMUCON<9:8> = 10 |
| | | | — | 0.721 | — | V | T _A = +25°C, CTMUCON<9:8> = 11 |
| CTMUFV2 | VFVR | Temperature Diode Rate of Change ^(1,2) | — | -1.92 | — | mV/°C | CTMUCON<9:8> = 01 |
| | | | — | -1.74 | — | mV/°C | CTMUCON<9:8> = 10 |
| | | | — | -1.56 | — | mV/°C | CTMUCON<9:8> = 11 |

Note 1: Nominal value at center point of current trim range (CTMUCON<15:10> = 000000).

2: Parameters are characterized but not tested in manufacturing. Measurements taken with the following conditions:

- VREF+ = AVDD = 3.3V
- ADC module configured for conversion speed of 500 ksp/s
- All PMD bits are cleared (PMDx = 0)
- Executing a `while(1)` statement
- Device operating from the FRC with no PLL

3: The CTMU module is functional at $V_{BORMIN} < V_{DD} < V_{DDMIN}$, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

FIGURE 30-23: EJTAG TIMING CHARACTERISTICS

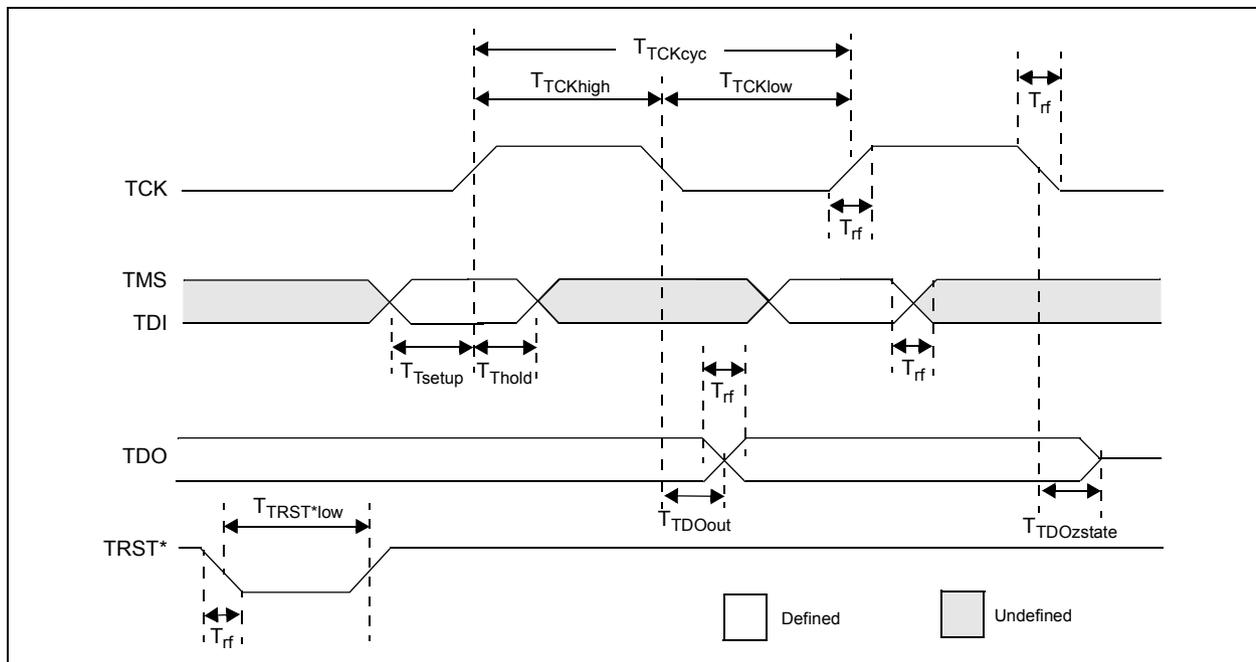


TABLE 30-42: EJTAG TIMING REQUIREMENTS

| AC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ T _A ≤ +85°C for Industrial -40°C ≤ T _A ≤ +105°C for V-temp | | | |
|--------------------|------------|--------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------|-------|------------|
| Param. No. | Symbol | Description ⁽¹⁾ | Min. | Max. | Units | Conditions |
| EJ1 | TTCKCYC | TCK Cycle Time | 25 | — | ns | — |
| EJ2 | TTCKHIGH | TCK High Time | 10 | — | ns | — |
| EJ3 | TTCKLOW | TCK Low Time | 10 | — | ns | — |
| EJ4 | TTSETUP | TAP Signals Setup Time Before Rising TCK | 5 | — | ns | — |
| EJ5 | TTHOLD | TAP Signals Hold Time After Rising TCK | 3 | — | ns | — |
| EJ6 | TTDOOUT | TDO Output Delay Time from Falling TCK | — | 5 | ns | — |
| EJ7 | TTDOZSTATE | TDO 3-State Delay Time from Falling TCK | — | 5 | ns | — |
| EJ8 | TTRSTLOW | TRST Low Time | 25 | — | ns | — |
| EJ9 | TRF | TAP Signals Rise/Fall Time, All Input and Output | — | — | ns | — |

Note 1: These parameters are characterized, but not tested in manufacturing.

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31.0 50 MHz ELECTRICAL CHARACTERISTICS

This section provides an overview of the PIC32MX1XX/2XX 28/36/44-pin Family electrical characteristics for devices operating at 50 MHz.

The specifications for 50 MHz are identical to those shown in [Section 30.0 “Electrical Characteristics”](#), with the exception of the parameters listed in this chapter.

Parameters in this chapter begin with the letter “M”, which denotes 50 MHz operation. For example, parameter DC29a in [Section 30.0 “Electrical Characteristics”](#), is the up to 40 MHz operation equivalent for MDC29a.

Absolute maximum ratings for the PIC32MX1XX/2XX 28/36/44-pin Family 50 MHz devices are listed below. Exposure to these maximum rating conditions for extended periods may affect device reliability. Functional operation of the device at these or any other conditions, above the parameters indicated in the operation listings of this specification, is not implied.

Absolute Maximum Ratings

(See Note 1)

| | |
|--------------------------------------------------------------------------------------------|---------------------------|
| Ambient temperature under bias | -40°C to +85°C |
| Storage temperature | -65°C to +150°C |
| Voltage on VDD with respect to VSS | -0.3V to +4.0V |
| Voltage on any pin that is not 5V tolerant, with respect to VSS (Note 3) | -0.3V to (VDD + 0.3V) |
| Voltage on any 5V tolerant pin with respect to VSS when VDD ≥ 2.3V (Note 3) | -0.3V to +5.5V |
| Voltage on any 5V tolerant pin with respect to VSS when VDD < 2.3V (Note 3) | -0.3V to +3.6V |
| Voltage on D+ or D- pin with respect to VUSB3V3 | -0.3V to (VUSB3V3 + 0.3V) |
| Voltage on VBUS with respect to VSS | -0.3V to +5.5V |
| Maximum current out of VSS pin(s) | 300 mA |
| Maximum current into VDD pin(s) (Note 2) | 300 mA |
| Maximum output current sunk by any I/O pin | 15 mA |
| Maximum output current sourced by any I/O pin | 15 mA |
| Maximum current sunk by all ports | 200 mA |
| Maximum current sourced by all ports (Note 2) | 200 mA |

Note 1: Stresses above those listed under “**Absolute Maximum Ratings**” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions, above those indicated in the operation listings of this specification, is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see [Table 30-2](#)).

3: See the “[Pin Diagrams](#)” section for the 5V tolerant pins.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

31.1 DC Characteristics

TABLE 31-1: OPERATING MIPS VS. VOLTAGE

| Characteristic | VDD Range (in Volts) ⁽¹⁾ | Temp. Range (in °C) | Max. Frequency |
|----------------|----------------------------------------|------------------------|------------------------------------|
| | | | PIC32MX1XX/2XX 28/36/44-pin Family |
| MDC5 | 2.3-3.6V | -40°C to +85°C | 50 MHz |

Note 1: Overall functional device operation at $V_{BORMIN} < V_{DD} < V_{DDMIN}$ is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below V_{DDMIN} . Refer to parameter BO10 in [Table 30-11](#) for BOR values.

TABLE 31-2: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

| DC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial | |
|--------------------------------------------|------------------------|------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------|
| Parameter No. | Typical ⁽³⁾ | Max. | Units | Conditions |
| Operating Current (IDD) (Note 1, 2) | | | | |
| MDC24 | 25 | 37 | mA | 50 MHz |

Note 1: A device's I_{DD} supply current is mainly a function of the operating voltage and frequency. Other factors, such as PBCLK (Peripheral Bus Clock) frequency, number of peripheral modules enabled, internal code execution pattern, execution from Program Flash memory vs. SRAM, I/O pin loading and switching rate, oscillator type, as well as temperature, can have an impact on the current consumption.

2: The test conditions for I_{DD} measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU, Program Flash, and SRAM data memory are operational, SRAM data memory Wait states = 1
- No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is cleared
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{\text{MCLR}} = V_{DD}$
- CPU executing `while(1)` statement from Flash

3: RTCC and JTAG are disabled

4: Data in "Typical" column is at 3.3V, 25°C at specified operating frequency unless otherwise stated. Parameters are for design guidance only and are not tested.

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TABLE 31-3: DC CHARACTERISTICS: IDLE CURRENT (I_{IDLE})

| DC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial | |
|----------------------------------------------------------------------------------|------------------------|------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------|
| Parameter No. | Typical ⁽²⁾ | Max. | Units | Conditions |
| Idle Current (I_{IDLE}): Core Off, Clock on Base Current (Note 1) | | | | |
| MDC34a | 8 | 13 | mA | 50 MHz |

Note 1: The test conditions for I_{IDLE} current measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU is in Idle mode (CPU core Halted), and SRAM data memory Wait states = 1
- No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is cleared
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{\text{MCLR}} = V_{DD}$
- RTCC and JTAG are disabled

2: Data in the “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

TABLE 31-4: DC CHARACTERISTICS: POWER-DOWN CURRENT (I_{PD})

| DC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial | |
|----------------------------------------------------------------------|------------------------|------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------|------------|
| Param. No. | Typical ⁽²⁾ | Max. | Units | Conditions |
| Power-Down Current (I_{PD}) (Note 1) | | | | |
| MDC40k | 10 | 25 | μA | -40°C |
| MDC40n | 250 | 500 | μA | +85°C |
| Base Power-Down Current | | | | |
| Module Differential Current | | | | |
| MDC41e | 10 | 55 | μA | 3.6V |
| MDC42e | 23 | 55 | μA | 3.6V |
| MDC43d | 1100 | 1300 | μA | 3.6V |
| Watchdog Timer Current: ΔI _{WDT} (Note 3) | | | | |
| RTCC + Timer1 w/32 kHz Crystal: ΔI _{RTCC} (Note 3) | | | | |
| ADC: ΔI _{ADC} (Notes 3,4) | | | | |

Note 1: The test conditions for I_{PD} current measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU is in Sleep mode, and SRAM data memory Wait states = 1
- No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is set
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to V_{SS}
- $\overline{\text{MCLR}} = V_{DD}$
- RTCC and JTAG are disabled

2: Data in the “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The Δ current is the additional current consumed when the module is enabled. This current should be added to the base I_{PD} current.

4: Test conditions for ADC module differential current are as follows: Internal ADC RC oscillator enabled.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 31-5: EXTERNAL CLOCK TIMING REQUIREMENTS

| AC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial | | | | |
|--------------------|--------|---------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------|----------|------------|-------------------------------|
| Param. No. | Symbol | Characteristics | Min. | Typical | Max. | Units | Conditions |
| MOS10 | Fosc | External CLKI Frequency (External clocks allowed only in EC and ECPLL modes) | DC 4 | — — | 50 50 | MHz MHz | EC (Note 2) ECPLL (Note 1) |

Note 1: PLL input requirements: $4\text{ MHz} \leq F_{\text{PLLIN}} \leq 5\text{ MHz}$ (use PLL prescaler to reduce Fosc). This parameter is characterized, but tested at 10 MHz only at manufacturing.

2: This parameter is characterized, but not tested in manufacturing.

TABLE 31-6: SPIx MASTER MODE (CKE = 0) TIMING REQUIREMENTS

| AC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial | | | | |
|--------------------|--------|-------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------|------|-------|------------|
| Param. No. | Symbol | Characteristics | Min. | Typical | Max. | Units | Conditions |
| MSP10 | TscL | SCKx Output Low Time (Note 1,2) | Tsck/2 | — | — | ns | — |
| MSP11 | Tsch | SCKx Output High Time (Note 1,2) | Tsck/2 | — | — | ns | — |

Note 1: These parameters are characterized, but not tested in manufacturing.

2: The minimum clock period for SCKx is 40 ns. Therefore, the clock generated in Master mode must not violate this specification.

TABLE 31-7: SPIx MODULE MASTER MODE (CKE = 1) TIMING REQUIREMENTS

| AC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial | | | | |
|--------------------|--------|-------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------|------|-------|------------|
| Param. No. | Symbol | Characteristics ⁽¹⁾ | Min. | Typ. | Max. | Units | Conditions |
| MSP10 | TscL | SCKx Output Low Time (Note 1,2) | Tsck/2 | — | — | ns | — |
| MSP11 | Tsch | SCKx Output High Time (Note 1,2) | Tsck/2 | — | — | ns | — |

Note 1: These parameters are characterized, but not tested in manufacturing.

2: The minimum clock period for SCKx is 40 ns. Therefore, the clock generated in Master mode must not violate this specification.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE 31-8: SPIx MODULE SLAVE MODE (CKE = 0) TIMING REQUIREMENTS

| AC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial $-40^{\circ}\text{C} \leq T_A \leq +105^{\circ}\text{C}$ for V-temp | | | | |
|--------------------|----------|---------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|------|------|-------|------------|
| Param. No. | Symbol | Characteristics | Min. | Typ. | Max. | Units | Conditions |
| MSP70 | TsCL | SCKx Input Low Time (Note 1,2) | $T_{SCK}/2$ | — | — | ns | — |
| MSP71 | TsCH | SCKx Input High Time (Note 1,2) | $T_{SCK}/2$ | — | — | ns | — |
| MSP51 | TssH2boZ | $\overline{SSx} \uparrow$ to SDOx Output High-Impedance (Note 2) | 5 | — | 25 | ns | — |

Note 1: These parameters are characterized, but not tested in manufacturing.

2: The minimum clock period for SCKx is 40 ns.

TABLE 31-9: SPIx MODULE SLAVE MODE (CKE = 1) TIMING REQUIREMENTS

| AC CHARACTERISTICS | | | Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature $-40^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$ for Industrial | | | | |
|--------------------|--------|------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------|---------|------|-------|------------|
| Param. No. | Symbol | Characteristics | Min. | Typical | Max. | Units | Conditions |
| SP70 | TsCL | SCKx Input Low Time (Note 1,2) | $T_{SCK}/2$ | — | — | ns | — |
| SP71 | TsCH | SCKx Input High Time (Note 1,2) | $T_{SCK}/2$ | — | — | ns | — |

Note 1: These parameters are characterized, but not tested in manufacturing.

2: The minimum clock period for SCKx is 40 ns.

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

NOTES:

32.0 DC AND AC DEVICE CHARACTERISTICS GRAPHS

Note: The graphs provided following this note are a statistical summary based on a limited number of samples and are provided for design guidance purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore, outside the warranted range.

FIGURE 32-1: I/O OUTPUT VOLTAGE HIGH (VOH)

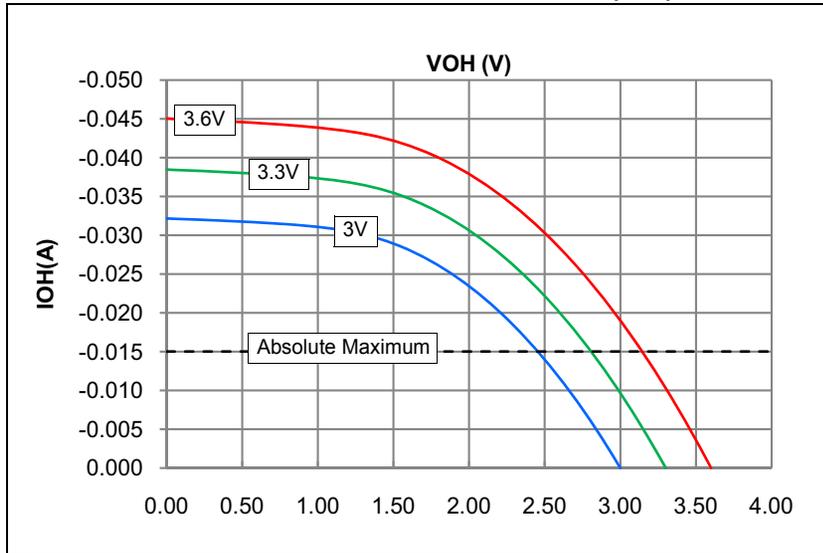


FIGURE 32-2: I/O OUTPUT VOLTAGE LOW (VOL)

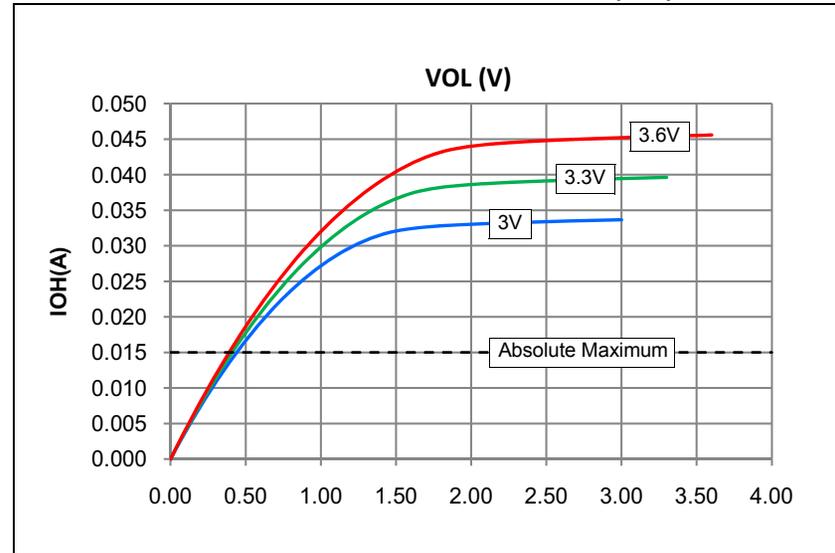


FIGURE 32-3: TYPICAL I_{PD} CURRENT @ V_{DD} = 3.3V

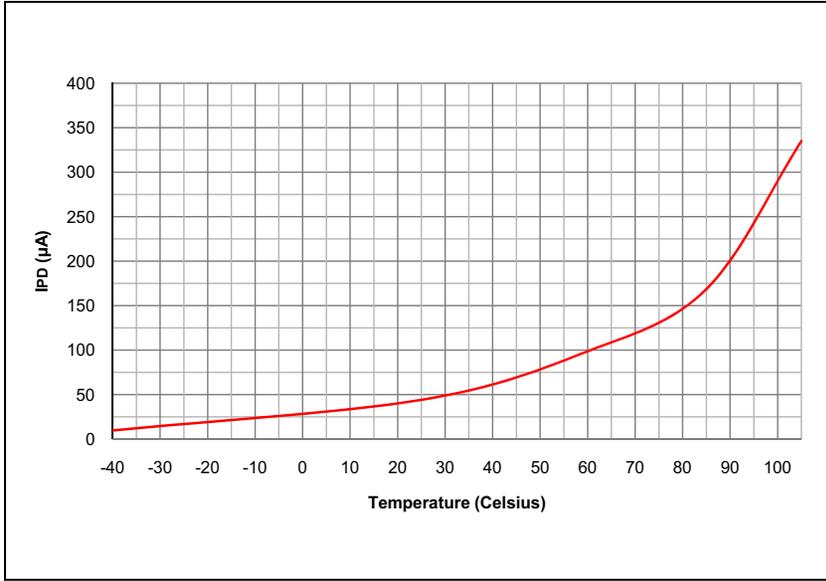


FIGURE 32-5: TYPICAL I_{IDLE} CURRENT @ V_{DD} = 3.3V

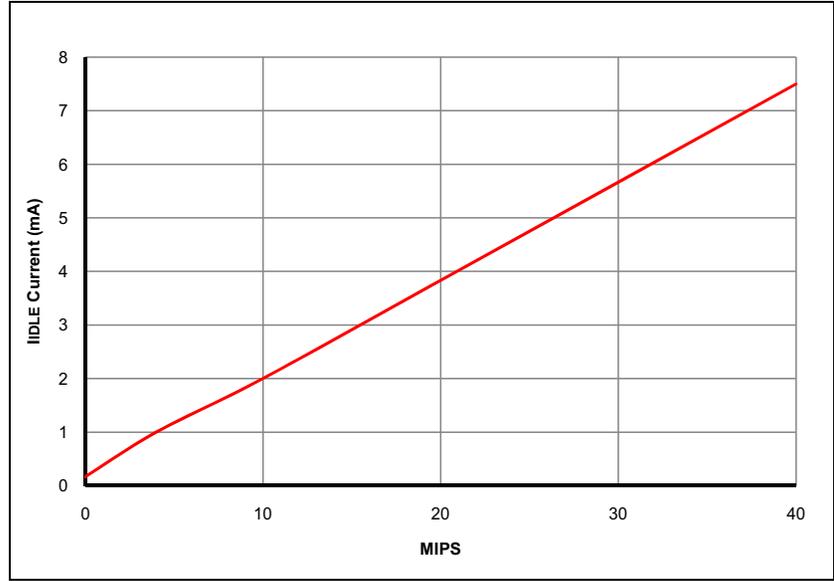


FIGURE 32-4: TYPICAL I_{DD} CURRENT @ V_{DD} = 3.3V

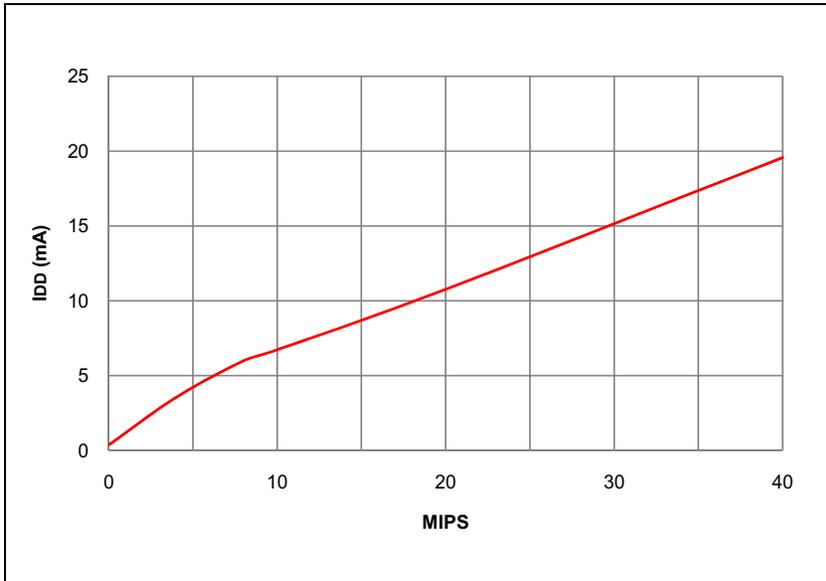


FIGURE 32-6: TYPICAL FRC FREQUENCY @ V_{DD} = 3.3V

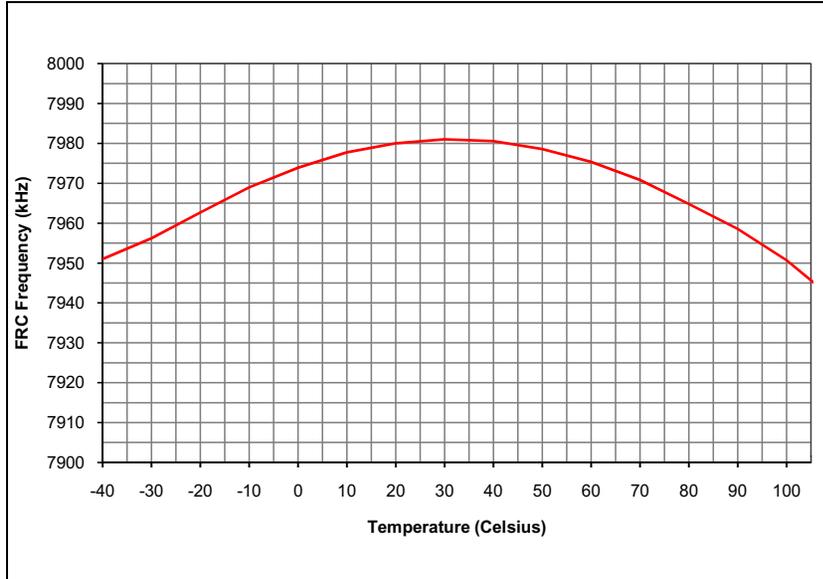


FIGURE 32-7: TYPICAL LPRC FREQUENCY @ V_{DD} = 3.3V

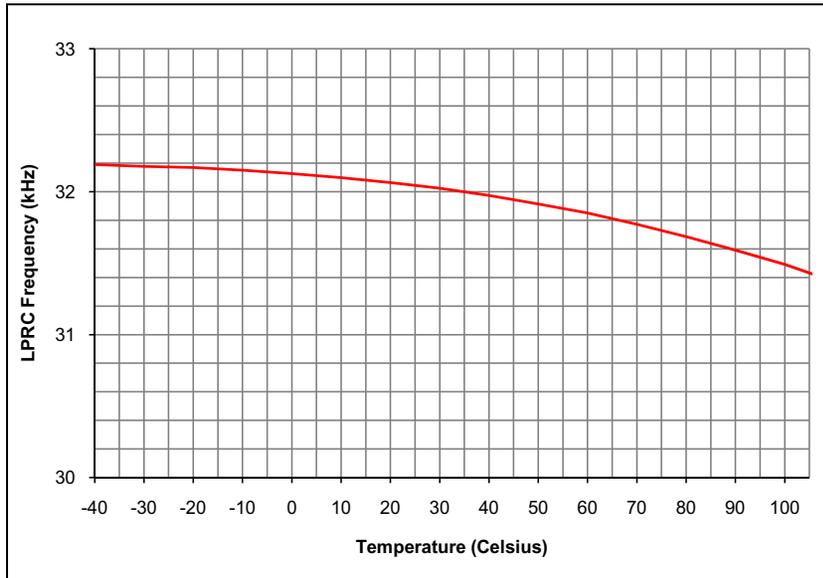
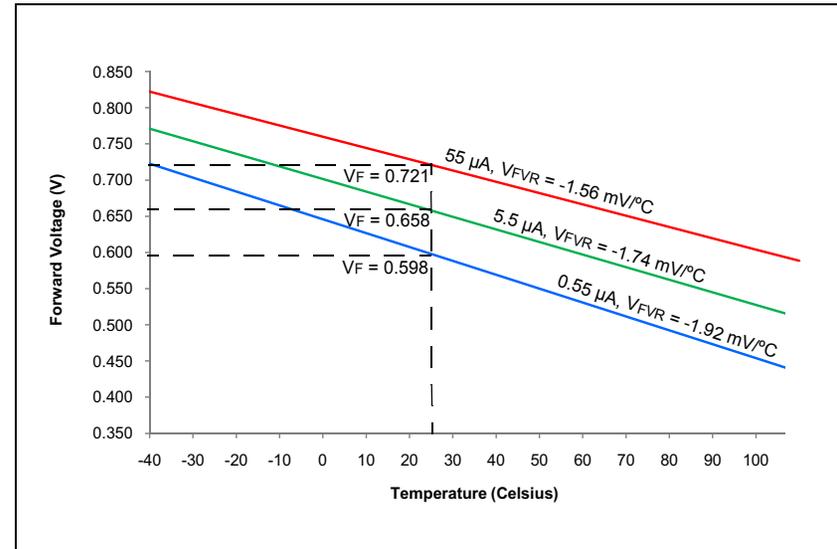


FIGURE 32-8: TYPICAL CTMU TEMPERATURE DIODE FORWARD VOLTAGE



PIC32MX1XX/2XX 28/36/44-PIN FAMILY

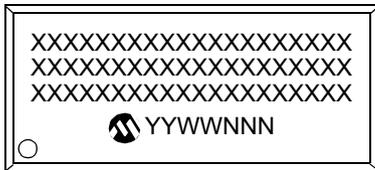
NOTES:

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

33.0 PACKAGING INFORMATION

33.1 Package Marking Information

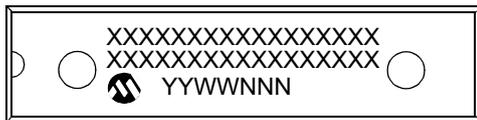
28-Lead SOIC



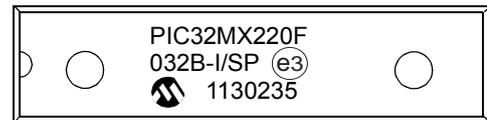
Example



28-Lead SPDIP



Example



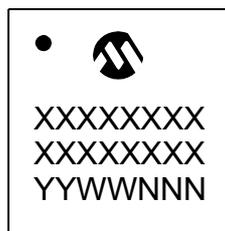
28-Lead SSOP



Example



28-Lead QFN



Example



| | | |
|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|--------|--------------------------------------------------------------------------------------------------------------------|
| Legend: | XX...X | Customer-specific information |
| | Y | Year code (last digit of calendar year) |
| | YY | Year code (last 2 digits of calendar year) |
| | WW | Week code (week of January 1 is week '01') |
| | NNN | Alphanumeric traceability code |
| | (e3) | Pb-free JEDEC designator for Matte Tin (Sn) |
| | * | This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package. |
| Note: If the full Microchip part number cannot be marked on one line, it is carried over to the next line, thus limiting the number of available characters for customer-specific information. | | |

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

33.1 Package Marking Information (Continued)

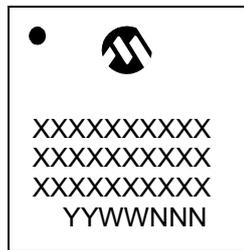
36-Lead VTLA



Example



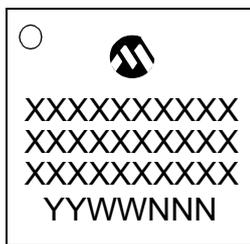
44-Lead VTLA



Example



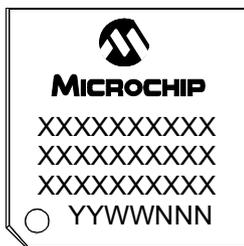
44-Lead QFN



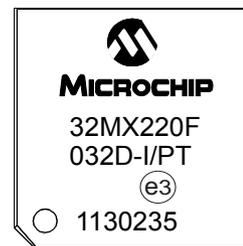
Example



44-Lead TQFP



Example



| | | |
|----------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|----------------------------------------------------------------------------------------------------------------------|
| Legend: | XX...X | Customer-specific information |
| | Y | Year code (last digit of calendar year) |
| | YY | Year code (last 2 digits of calendar year) |
| | WW | Week code (week of January 1 is week '01') |
| | NNN | Alphanumeric traceability code |
| | (e3) | Pb-free JEDEC designator for Matte Tin (Sn) |
| | * (e3) | This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package. |
| Note: | If the full Microchip part number cannot be marked on one line, it is carried over to the next line, thus limiting the number of available characters for customer-specific information. | |

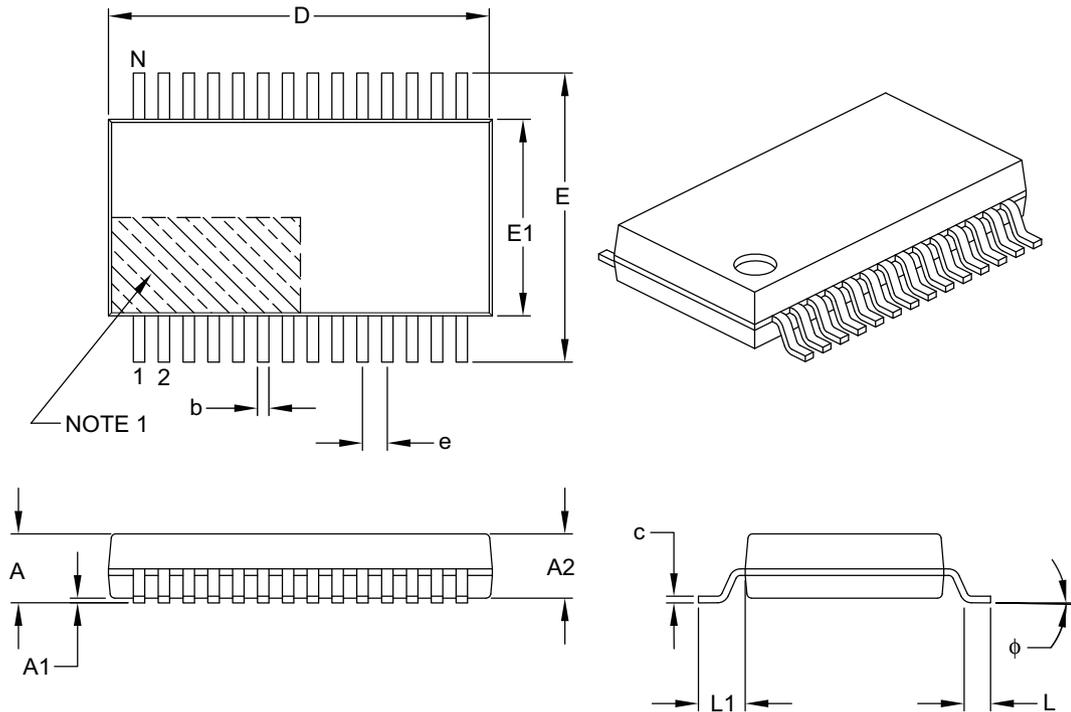
PIC32MX1XX/2XX 28/36/44-PIN FAMILY

33.2 Package Details

This section provides the technical details of the packages.

28-Lead Plastic Shrink Small Outline (SS) – 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| | | Units | MILLIMETERS | | |
|--------------------------|--------|-------|-------------|-------|-------|
| Dimension Limits | | | MIN | NOM | MAX |
| Number of Pins | N | | 28 | | |
| Pitch | e | | 0.65 BSC | | |
| Overall Height | A | – | – | – | 2.00 |
| Molded Package Thickness | A2 | | 1.65 | 1.75 | 1.85 |
| Standoff | A1 | | 0.05 | – | – |
| Overall Width | E | | 7.40 | 7.80 | 8.20 |
| Molded Package Width | E1 | | 5.00 | 5.30 | 5.60 |
| Overall Length | D | | 9.90 | 10.20 | 10.50 |
| Foot Length | L | | 0.55 | 0.75 | 0.95 |
| Footprint | L1 | | 1.25 REF | | |
| Lead Thickness | c | | 0.09 | – | 0.25 |
| Foot Angle | ϕ | | 0° | 4° | 8° |
| Lead Width | b | | 0.22 | – | 0.38 |

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.20 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

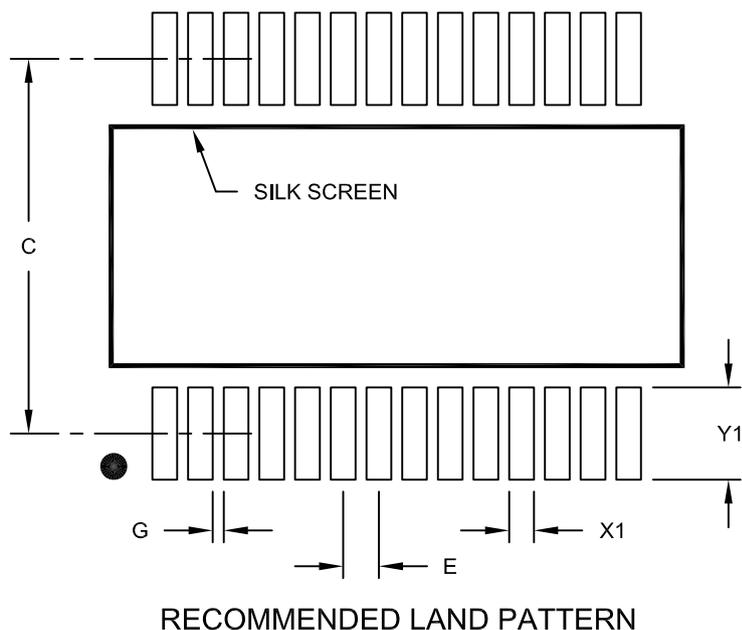
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-073B

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

28-Lead Plastic Shrink Small Outline (SS) - 5.30 mm Body [SSOP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| | | Units | MILLIMETERS | | |
|--------------------------|----|-------|-------------|------|------|
| Dimension Limits | | | MIN | NOM | MAX |
| Contact Pitch | E | | 0.65 BSC | | |
| Contact Pad Spacing | C | | | 7.20 | |
| Contact Pad Width (X28) | X1 | | | | 0.45 |
| Contact Pad Length (X28) | Y1 | | | | 1.75 |
| Distance Between Pads | G | 0.20 | | | |

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

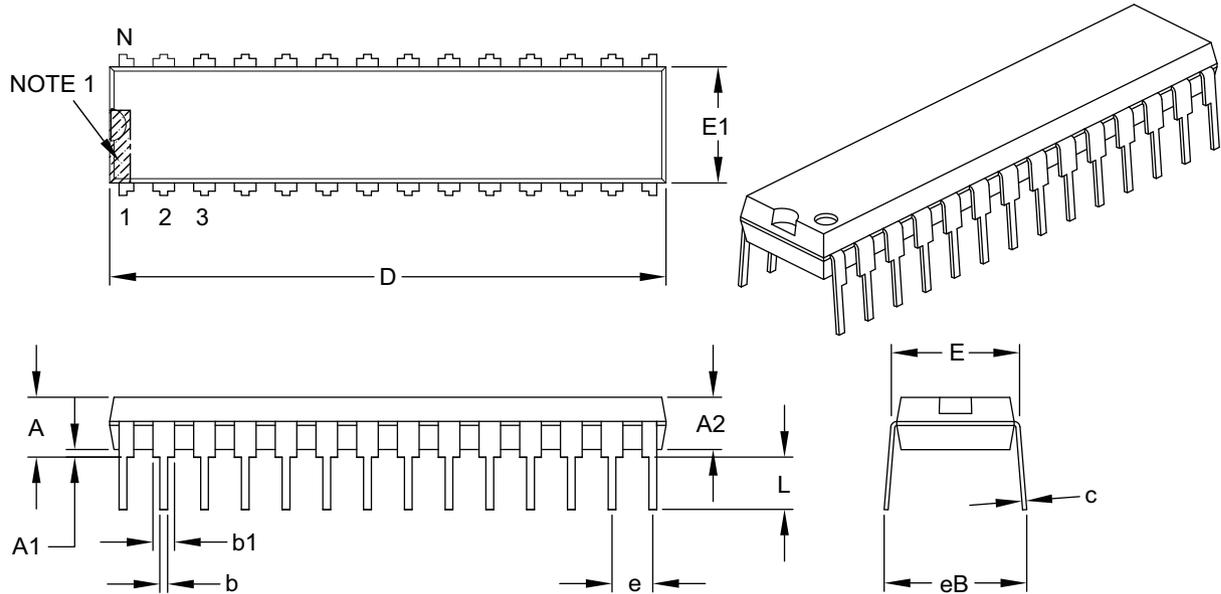
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2073A

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

28-Lead Skinny Plastic Dual In-Line (SP) – 300 mil Body [SPDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packages>



| Dimension Limits | Units | INCHES | | |
|----------------------------|-------|----------|-------|-------|
| | | MIN | NOM | MAX |
| Number of Pins | N | 28 | | |
| Pitch | e | .100 BSC | | |
| Top to Seating Plane | A | – | – | .200 |
| Molded Package Thickness | A2 | .120 | .135 | .150 |
| Base to Seating Plane | A1 | .015 | – | – |
| Shoulder to Shoulder Width | E | .290 | .310 | .335 |
| Molded Package Width | E1 | .240 | .285 | .295 |
| Overall Length | D | 1.345 | 1.365 | 1.400 |
| Tip to Seating Plane | L | .110 | .130 | .150 |
| Lead Thickness | c | .008 | .010 | .015 |
| Upper Lead Width | b1 | .040 | .050 | .070 |
| Lower Lead Width | b | .014 | .018 | .022 |
| Overall Row Spacing § | eB | – | – | .430 |

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic.
- Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
- Dimensioning and tolerancing per ASME Y14.5M.

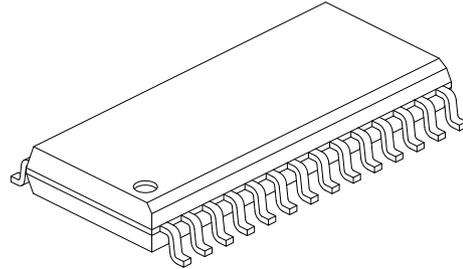
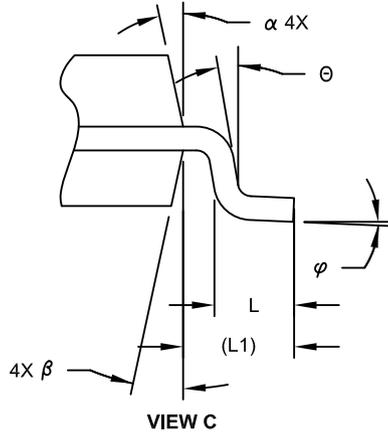
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-070B

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| Dimension Limits | Units | MILLIMETERS | | |
|--------------------------|-----------|-------------|-----|------|
| | | MIN | NOM | MAX |
| Number of Pins | N | 28 | | |
| Pitch | e | 1.27 BSC | | |
| Overall Height | A | - | - | 2.65 |
| Molded Package Thickness | A2 | 2.05 | - | - |
| Standoff § | A1 | 0.10 | - | 0.30 |
| Overall Width | E | 10.30 BSC | | |
| Molded Package Width | E1 | 7.50 BSC | | |
| Overall Length | D | 17.90 BSC | | |
| Chamfer (Optional) | h | 0.25 | - | 0.75 |
| Foot Length | L | 0.40 | - | 1.27 |
| Footprint | L1 | 1.40 REF | | |
| Lead Angle | Θ | 0° | - | - |
| Foot Angle | φ | 0° | - | 8° |
| Lead Thickness | c | 0.18 | - | 0.33 |
| Lead Width | b | 0.31 | - | 0.51 |
| Mold Draft Angle Top | α | 5° | - | 15° |
| Mold Draft Angle Bottom | β | 5° | - | 15° |

Notes:

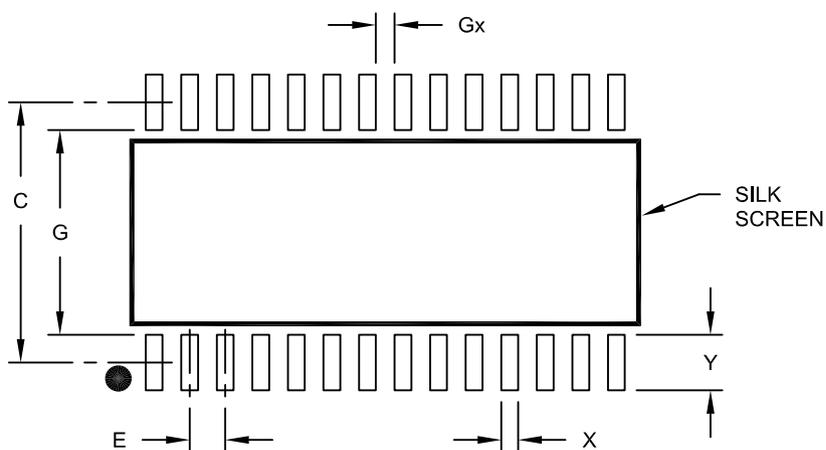
- Pin 1 visual index feature may vary, but must be located within the hatched area.
- § Significant Characteristic
- Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 REF: Reference Dimension, usually without tolerance, for information purposes only.
- Datums A & B to be determined at Datum H.

Microchip Technology Drawing C04-052C Sheet 2 of 2

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

| Dimension Limits | Units | MILLIMETERS | | |
|--------------------------|-------|-------------|------|------|
| | | MIN | NOM | MAX |
| Contact Pitch | E | 1.27 BSC | | |
| Contact Pad Spacing | C | | 9.40 | |
| Contact Pad Width (X28) | X | | | 0.60 |
| Contact Pad Length (X28) | Y | | | 2.00 |
| Distance Between Pads | Gx | 0.67 | | |
| Distance Between Pads | G | 7.40 | | |

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

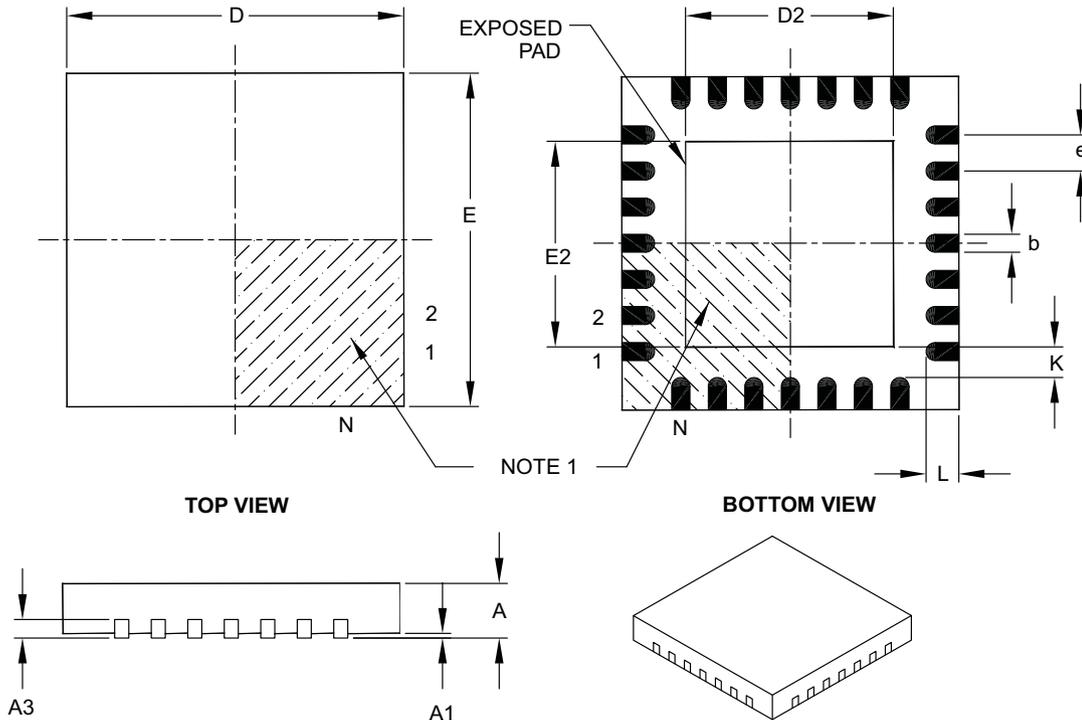
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

28-Lead Plastic Quad Flat, No Lead Package (ML) – 6x6 mm Body [QFN] with 0.55 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| Dimension Limits | Units | MILLIMETERS | | |
|------------------------|-------|-------------|------|------|
| | | MIN | NOM | MAX |
| Number of Pins | N | 28 | | |
| Pitch | e | 0.65 BSC | | |
| Overall Height | A | 0.80 | 0.90 | 1.00 |
| Standoff | A1 | 0.00 | 0.02 | 0.05 |
| Contact Thickness | A3 | 0.20 REF | | |
| Overall Width | E | 6.00 BSC | | |
| Exposed Pad Width | E2 | 3.65 | 3.70 | 4.20 |
| Overall Length | D | 6.00 BSC | | |
| Exposed Pad Length | D2 | 3.65 | 3.70 | 4.20 |
| Contact Width | b | 0.23 | 0.30 | 0.35 |
| Contact Length | L | 0.50 | 0.55 | 0.70 |
| Contact-to-Exposed Pad | K | 0.20 | – | – |

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

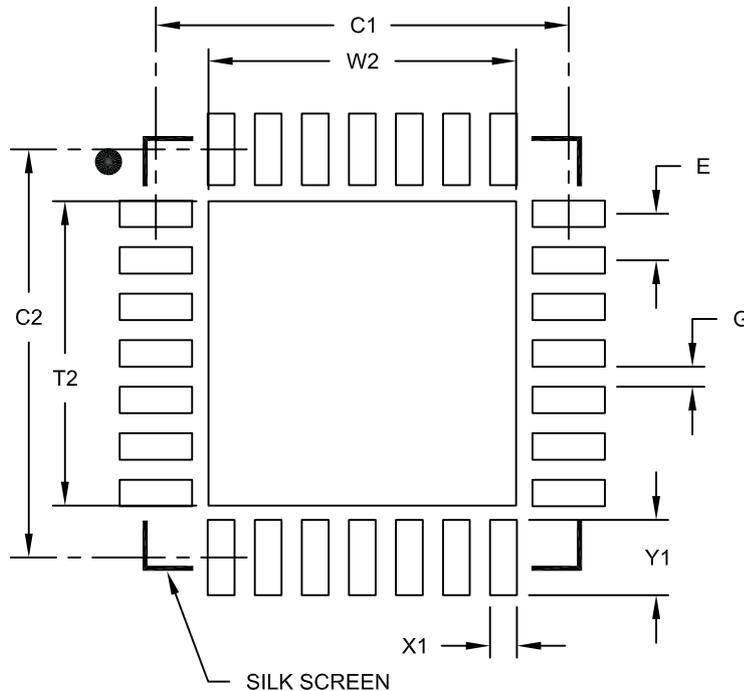
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-105B

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

28-Lead Plastic Quad Flat, No Lead Package (ML) – 6x6 mm Body [QFN] with 0.55 mm Contact Length

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

| Dimension Limits | Units | MILLIMETERS | | |
|----------------------------|-------|-------------|------|------|
| | | MIN | NOM | MAX |
| Contact Pitch | E | 0.65 BSC | | |
| Optional Center Pad Width | W2 | | | 4.25 |
| Optional Center Pad Length | T2 | | | 4.25 |
| Contact Pad Spacing | C1 | | 5.70 | |
| Contact Pad Spacing | C2 | | 5.70 | |
| Contact Pad Width (X28) | X1 | | | 0.37 |
| Contact Pad Length (X28) | Y1 | | | 1.00 |
| Distance Between Pads | G | 0.20 | | |

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

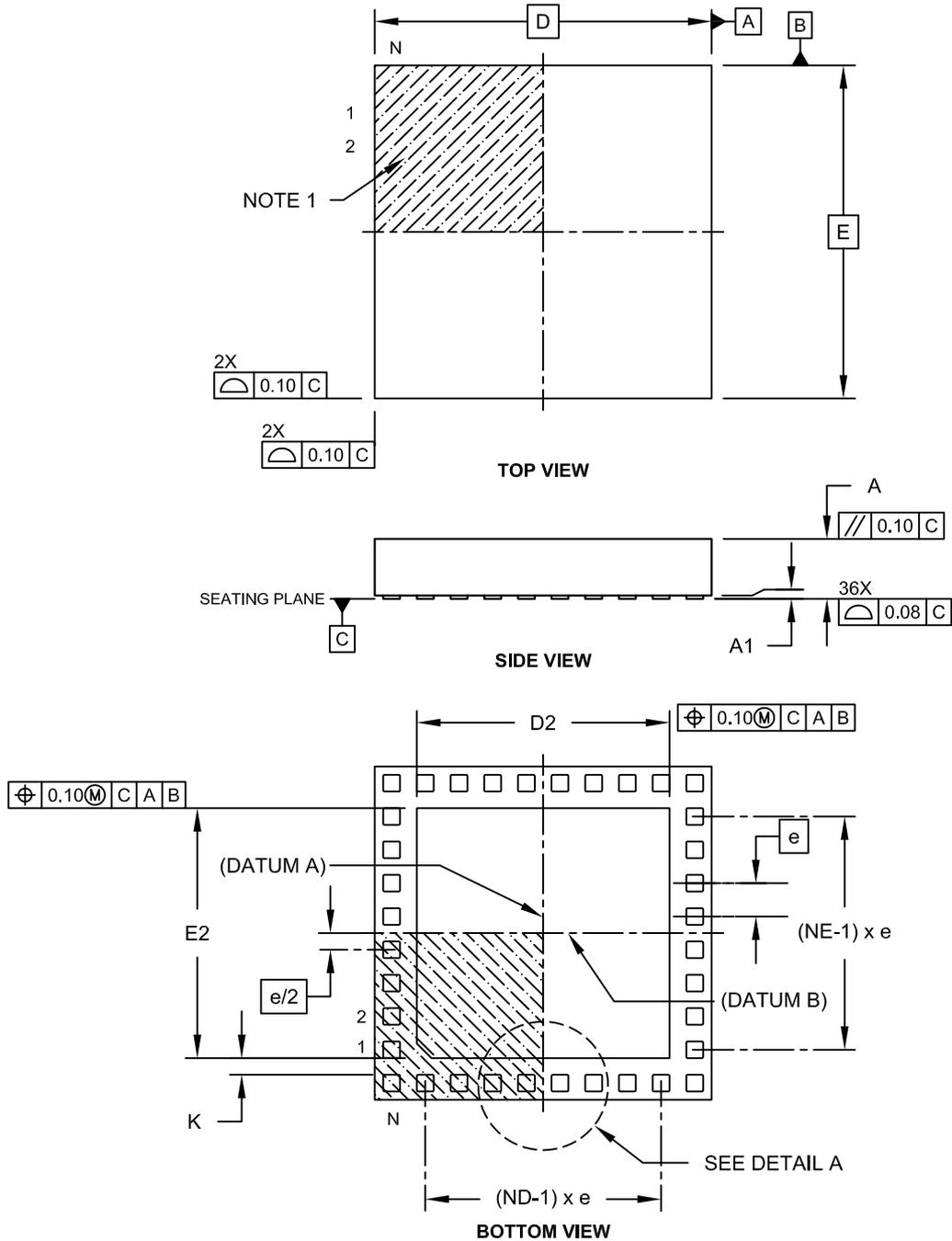
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2105A

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

36-Terminal Very Thin Thermal Leadless Array Package (TL) – 5x5x0.9 mm Body with Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

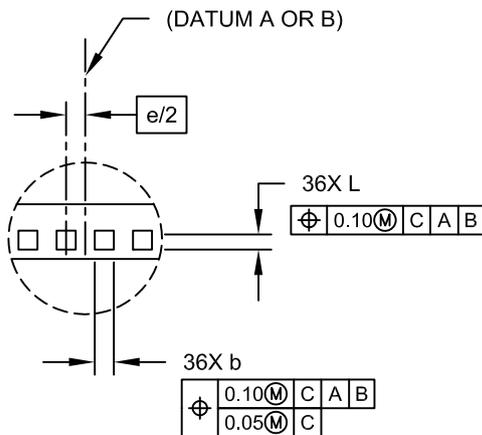


Microchip Technology Drawing C04-187C Sheet 1 of 2

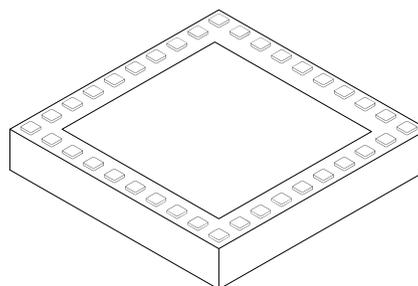
PIC32MX1XX/2XX 28/36/44-PIN FAMILY

36-Terminal Very Thin Thermal Leadless Array Package (TL) – 5x5x0.9 mm Body with Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



DETAIL A



| Dimension | Units | MILLIMETERS | | |
|-------------------------|--------|-------------|------|-------|
| | Limits | MIN | NOM | MAX |
| Number of Pins | N | 36 | | |
| Number of Pins per Side | ND | 10 | | |
| Number of Pins per Side | NE | 8 | | |
| Pitch | e | 0.50 BSC | | |
| Overall Height | A | 0.80 | 0.90 | 1.00 |
| Standoff | A1 | 0.025 | - | 0.075 |
| Overall Width | E | 5.00 BSC | | |
| Exposed Pad Width | E2 | 3.60 | 3.75 | 3.90 |
| Overall Length | D | 5.00 BSC | | |
| Exposed Pad Length | D2 | 3.60 | 3.75 | 3.90 |
| Contact Width | b | 0.20 | 0.25 | 0.30 |
| Contact Length | L | 0.20 | 0.25 | 0.30 |
| Contact-to-Exposed Pad | K | 0.20 | - | - |

Notes:

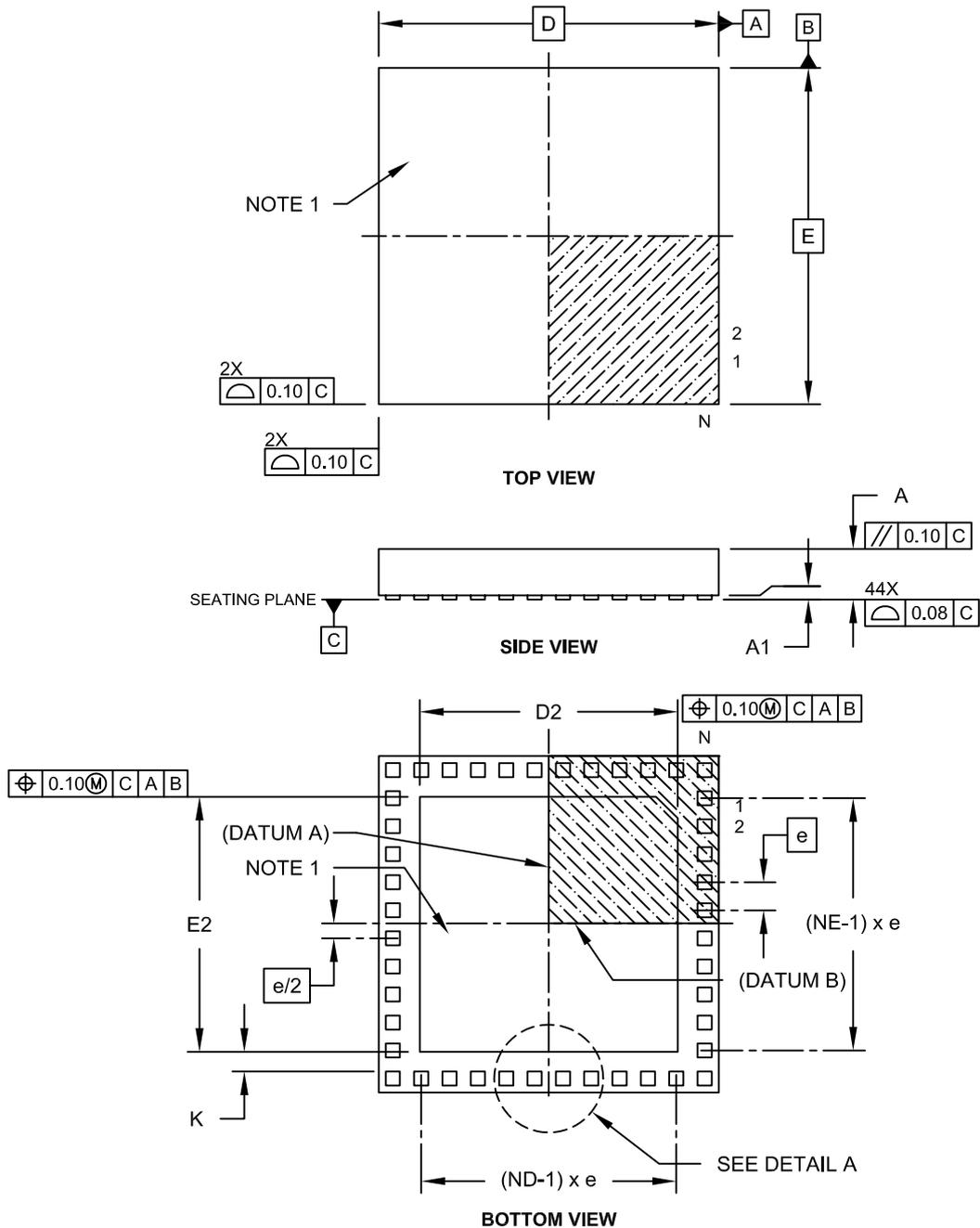
- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated.
- Dimensioning and tolerancing per ASME Y14.5M.
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-187C Sheet 2 of 2

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

44-Terminal Very Thin Leadless Array Package (TL) – 6x6x0.9 mm Body With Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

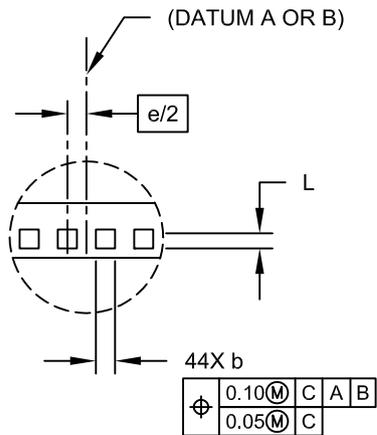


Microchip Technology Drawing C04-157C Sheet 1 of 2

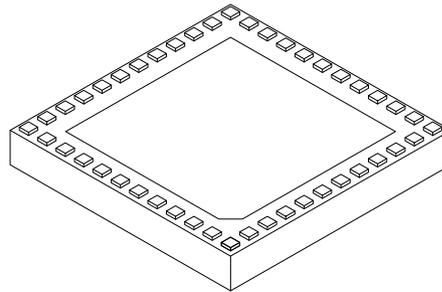
PIC32MX1XX/2XX 28/36/44-PIN FAMILY

44-Terminal Very Thin Leadless Array Package (TL) – 6x6x0.9 mm Body With Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



DETAIL A



| Dimension | Units Limits | MILLIMETERS | | |
|-------------------------|-----------------|-------------|------|-------|
| | | MIN | NOM | MAX |
| Number of Pins | N | 44 | | |
| Number of Pins per Side | ND | 12 | | |
| Number of Pins per Side | NE | 10 | | |
| Pitch | e | 0.50 BSC | | |
| Overall Height | A | 0.80 | 0.90 | 1.00 |
| Standoff | A1 | 0.025 | - | 0.075 |
| Overall Width | E | 6.00 BSC | | |
| Exposed Pad Width | E2 | 4.40 | 4.55 | 4.70 |
| Overall Length | D | 6.00 BSC | | |
| Exposed Pad Length | D2 | 4.40 | 4.55 | 4.70 |
| Contact Width | b | 0.20 | 0.25 | 0.30 |
| Contact Length | L | 0.20 | 0.25 | 0.30 |
| Contact-to-Exposed Pad | K | 0.20 | - | - |

Notes:

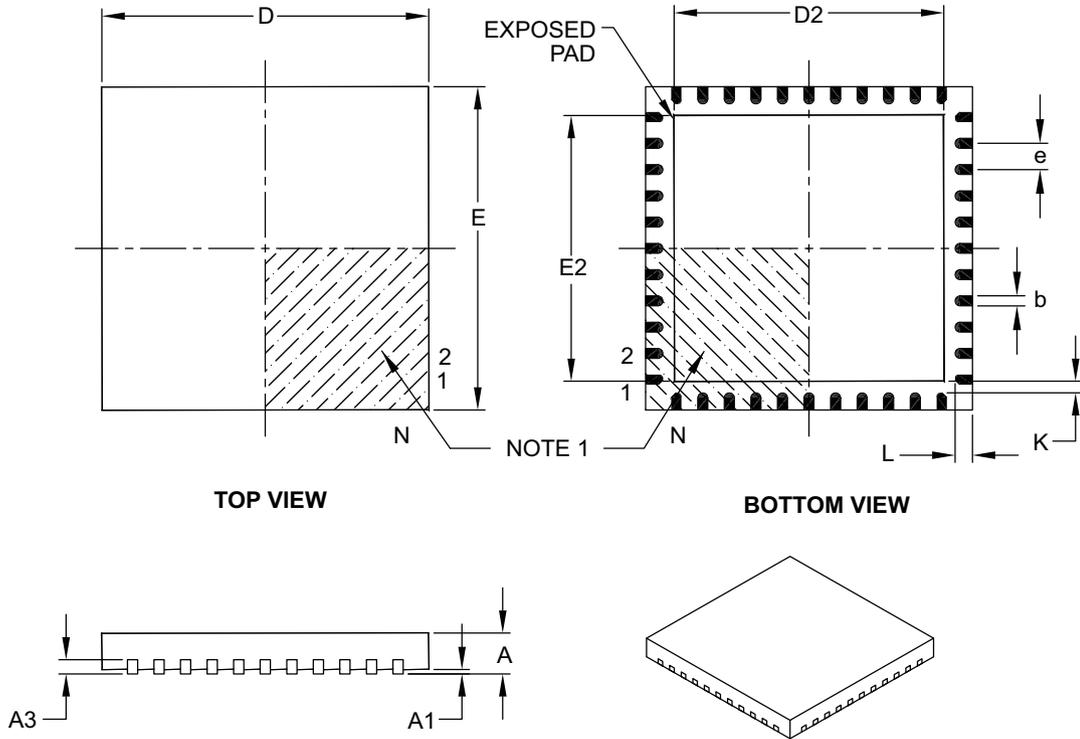
- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated.
- Dimensioning and tolerancing per ASME Y14.5M.
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-157C Sheet 2 of 2

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

44-Lead Plastic Quad Flat, No Lead Package (ML) – 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| Dimension Limits | Units | MILLIMETERS | | |
|------------------------|-------|-------------|------|------|
| | | MIN | NOM | MAX |
| Number of Pins | N | 44 | | |
| Pitch | e | 0.65 BSC | | |
| Overall Height | A | 0.80 | 0.90 | 1.00 |
| Standoff | A1 | 0.00 | 0.02 | 0.05 |
| Contact Thickness | A3 | 0.20 REF | | |
| Overall Width | E | 8.00 BSC | | |
| Exposed Pad Width | E2 | 6.30 | 6.45 | 6.80 |
| Overall Length | D | 8.00 BSC | | |
| Exposed Pad Length | D2 | 6.30 | 6.45 | 6.80 |
| Contact Width | b | 0.25 | 0.30 | 0.38 |
| Contact Length | L | 0.30 | 0.40 | 0.50 |
| Contact-to-Exposed Pad | K | 0.20 | – | – |

Notes:

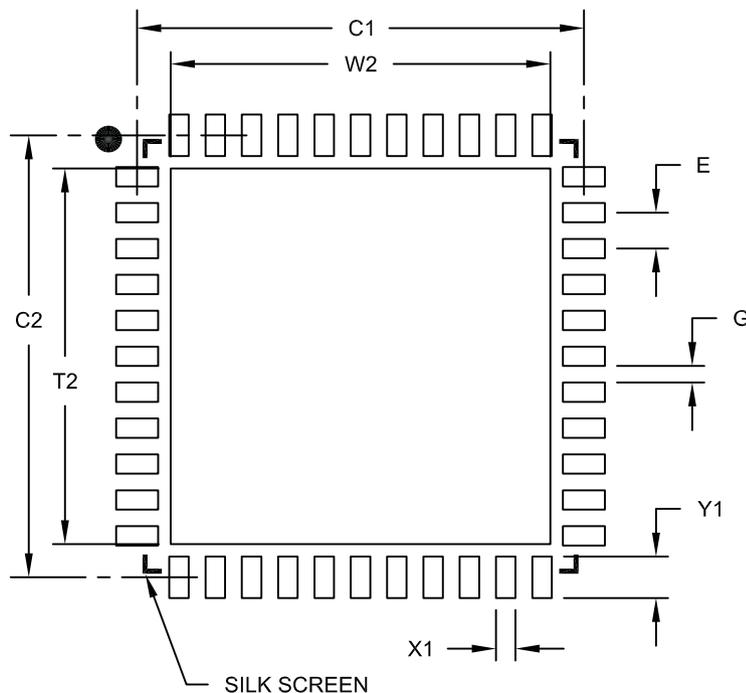
- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Package is saw singulated.
- Dimensioning and tolerancing per ASME Y14.5M.
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-103B

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

44-Lead Plastic Quad Flat, No Lead Package (ML) – 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

| Dimension Limits | Units | MILLIMETERS | | |
|----------------------------|-------|-------------|------|------|
| | | MIN | NOM | MAX |
| Contact Pitch | E | 0.65 BSC | | |
| Optional Center Pad Width | W2 | | | 6.80 |
| Optional Center Pad Length | T2 | | | 6.80 |
| Contact Pad Spacing | C1 | | 8.00 | |
| Contact Pad Spacing | C2 | | 8.00 | |
| Contact Pad Width (X44) | X1 | | | 0.35 |
| Contact Pad Length (X44) | Y1 | | | 0.80 |
| Distance Between Pads | G | 0.25 | | |

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

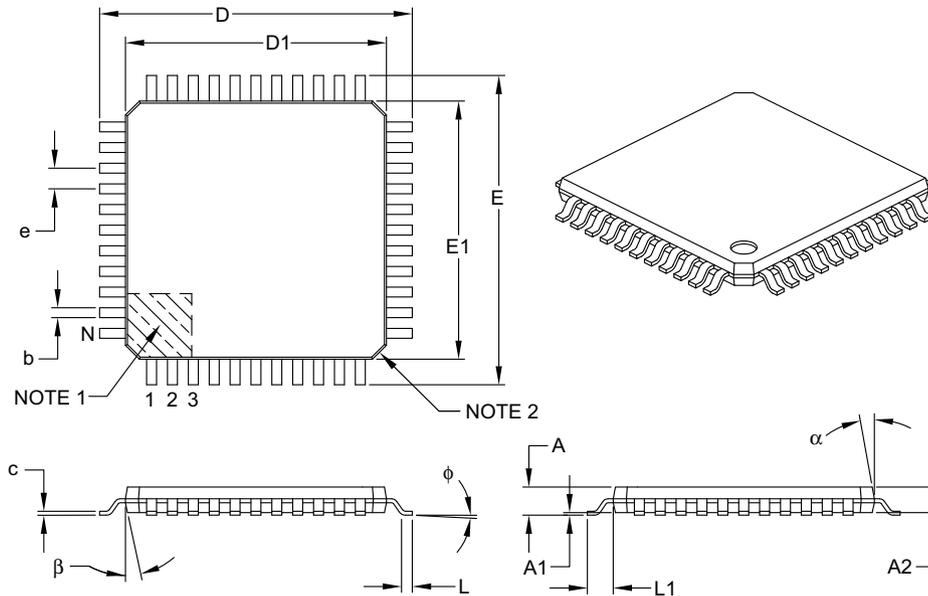
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2103A

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

44-Lead Plastic Thin Quad Flatpack (PT) – 10x10x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



| Dimension Limits | Units | MILLIMETERS | | |
|--------------------------|----------|-------------|------|------|
| | | MIN | NOM | MAX |
| Number of Leads | N | 44 | | |
| Lead Pitch | e | 0.80 BSC | | |
| Overall Height | A | – | – | 1.20 |
| Molded Package Thickness | A2 | 0.95 | 1.00 | 1.05 |
| Standoff | A1 | 0.05 | – | 0.15 |
| Foot Length | L | 0.45 | 0.60 | 0.75 |
| Footprint | L1 | 1.00 REF | | |
| Foot Angle | ϕ | 0° | 3.5° | 7° |
| Overall Width | E | 12.00 BSC | | |
| Overall Length | D | 12.00 BSC | | |
| Molded Package Width | E1 | 10.00 BSC | | |
| Molded Package Length | D1 | 10.00 BSC | | |
| Lead Thickness | c | 0.09 | – | 0.20 |
| Lead Width | b | 0.30 | 0.37 | 0.45 |
| Mold Draft Angle Top | α | 11° | 12° | 13° |
| Mold Draft Angle Bottom | β | 11° | 12° | 13° |

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Chamfers at corners are optional; size may vary.
- Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

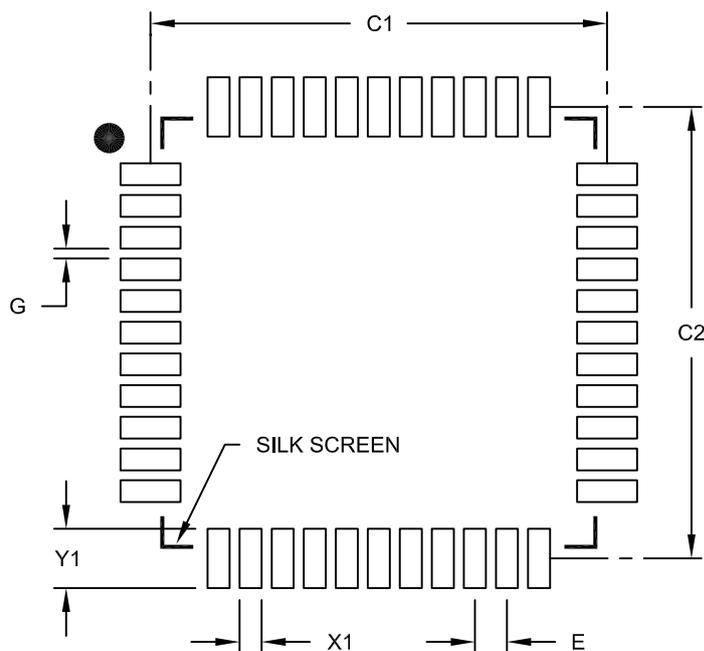
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-076B

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

44-Lead Plastic Thin Quad Flatpack (PT) 10X10X1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

| Dimension Limits | Units | MILLIMETERS | | |
|--------------------------|-------|-------------|-------|------|
| | | MIN | NOM | MAX |
| Contact Pitch | E | 0.80 BSC | | |
| Contact Pad Spacing | C1 | | 11.40 | |
| Contact Pad Spacing | C2 | | 11.40 | |
| Contact Pad Width (X44) | X1 | | | 0.55 |
| Contact Pad Length (X44) | Y1 | | | 1.50 |
| Distance Between Pads | G | 0.25 | | |

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2076B

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

APPENDIX A: REVISION HISTORY

Revision A (May 2011)

This is the initial released version of this document.

Revision B (October 2011)

The following two global changes are included in this revision:

- All packaging references to VLAP have been changed to VTLA throughout the document
- All references to VCORE have been removed
- All occurrences of the ASCL1, ASCL2, ASDA1, and ASDA2 pins have been removed
- V-temp temperature range (-40°C to +105°C) was added to all electrical specification tables

This revision includes the addition of the following devices:

- PIC32MX130F064B
- PIC32MX130F064C
- PIC32MX130F064D
- PIC32MX150F128B
- PIC32MX150F128C
- PIC32MX150F128D
- PIC32MX230F064B
- PIC32MX230F064C
- PIC32MX230F064D
- PIC32MX250F128B
- PIC32MX250F128C
- PIC32MX250F128D

Text and formatting changes were incorporated throughout the document.

All other major changes are referenced by their respective section in [Table A-1](#).

TABLE A-1: MAJOR SECTION UPDATES

| Section | Update Description |
|----------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| “32-bit Microcontrollers (up to 128 KB Flash and 32 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog” | <p>Split the existing Features table into two: PIC32MX1XX General Purpose Family Features (Table 1) and PIC32MX2XX USB Family Features (Table 2).</p> <p>Added the SPDIP package reference (see Table 1, Table 2, and “Pin Diagrams”).</p> <p>Added the new devices to the applicable pin diagrams.</p> <p>Changed PGED2 to PGED1 on pin 35 of the 36-pin VTLA diagram for PIC32MX220F032C, PIC32MX220F016C, PIC32MX230F064C, and PIC32MX250F128C devices.</p> |
| 1.0 “Device Overview” | <p>Added the SPDIP package reference and updated the pin number for AN12 for 44-pin QFN devices in the Pinout I/O Descriptions (see Table 1-1).</p> <p>Added the PGEC4/PGED4 pin pair and updated the C1INA-C1IND and C2INA-C2IND pin numbers for 28-pin SSOP/SPDIP/SOIC devices in the Pinout I/O Descriptions (see Table 1-1).</p> |
| 2.0 “Guidelines for Getting Started with 32-bit Microcontrollers” | <p>Updated the Recommended Minimum Connection diagram (see Figure 2-1).</p> |

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE A-1: MAJOR SECTION UPDATES (CONTINUED)

| Section | Update Description |
|--------------------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 4.0 “Memory Organization” | <p>Added Memory Maps for the new devices (see Figure 4-3 and Figure 4-4).</p> <p>Removed the BMXCHEDMA bit from the Bus Matrix Register map (see Table 4-1).</p> <p>Added the REFOTRIM register, added the DIVSWEN bit to the REFOCON registers, added Note 4 to the ULOCK and SOSSEN bits and added the PBDIVRDY bit in the OSCCON register in the in the System Control Register map (see Table 4-16).</p> <p>Removed the ALTI2C1 and ALTI2C2 bits from the DEVCFG3 register and added Note 1 to the UPLEN and UPLLIDIV<2:0> bits of the DEVCFG2 register in the Device Configuration Word Summary (see Table 4-17).</p> <p>Updated Note 1 in the Device and Revision ID Summary (see Table 4-18).</p> <p>Added Note 2 to the PORTA Register map (see Table 4-19).</p> <p>Added the ANSB6 and ANSB12 bits to the ANSELB register in the PORTB Register map (see Table 4-20).</p> <p>Added Notes 2 and 3 to the PORTC Register map (see Table 4-21).</p> <p>Updated all register names in the Peripheral Pin Select Register map (see Table 4-23).</p> <p>Added values in support of new devices (16 KB RAM and 32 KB RAM) in the Data RAM Size register (see Register 4-5).</p> <p>Added values in support of new devices (64 KB Flash and 128 KB Flash) in the Data RAM Size register (see Register 4-5).</p> |
| 8.0 “Oscillator Configuration” | <p>Added Note 5 to the PIC32MX1XX/2XX Family Clock Diagram (see Figure 8-1).</p> <p>Added the PBDIVRDY bit and Note 2 to the Oscillator Control register (see Register 8-1).</p> <p>Added the DIVSWEN bit and Note 3 to the Reference Oscillator Control register (see Register 8-3).</p> <p>Added the REFOTRIM register (see Register 8-4).</p> |
| 21.0 “10-bit Analog-to-Digital Converter (ADC)” | <p>Updated the ADC1 Module Block Diagram (see Figure 21-1).</p> <p>Updated the Notes in the ADC Input Select register (see Register 21-4).</p> |
| 24.0 “Charge Time Measurement Unit (CTMU)” | <p>Updated the CTMU Block Diagram (see Figure 24-1).</p> <p>Added Note 3 to the CTMU Control register (see Register 24-1)</p> |
| 26.0 “Special Features” | <p>Added Note 1 and the PGEC4/PGED4 pin pair to the ICESSEL<1:0> bits in DEVCFG0: Device Configuration Word 0 (see Register 26-1).</p> <p>Removed the ALTI2C1 and ALTI2C2 bits from the Device Configuration Word 3 register (see Register 26-4).</p> <p>Removed 26.3.3 “Power-up Requirements”.</p> <p>Added Note 3 to the Connections for the On-Chip Regulator diagram (see Figure 26-2).</p> <p>Updated the Block Diagram of Programming, Debugging and Trace Ports diagram (see Figure 26-3).</p> |

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

TABLE A-1: MAJOR SECTION UPDATES (CONTINUED)

| Section | Update Description |
|------------------------------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 29.0 “Electrical Characteristics” | <p>Updated the Absolute Maximum Ratings (removed Voltage on V_{CORE} with respect to V_{SS}).</p> <p>Added the SPDIP specification to the Thermal Packaging Characteristics (see Table 29-2).</p> <p>Updated the Typical values for parameters DC20-DC24 in the Operating Current (I_{DD}) specification (see Table 29-5).</p> <p>Updated the Typical values for parameters DC30a-DC34a in the Idle Current (I_{IDLE}) specification (see Table 29-6).</p> <p>Updated the Typical values for parameters DC40i and DC40n and removed parameter DC40m in the Power-down Current (I_{PD}) specification (see Table 29-7).</p> <p>Removed parameter D320 (V_{CORE}) from the Internal Voltage Regulator Specifications and updated the Comments (see Table 29-13).</p> <p>Updated the Minimum, Typical, and Maximum values for parameter F20b in the Internal FRC Accuracy specification (see Table 29-17).</p> <p>Removed parameter SY01 (TPWRT) and removed all Conditions from Resets Timing (see Table 29-20).</p> <p>Updated all parameters in the CTMU Specifications (see Table 29-39).</p> |
| 31.0 “Packaging Information” | Added the 28-lead SPDIP package diagram information (see 31.1 “Package Marking Information” and 31.2 “Package Details”). |
| “Product Identification System” | Added the SPDIP (SP) package definition. |

Revision C (November 2011)

All major changes are referenced by their respective section in [Table A-2](#).

TABLE A-2: MAJOR SECTION UPDATES

| Section | Update Description |
|----------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| “32-bit Microcontrollers (up to 128 KB Flash and 32 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog” | <p>Revised the source/sink on I/O pins (see “Input/Output” on page 1).</p> <p>Added the SPDIP package to the PIC32MX220F032B device in the PIC32MX2XX USB Family Features (see Table 2).</p> |
| 4.0 “Memory Organization” | Removed ANSB6 from the ANSELB register and added the ODCB6, ODCB10, and ODCB11 bits in the PORTB Register Map (see Table 4-20). |
| 29.0 “Electrical Characteristics” | Updated the minimum value for parameter OS50 in the PLL Clock Timing Specifications (see Table 29-16). |

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

Revision D (February 2012)

All occurrences of VUSB were changed to: VUSB3V3. In addition, text and formatting changes were incorporated throughout the document.

All other major changes are referenced by their respective section in [Table A-3](#).

TABLE A-3: MAJOR SECTION UPDATES

| Section | Update Description |
|----------------------------------------------------------------------------------------------------------------------------|-------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| “32-bit Microcontrollers (up to 128 KB Flash and 32 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog” | Corrected a part number error in all pin diagrams. Updated the DMA Channels (Programmable/Dedicated) column in the PIC32MX1XX General Purpose Family Features (see Table 1). |
| 1.0 “Device Overview” | Added the TQFP and VTLA packages to the 44-pin column heading and updated the pin numbers for the SCL1, SCL2, SDA1, and SDA2 pins in the Pinout I/O Descriptions (see Table 1-1). |
| 7.0 “Interrupt Controller” | Updated the Note that follows the features. Updated the Interrupt Controller Block Diagram (see Figure 7-1). |
| 29.0 “Electrical Characteristics” | Updated the Maximum values for parameters DC20-DC24, and the Minimum value for parameter DC21 in the Operating Current (IDD) DC Characteristics (see Table 29-5). Updated all Minimum and Maximum values for the Idle Current (IIDL) DC Characteristics (see Table 29-6). Updated the Maximum values for parameters DC40k, DC40l, DC40n, and DC40m in the Power-down Current (IPD) DC Characteristics (see Table 29-7). Changed the minimum clock period for SCKx from 40 ns to 50 ns in Note 3 of the SPIx Master and Slave Mode Timing Requirements (see Table 29-26 through Table 29-29). |
| 30.0 “DC and AC Device Characteristics Graphs” | Updated the Typical IIDL Current @ VDD = 3.3V graph (see Figure 30-5). |

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

Revision E (October 2012)

All singular pin diagram occurrences of CVREF were changed to: CVREFOUT. In addition, minor text and formatting changes were incorporated throughout the document.

All major changes are referenced by their respective section in [Table A-4](#).

TABLE A-4: MAJOR SECTION UPDATES

| Section | Update Description |
|-----------------------------------------------------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| “32-bit Microcontrollers (up to 128 KB Flash and 32 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog” | Updated the following feature sections: <ul style="list-style-type: none">• “Operating Conditions”• “Communication Interfaces” |
| 2.0 “Guidelines for Getting Started with 32-bit MCUs” | Removed Section 2.8 “Configuration of Analog and Digital Pins During ICSP Operations”. |
| 3.0 “CPU” | Removed references to GPR shadow registers in 3.1 “Features” and 3.2.1 “Execution Unit” . |
| 4.0 “Memory Organization” | Updated the BRG bit range in the SPI1 and SPI2 Register Map (see Table 4-8). Added the PWP<6> bit to the Device Configuration Word Summary (see Table 4-17). |
| 5.0 “Flash Program Memory” | Added a note with Flash page size and row size information. |
| 7.0 “Interrupt Controller” | Updated the TPC<2:0> bit definitions (see Register 7-1). Updated the IPTMR<31:0> bit definition (see Register 7-3). |
| 8.0 “Oscillator Configuration” | Updated the PIC32MX1XX/2XX Family Clock Diagram (see Figure 8-1). Updated the RODIV<14:0> bit definitions (see Register 8-3). |
| 10.0 “USB On-The-Go (OTG)” | Updated the Notes in the USB Interface Diagram (see Figure 10-1). |
| 18.0 “Universal Asynchronous Receiver Transmitter (UART)” | Updated the baud rate range in the list of primary features. |
| 26.0 “Special Features” | Added the PWP<6> bit to the Device Configuration Word 0 (see Register 26-1). |
| 29.0 “Electrical Characteristics” | Added Note 1 to Operating MIPS vs. Voltage (see Table 29-1). Added Note 2 to DC Temperature and Voltage Specifications (see Table 29-4). Updated the Conditions for parameter DC25 in DC Characteristics: Operating Current (IDD) (see Table 29-5). Added Note 2 to Electrical Characteristics: BOR (see Table 29-10). Added Note 4 to Comparator Specifications (see Table 29-12). Added Note 5 to ADC Module Specifications (see Table 29-32). Updated the 10-bit Conversion Rate Parameters and added Note 3 (see Table 29-33). Added Note 4 to the Analog-to-Digital Conversion Timing Requirements (see Table 29-34). Added Note 3 to CTMU Current Source Specifications (see Table 29-39). |
| 30.0 “50 MHz Electrical Characteristics” | New chapter with electrical characteristics for 50 MHz devices. |
| 31.0 “Packaging Information” | The 36-pin and 44-pin VTLA packages have been updated. |

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

Revision F (February 2014)

This revision includes the addition of the following devices:

- PIC32MX170F256B
- PIC32MX270F256B
- PIC32MX170F256D
- PIC32MX270F256D

In addition, this revision includes the following major changes as described in [Table A-5](#), as well as minor updates to text and formatting, which were incorporated throughout the document.

TABLE A-5: MAJOR SECTION UPDATES

| Section | Update Description |
|---------------------------------------------------------------------------------------------------------------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 32-bit Microcontrollers (up to 256 KB Flash and 64 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog | Added new devices to the family features (see Table 1 and Table 2). Updated pin diagrams to include new devices (see “Pin Diagrams”). |
| 1.0 “Device Overview” | Added Note 3 reference to the following pin names: VBUS, VUSB3V3, VBUSON, D+, D-, and USBID. |
| 2.0 “Guidelines for Getting Started with 32-bit MCUs” | Replaced Figure 2-1: Recommended Minimum Connection. Updated Figure 2-2: MCLR Pin Connections. Added 2.9 “Sosc Design Recommendation” . |
| 4.0 “Memory Organization” | Added memory tables for devices with 64 KB RAM (see Table 4-4 through Table 4-5). Changed the Virtual Addresses for all registers and updated the PWP bits in the DEVCFG: Device Configuration Word Summary (see Table 4-17). Updated the ODCA, ODCB, and ODCC port registers (see Table 4-19, Table 4-20, and Table 4-21). The RTCTIME, RTCDATE, ALRMTIME, and ALRMDATE registers were updated (see Table 4-25). Added Data Ram Size value for 64 KB RAM devices (see Register 4-5). Added Program Flash Size value for 256 KB Flash devices (see Register 4-5). |
| 12.0 “Timer1” | The Timer1 block diagram was updated to include the 16-bit data bus (see Figure 12-1). |
| 13.0 “Timer2/3, Timer4/5” | The Timer2-Timer5 block diagram (16-bit) was updated to include the 16-bit data bus (see Figure 13-1). The Timer2/3, Timer4/5 block diagram (32-bit) was updated to include the 32-bit data bus (see Figure 13-1). |
| 19.0 “Parallel Master Port (PMP)” | The CSF<1:0> bit value definitions for ‘00’ and ‘01’ were updated (see Register 19-1). Bit 14 in the Parallel Port Address register (PMADDR) was updated (see Register 19-3). |
| 20.0 “Real-Time Clock and Calendar (RTCC)” | The following registers were updated: RTCTIME (see Register 20-3) RTCDATE (see Register 20-4) ALRMTIME (see Register 20-5) ALRMDATE (see Register 20-6) |
| 26.0 “Special Features” | Updated the PWP bits (see Register 26-1). |
| 29.0 “Electrical Characteristics” | Added parameters DO50 and DO50a to the Capacitive Loading Requirements on Output Pins (see Table 29-14). Added Note 5 to the IDD DC Characteristics (see Table 29-5). Added Note 4 to the IDLE DC Characteristics (see Table 29-6). Added Note 5 to the IPD DC Characteristics (see Table 29-7). Updated the conditions for parameters USB321 (VOL) and USB322 (VOH) in the OTG Electrical Specifications (see Table 29-38). |
| Product Identification System | Added 40 MHz speed information. |

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

Revision G (April 2015)

This revision includes the addition of the following devices:

- PIC32MX130F256B
- PIC32MX230F256B
- PIC32MX130F256D
- PIC32MX230F256D

The title of the document was updated to avoid confusion with the PIC32MX1XX/2XX/5XX 64/100-pin Family data sheet.

All peripheral SFR maps have been relocated from the Memory chapter to their respective peripheral chapters.

In addition, this revision includes the following major changes as described in [Table A-6](#), as well as minor updates to text and formatting, which were incorporated throughout the document.

TABLE A-6: MAJOR SECTION UPDATES

| Section | Update Description |
|---------------------------------------------------------------------------------------------------------------------------------|--------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 32-bit Microcontrollers (up to 256 KB Flash and 64 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog | Added new devices to the family features (see Table 1 and Table 2). Updated pin diagrams to include new devices (see Pin Diagrams). |
| 2.0 “Guidelines for Getting Started with 32-bit MCUs” | Updated these sections: 2.2 “Decoupling Capacitors” , 2.3 “Capacitor on Internal Voltage Regulator (VCAP)” , 2.4 “Master Clear (MCLR) Pin” , 2.8.1 “Crystal Oscillator Design Consideration” |
| 4.0 “Memory Organization” | Added Memory Map for new devices (see Figure 4-6). |
| 14.0 “Watchdog Timer (WDT)” | New chapter created from content previously located in the Special Features chapter. |
| 30.0 “Electrical Characteristics” | Removed parameter D312 (TSET) from the Comparator Specifications (see Table 30-12). Added the Comparator Voltage Reference Specifications (see Table 30-13). Updated Table 30-12. |

Revision H (July 2015)

This revision includes the following major changes as described in [Table A-7](#), as well as minor updates to text and formatting, which were incorporated throughout the document.

TABLE A-7: MAJOR SECTION UPDATES

| Section | Update Description |
|--------------------------------------------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 2.0 “Guidelines for Getting Started with 32-bit MCUs” | Section 2.9 “Sosc Design Recommendation” was removed. |
| 8.0 “Oscillator Configuration” | The Primary Oscillator (Posc) logic in the Oscillator diagram was updated (see Figure 8-1). |
| 30.0 “Electrical Characteristics” | The Power-Down Current (IPD) DC Characteristics parameter DC40k was updated (see Table 30-7). Table 30-9: “DC Characteristics: I/O Pin Input Injection current Specifications” was added. |

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

Revision J (April 2016)

This revision includes the following major changes as described in [Table A-8](#), as well as minor updates to text and formatting, which were incorporated throughout the document.

TABLE A-8: MAJOR SECTION UPDATES

| Section | Update Description |
|-----------------------------------------------------------------------------------------------------------------------------------|----------------------------------------------------------------------------------------------------------------------------------------------------|
| “32-bit Microcontrollers (up to 256 KB Flash and 64 KB SRAM) with Audio and Graphics Interfaces, USB, and Advanced Analog” | The PIC32MX270FDB device and Note 4 were added to TABLE 2: “PIC32MX2XX 28/36/44-pin USB Family Features” . |
| 2.0 “Guidelines for Getting Started with 32-bit MCUs” | EXAMPLE 2-1: “Crystal Load Capacitor Calculation” was updated. |
| 30.0 “Electrical Characteristics” | Parameter DO50a (Csosc) was removed from the Capacitive Loading Requirements on Output Pins AC Characteristics (see Table 30-16). |
| “Product Identification System” | The device mapping was updated to include type B for Software Targeting. |

PIC32MX1XX/2XX 28/36/44-PIN FAMILY

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PIC32MX1XX/2XX 28/36/44-PIN FAMILY

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

| | PIC32 | MX | 1XX | F | 032 | D | B | T | 50 | I / PT | XXX |
|------------------------------------|-------|----|-----|---|-----|---|---|---|----|--------|-----|
| Microchip Brand | _____ | | | | | | | | | | |
| Architecture | _____ | | | | | | | | | | |
| Product Groups | _____ | | | | | | | | | | |
| Flash Memory Family | _____ | | | | | | | | | | |
| Program Memory Size (KB) | _____ | | | | | | | | | | |
| Pin Count | _____ | | | | | | | | | | |
| Software Targeting | _____ | | | | | | | | | | |
| Tape and Reel Flag (if applicable) | _____ | | | | | | | | | | |
| Speed (if applicable) | _____ | | | | | | | | | | |
| Temperature Range | _____ | | | | | | | | | | |
| Package | _____ | | | | | | | | | | |
| Pattern | _____ | | | | | | | | | | |

Example:
 PIC32MX110F032DT-I/PT:
 General purpose PIC32,
 32-bit RISC MCU with M4K® core,
 32 KB program memory, 44-pin,
 Industrial temperature,
 TQFP package.

Flash Memory Family

| | |
|---------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| Architecture | MX = M4K® MCU core |
| Product Groups | 1XX = General purpose microcontroller family 2XX = General purpose microcontroller family |
| Flash Memory Family | F = Flash program memory |
| Program Memory Size | 016 = 16K 032 = 32K 064 = 64K 128 = 128K 256 = 256K |
| Pin Count | B = 28-pin C = 36-pin D = 44-pin |
| Software Targeting | B = Targeted for Bluetooth® Audio Break-in devices |
| Speed | () = 40 MHz – () indicates a blank field; package markings for 40 MHz devices do not include the Speed 50 = 50 MHz |
| Temperature Range | I = -40°C to +85°C (Industrial) V = -40°C to +105°C (V-temp) |
| Package | ML = 28-Lead (6x6 mm) QFN (Plastic Quad Flatpack) ML = 44-Lead (8x8 mm) QFN (Plastic Quad Flatpack) PT = 44-Lead (10x10x1 mm) TQFP (Plastic Thin Quad Flatpack) SO = 28-Lead (7.50 mm) SOIC (Plastic Small Outline) SP = 28-Lead (300 mil) SPDIP (Skinny Plastic Dual In-line) SS = 28-Lead (5.30 mm) SSOP (Plastic Shrink Small Outline) TL = 36-Lead (5x5 mm) VTLA (Very Thin Leadless Array) TL = 44-Lead (6x6 mm) VTLA (Very Thin Leadless Array) |
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